

Selek 15" Schematic

CFL-H refresh

2019/04/03

REV : A00

DY : None Installed
UMA: UMA only installed
OPS: DISCRTE OPTIMUS installed

Selek CFLH N17P



Wistron Corporation

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Title

Cover Page

Size
A4

Document Number

Selek CFL-H

Rev

A00

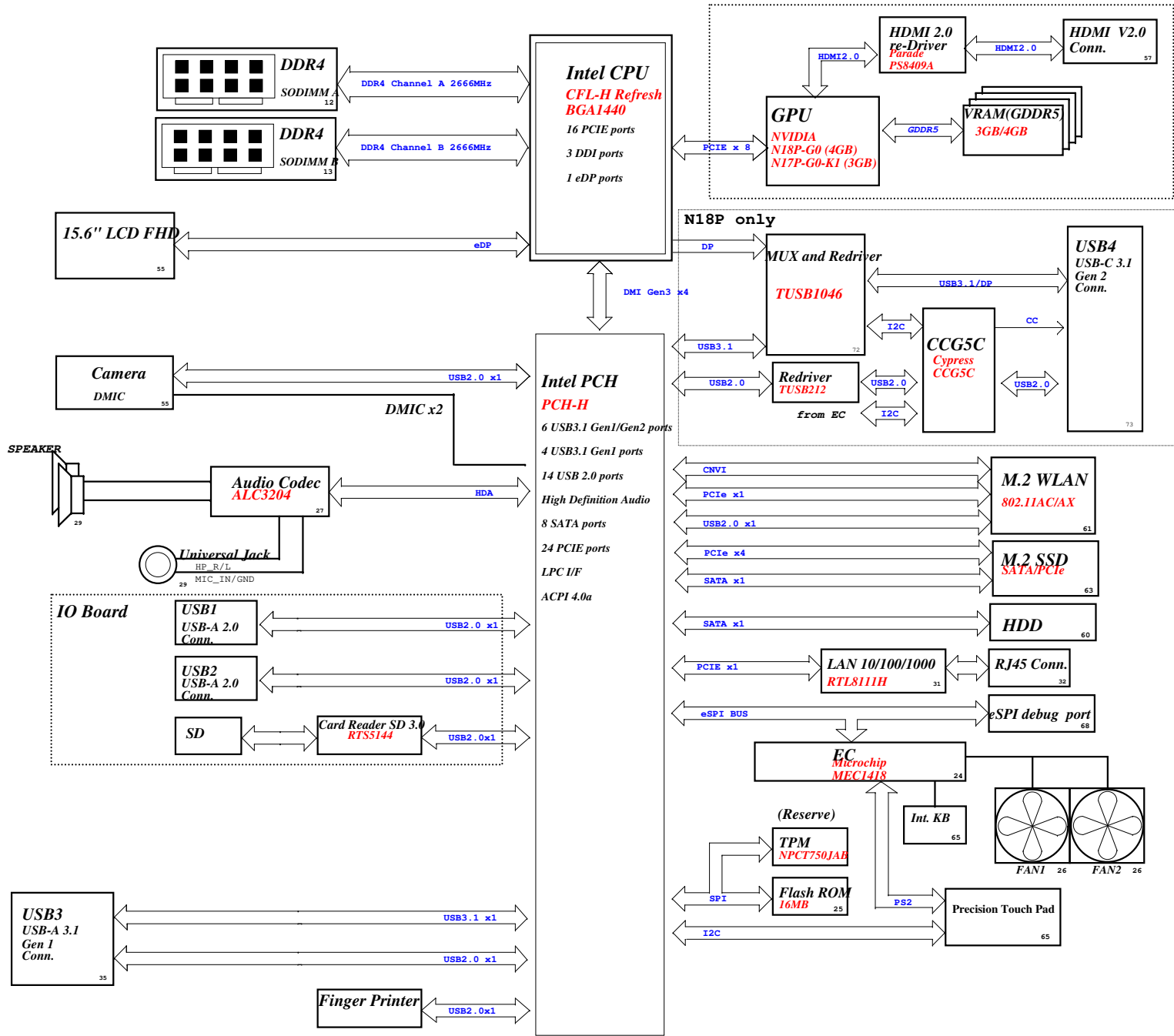
Date: Wednesday, April 03, 2019

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Project Code : 4PD0H7010001
PCB P/N : 18825-1
Revision : A00

Selek CFL-H refresh Block Diagram

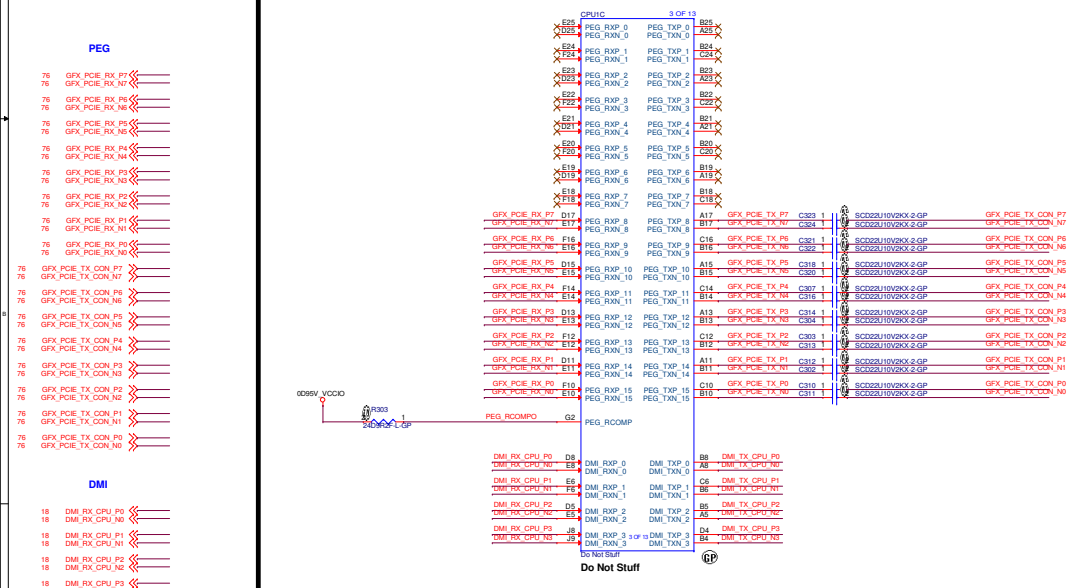
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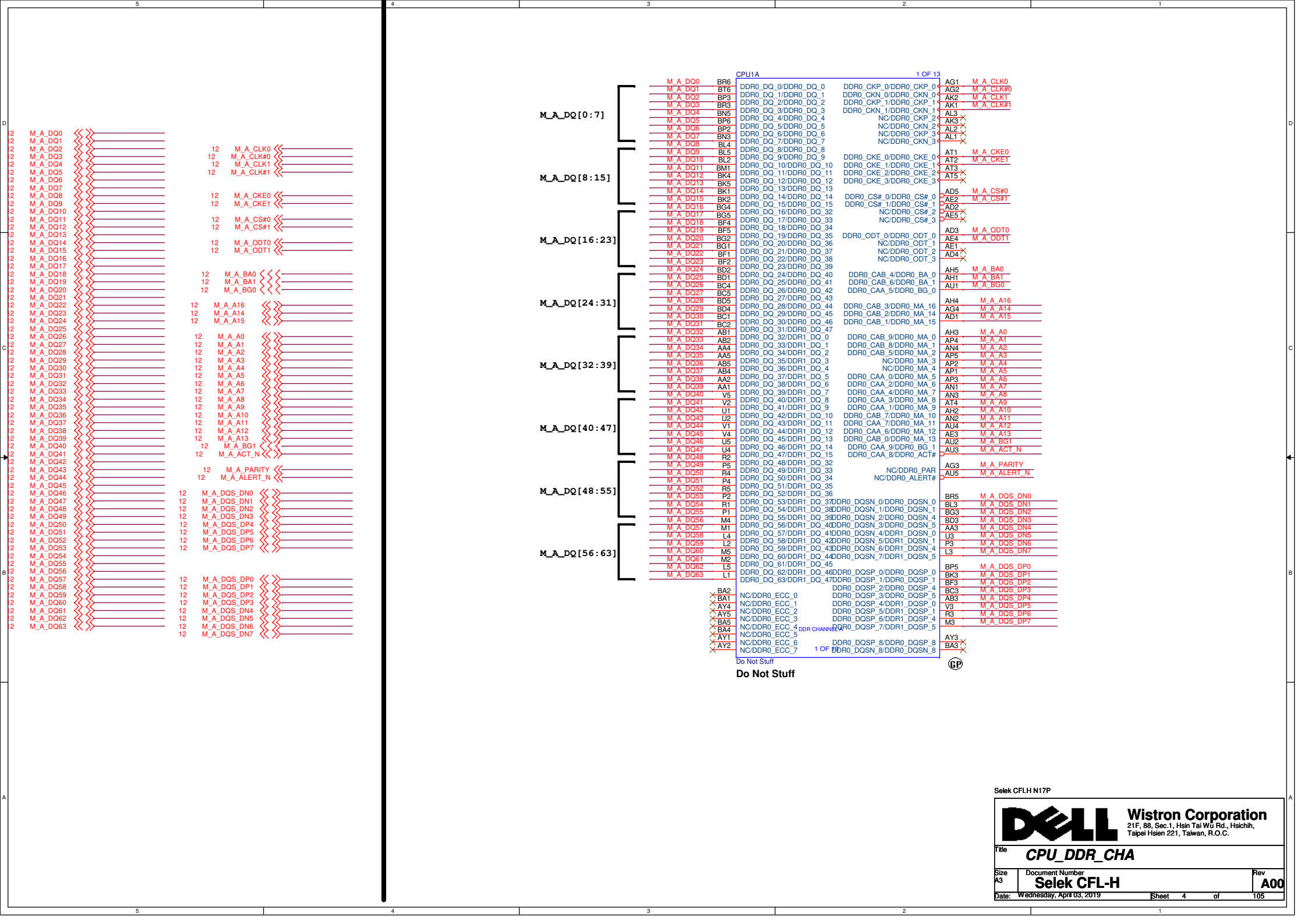


CHARGER	
ISL88739	44
INPUTS	OUTPUTS
AD+	DCBATOUT
BT+	
SYSTEM DC/DC	
TPS51225RUKR-GP	45
INPUTS	OUTPUTS
3D3V PWR	3D3V S5
5V PWR	5V S5
DCBATOUT	
CPU Core Power	
NCPS1208MNTXG	46-50
NCPS1382MNTXG x 2	
NCPS1382MNTXG (23e)	
NCPS1253MNTBG	
INPUTS	OUTPUTS
DCBATOUT	VCC CORE
DCBATOUT	+VCCGT
DCBATOUT	+VCCGT (23e)
DCBATOUT	+VCCSA
DDR4 SUS	
RT8231AGQW-GP	
APL5930KAI-TRG	51
INPUTS	OUTPUTS
DCBATOUT	1D2V S3
3D3V S5	0D6V S0
	2D5V S3
CPU VCCPRIM_CORE 1V	
	11
INPUTS	OUTPUTS
1D0V S5	+VCCPRIM CORE
CPU DCDC-V1D00A	
AO22262QI-10-GP-U	53
INPUTS	OUTPUTS
DCBATOUT	1D0V S5
LDO-V1D8V	
APL5930KAI-TRG	54
INPUTS	OUTPUTS
3D3V S5	1D8V S5
5V/3V S0	
TPS22966DPUR-GP	40
INPUTS	OUTPUTS
5V_S0	5V_S0
3D3V_S5	3D3V_S0
EOP10/EDRAM (23e)	
TPS22961DNYT	40
INPUTS	OUTPUTS
1D0V_S5	+V_EDRAM_VR
1D0V_S5	+V_EOP10_VR
3D3V VGA	
AO3419L	86
INPUTS	OUTPUTS
3D3V_S0	3D3V_VGA_S0
VGA CORE	
ISL62771HRTZ-GP-U	85
INPUTS	OUTPUTS
DCBATOUT	VGA_CORE
1D5V_VGA_S0	
Y8288RAC-GP	86
INPUTS	OUTPUTS
DCBATOUT	1D5V_VGA_S0

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DMI

**Selak CFLH N17P**



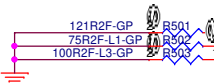
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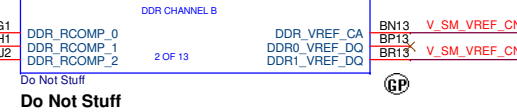
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CPU_DDR_CHA

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SSID = CPU



CPU1B		2 OF 13	
M_B_DQ00	BT11	DDR1_DQ_0/DDR0_DQ_16	AM9 M_B_CLK0
M_B_DQ01	BR11	DDR1_DQ_1/DDR0_DQ_17	AN9 M_B_CLK#0
M_B_DQ02	BT9	DDR1_DQ_2/DDR0_DQ_18	AM7 M_B_CLK1
M_B_DQ03	BR8	DDR1_DQ_3/DDR0_DQ_19	AM6 M_B_CLK#1
M_B_DQ04	BP11	DDR1_DQ_4/DDR0_DQ_20	AM11
M_B_DQ05	BN11	DDR1_DQ_5/DDR0_DQ_21	AM10
M_B_DQ06	BP8	DDR1_DQ_6/DDR0_DQ_22	AJ10
M_B_DQ07	BN8	DDR1_DQ_7/DDR0_DQ_23	AJ11
M_B_DQ08	BL12	DDR1_DQ_8/DDR0_DQ_24	
M_B_DQ09	BL11	DDR1_DQ_9/DDR0_DQ_25	AT8 M_B_CKE0
M_B_DQ10	BL8	DDR1_DQ_10/DDR0_DQ_26	AT10 M_B_CKE1
M_B_DQ11	BJ8	DDR1_DQ_11/DDR0_DQ_27	AT7
M_B_DQ12	BJ11	DDR1_DQ_12/DDR0_DQ_28	AT11
M_B_DQ13	BJ10	DDR1_DQ_13/DDR0_DQ_29	
M_B_DQ14	BL7	DDR1_DQ_14/DDR0_DQ_30	AF11 M_B_CS#0
M_B_DQ15	BJ7	DDR1_DQ_15/DDR0_DQ_31	AE7 M_B_CS#1
M_B_DQ16	BG11	DDR1_DQ_16/DDR0_DQ_48	AF10
M_B_DQ17	BG10	DDR1_DQ_17/DDR0_DQ_49	AE10
M_B_DQ18	BG8	DDR1_DQ_18/DDR0_DQ_50	
M_B_DQ19	BF8	DDR1_DQ_19/DDR0_DQ_51	AF7 M_B_ODT0
M_B_DQ20	BF11	DDR1_DQ_20/DDR0_DQ_52	AE8 M_B_ODT1
M_B_DQ21	BF10	DDR1_DQ_21/DDR0_DQ_53	AE9
M_B_DQ22	BG7	DDR1_DQ_22/DDR0_DQ_54	AE11
M_B_DQ23	BF7	DDR1_DQ_23/DDR0_DQ_55	
M_B_DQ24	BB11	DDR1_DQ_24/DDR0_DQ_56	AH10 M_B_A16
M_B_DQ25	BC11	DDR1_DQ_25/DDR0_DQ_57	AH11 M_B_A14
M_B_DQ26	BB8	DDR1_DQ_26/DDR0_DQ_58	AF8 M_B_A15
M_B_DQ27	BC8	DDR1_DQ_27/DDR0_DQ_59	
M_B_DQ28	BC10	DDR1_DQ_28/DDR0_DQ_60	AH8 M_B_BA0
M_B_DQ29	BC7	DDR1_DQ_29/DDR0_DQ_61	AH9 M_B_BA1
M_B_DQ30	BC7	DDR1_DQ_30/DDR0_DQ_62	AR9 M_B_BG0
M_B_DQ31	BB7	DDR1_DQ_31/DDR0_DQ_63	
M_B_DQ32	AA11	DDR1_DQ_32/DDR1_DQ_16	AJ9 M_B_A0
M_B_DQ33	AA10	DDR1_DQ_33/DDR1_DQ_17	AK6 M_B_A1
M_B_DQ34	AC11	DDR1_DQ_34/DDR1_DQ_18	AK5 M_B_A2
M_B_DQ35	AC10	DDR1_DQ_35/DDR1_DQ_19	AL5 M_B_A3
M_B_DQ36	AA7	DDR1_DQ_36/DDR1_DQ_20	AL6 M_B_A4
M_B_DQ37	AA8	DDR1_DQ_37/DDR1_DQ_21	AM6 M_B_A5
M_B_DQ38	AC8	DDR1_DQ_38/DDR1_DQ_22	AN7 M_B_A6
M_B_DQ39	AC7	DDR1_DQ_39/DDR1_DQ_23	AN10 M_B_A7
M_B_DQ40	W8	DDR1_DQ_40/DDR1_DQ_24	AN8 M_B_A8
M_B_DQ41	W7	DDR1_DQ_41/DDR1_DQ_25	AR11 M_B_A9
M_B_DQ42	V10	DDR1_DQ_42/DDR1_DQ_26	AH7 M_B_A10
M_B_DQ43	V11	DDR1_DQ_43/DDR1_DQ_27	AN11 M_B_A11
M_B_DQ44	W11	DDR1_DQ_44/DDR1_DQ_28	AR10 M_B_A12
M_B_DQ45	W10	DDR1_DQ_45/DDR1_DQ_29	AF9 M_B_A13
M_B_DQ46	V7	DDR1_DQ_46/DDR1_DQ_30	AR7 M_B_BG1
M_B_DQ47	V8	DDR1_DQ_47/DDR1_DQ_31	AT9 M_B_ACT_N
M_B_DQ48	R11	DDR1_DQ_48/DDR1_DQ_48	
M_B_DQ49	P11	DDR1_DQ_49/DDR1_DQ_49	
M_B_DQ50	P7	DDR1_DQ_50/DDR1_DQ_50	
M_B_DQ51	R8	DDR1_DQ_51/DDR1_DQ_51	
M_B_DQ52	R10	DDR1_DQ_52/DDR1_DQ_52	
M_B_DQ53	P10	DDR1_DQ_53/DDR1_DQ_53	
M_B_DQ54	R7	DDR1_DQ_54/DDR1_DQ_54	
M_B_DQ55	P8	DDR1_DQ_55/DDR1_DQ_55	
M_B_DQ56	L11	DDR1_DQ_56/DDR1_DQ_56	
M_B_DQ57	M11	DDR1_DQ_57/DDR1_DQ_57	
M_B_DQ58	L7	DDR1_DQ_58/DDR1_DQ_58	
M_B_DQ59	M8	DDR1_DQ_59/DDR1_DQ_59	
M_B_DQ60	L10	DDR1_DQ_60/DDR1_DQ_60	
M_B_DQ61	M10	DDR1_DQ_61/DDR1_DQ_61	
M_B_DQ62	M7	DDR1_DQ_62/DDR1_DQ_62	
M_B_DQ63	L8	DDR1_DQ_63/DDR1_DQ_63	
AW11		NC/DDR1_ECC_0	
AY11		NC/DDR1_ECC_1	
AW8		NC/DDR1_ECC_2	
AY10		NC/DDR1_ECC_3	
AW10		NC/DDR1_ECC_4	
AY7		NC/DDR1_ECC_5	
AW7		NC/DDR1_ECC_6	
		NC/DDR1_ECC_7	
		DDR1_CK_P_0/DDR1_CK_P_0	
		DDR1_CK_N_0/DDR1_CK_N_0	
		DDR1_CK_P_1/DDR1_CK_P_1	
		DDR1_CK_N_1/DDR1_CK_N_1	
		NC/DDR1_CK_P_2	
		NC/DDR1_CK_N_2	
		NC/DDR1_CK_P_3	
		NC/DDR1_CK_N_3	
		DDR1_CKE_0/DDR1_CKE_0	
		DDR1_CKE_1/DDR1_CKE_1	
		DDR1_CKE_2/DDR1_CKE_2	
		DDR1_CKE_3/DDR1_CKE_3	
		DDR1_CS#_0/DDR1_CS#_0	
		DDR1_CS#_1/DDR1_CS#_1	
		NC/DDR1_CS#_2	
		NC/DDR1_CS#_3	
		DDR1_ODT_0/DDR1_ODT_0	
		NC/DDR1_ODT_1	
		NC/DDR1_ODT_2	
		NC/DDR1_ODT_3	
		DDR1_CAB_3/DDR1_MA_16	
		DDR1_CAB_2/DDR1_MA_14	
		DDR1_CAB_1/DDR1_MA_15	
		DDR1_CAB_4/DDR1_MA_0	
		DDR1_CAB_6/DDR1_BA_1	
		DDR1_CAA_5/DDR1_BG_0	
		DDR1_CAB_9/DDR1_MA_0	
		DDR1_CAB_3/DDR1_MA_1	
		DDR1_CAB_5/DDR1_MA_2	
		NC/DDR1_MA_3	
		NC/DDR1_MA_4	
		DDR1_CAA_0/DDR1_MA_5	
		DDR1_CAA_2/DDR1_MA_6	
		DDR1_CAA_4/DDR1_MA_7	
		DDR1_CAA_3/DDR1_MA_8	
		DDR1_CAA_1/DDR1_MA_9	
		DDR1_CAB_7/DDR1_MA_10	
		DDR1_CAA_7/DDR1_MA_11	
		DDR1_CAA_6/DDR1_MA_12	
		DDR1_CAB_0/DDR1_MA_13	
		DDR1_CAA_9/DDR1_BG_1	
		DDR1_CAA_8/DDR1_ACT#	
		NC/DDR1_PAR	
		NC/DDR1_ALERT#	
		BN9 M_B_DQS_DN0	
		BL9 M_B_DQS_DN1	
		BC9 M_B_DQS_DN2	
		BC9 M_B_DQS_DN3	
		AC9 M_B_DQS_DN4	
		W9 M_B_DQS_DN5	
		R9 M_B_DQS_DN6	
		M9 M_B_DQS_DN7	
		BP9 M_B_DQS_DP0	
		BL9 M_B_DQS_DP1	
		BF9 M_B_DQS_DP2	
		BB9 M_B_DQS_DP3	
		AA9 M_B_DQS_DP4	
		V9 M_B_DQS_DP5	
		P9 M_B_DQS_DP6	
		L9 M_B_DQS_DP7	
		AW9	
		AY9	



AROUND_CPU

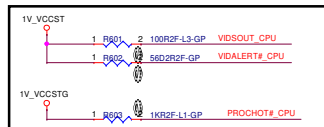
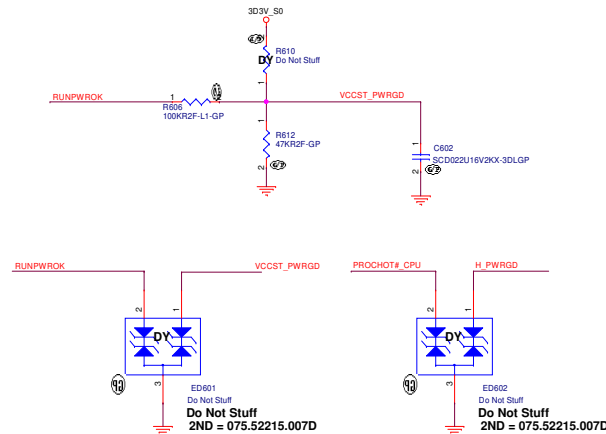


Table 13-14. SVID Bus Routing Guidelines

Signal	W1 [inches]	W2 [inches]	W3/4/5 [inches]	W2+W3+W4+W5 [inches]	W51 [inches]	W52 [inches]	R _{PULL} [Ω]	R _{IN1} [Ω]	R _{E1} [Ω]	R _{E2} [Ω]	V _{CC1T} [V]
VIDOUT							100	100	0	10	
VIDSK	0.5-3	1-15	0.5-4	3-17	<0.1	<0.1	Empty	45	0	50	1.0
VIDALERT#							56	Empty	220	0	

Note: For additional information regarding SVID and power management refer to "Power Architecture Guide".



GPD11 pull high by Intel PDG1.3 request

PEG Static Lane Reversal
CFG2
1: Normal Operation; Lane # definition matches socket pin map definition
0: Lane Reversed

eDP Enable
CFG4
1: Disable
0: Enable

PEG Training
CFG7
1: (default) PEG Train immediately following RESET# de assertion
0 = PEG Wait for BIOS for training.

Physical_Debug_Enabled (DPX privacy)
CFG4
1: Disable
0: Enable (Set DXF enables bit in debug)

PCIe Port Bifurcation Straps
CFG[6:5]
01: x16 - Device 1 functions 1 and 2 disabled
00: x8, x4 - Device 1 function 1 enabled, function 2 disabled
01: Reserved - (Device 1 function 1 disabled, function 2 enabled)
00: x8, x4, x4 - Device 1 functions 1 and 2 enabled



Processor Internal Pull-Up / Pull-Down Terminations

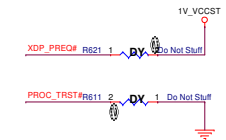
Processor Internal Pull-Up / Pull-Down Terminations

Signal Name	Pull Up/Pull Down	Rail	Value
BPM[3:0]	Pull Up	VCC _{IO}	16-60 Ω
PREQ#	Pull Up	VCC _{ST}	3 kΩ
PROC_TDI	Pull Up	VCC _{STG} ¹	3 kΩ
PROC_TMS	Pull Up	VCC _{STG} ¹	3 kΩ
CFG[19:0]	Pull Up	VCC _{IO}	3 kΩ

Note:
1. For SKL-S it should be VCC_{ST}

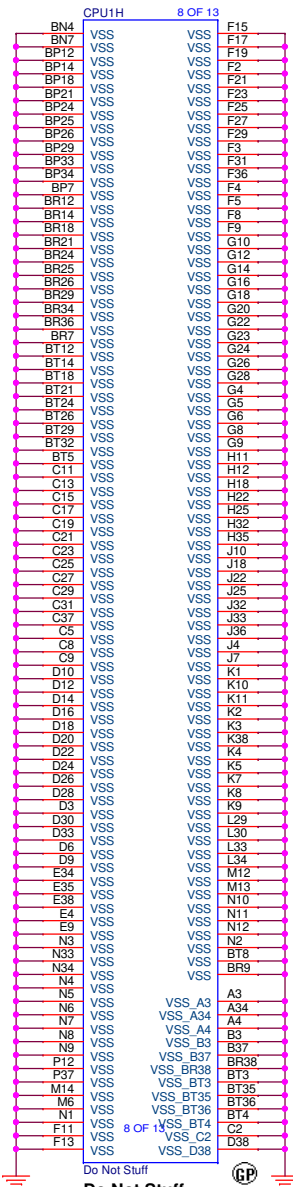
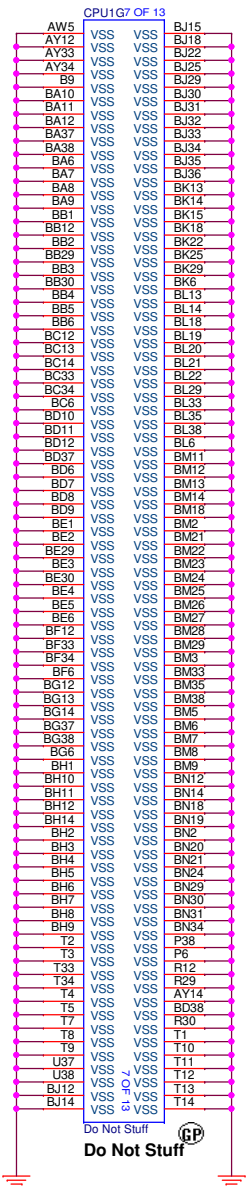
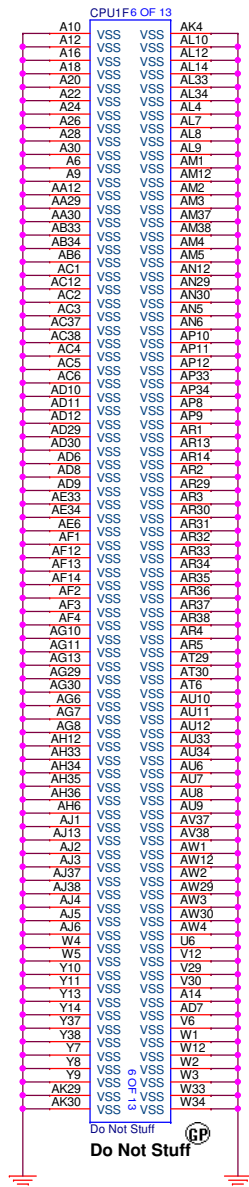
Table 6-8. Reset and Miscellaneous Signals

Signal Name	Description	Dir.	Buffer Type	Link Type	Availability
CFG[19:0]	Configuration Signals: The CFG signals have a default value of '1' if not terminated on the board. Refer to the appropriate platform design guide for pull-down recommendations when a logic low is desired. Intel recommends placing test points on the board for CFG pins. • CFG[0]: Shall reset sequence after PCU PLL lock until de-asserted. - 1 = (Default) Normal Operation; - 0 = Stall. • CFG[1]: Reserved configuration lane. • CFG[2]: PCI Express® Static x16 Lane Numbering Reversal. - 1 = Normal operation - 0 = Lane numbers reversed. • CFG[3]: Reserved configuration lane. • CFG[4]: eDP enable. - 1 = Disabled. - 0 = Enabled. • CFG[6:5]: PCI Express® Bifurcation - 00 = 1 x8, 2 x4 PCI Express® - 01 = reserved - 10 = 2 x8 PCI Express® - 11 = 1 x16 PCI Express® • CFG[7]: PEG Training. - 1 = (default) PEG Train immediately following RESET# de assertion. - 0 = PEG Wait for BIOS for training. • CFG[19:8]: Reserved configuration lanes.	I/O	GTL		All processor lanes. CFG[2], CFG[6:5] and CFG[7] are relevant for H and S-processor line only and test point may be placed on the board for them.



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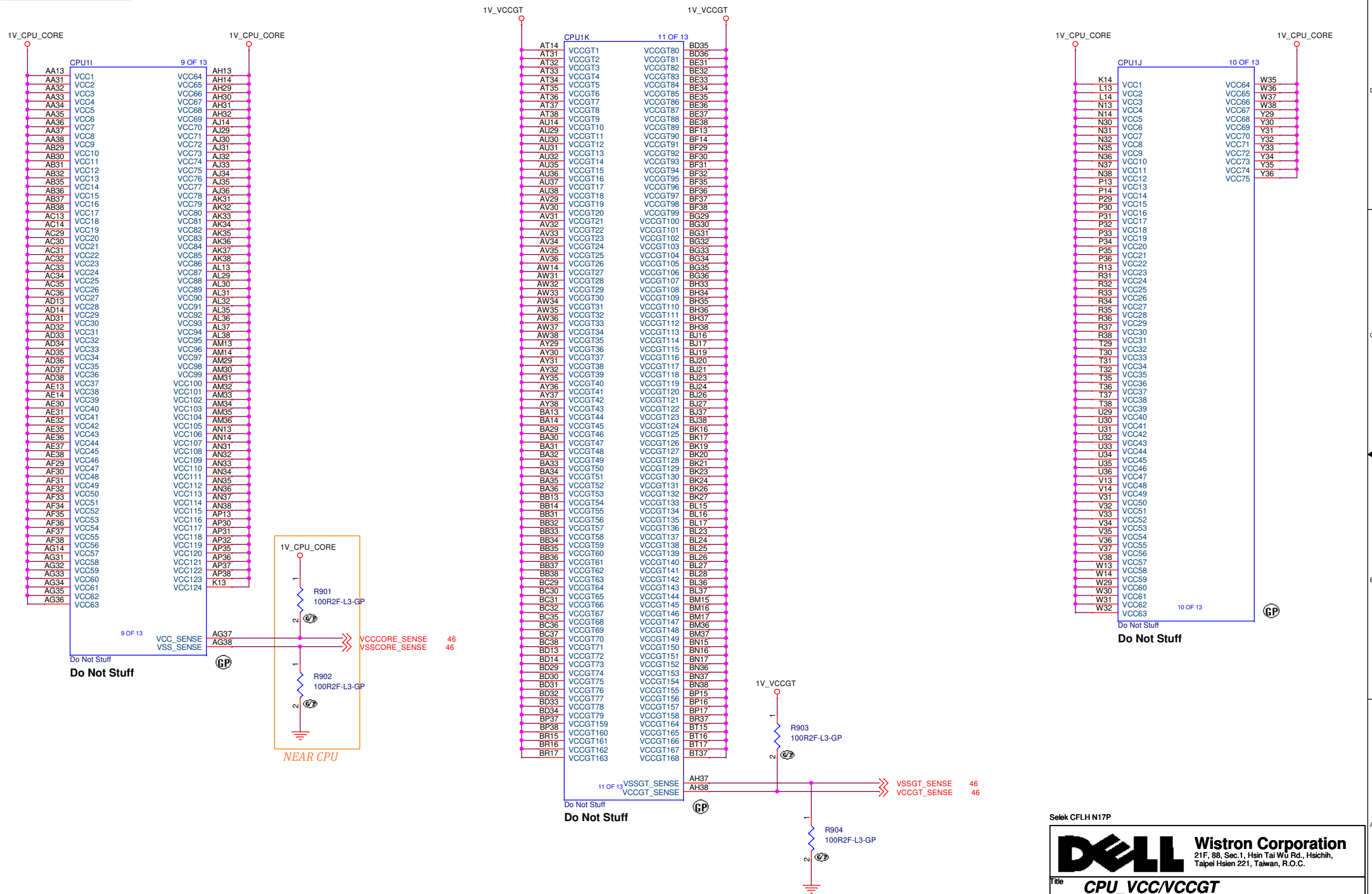
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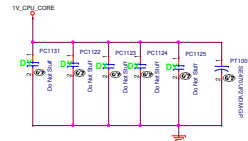
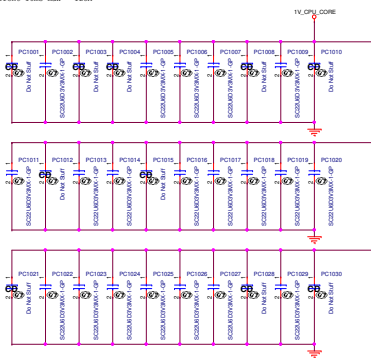
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Title CPU_GND			
Size A3	Document Number	Rev	
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SSID = CPU

**Selek CFLH N17P**

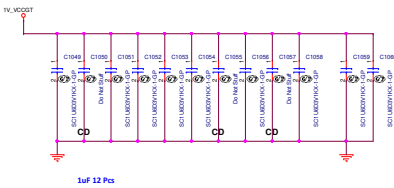
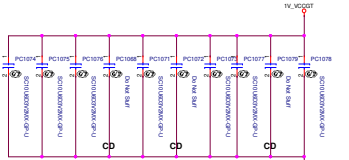
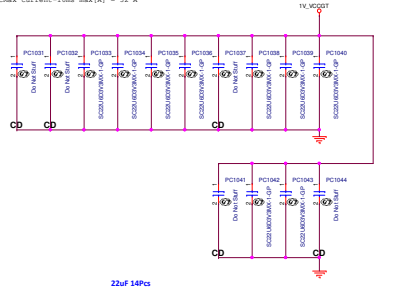
CFL-H_45W

H-Line 45W
IccMax current=10mA max = 128A



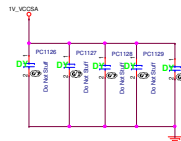
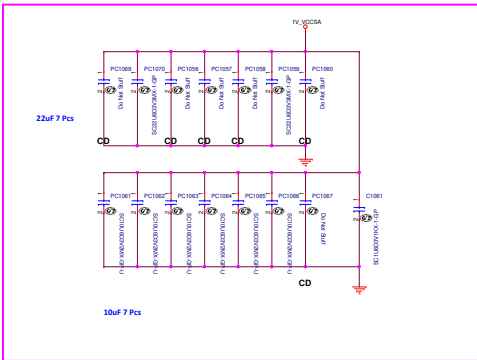
CFL-H_45W

IccMax current=10mA max(A) = 32 A

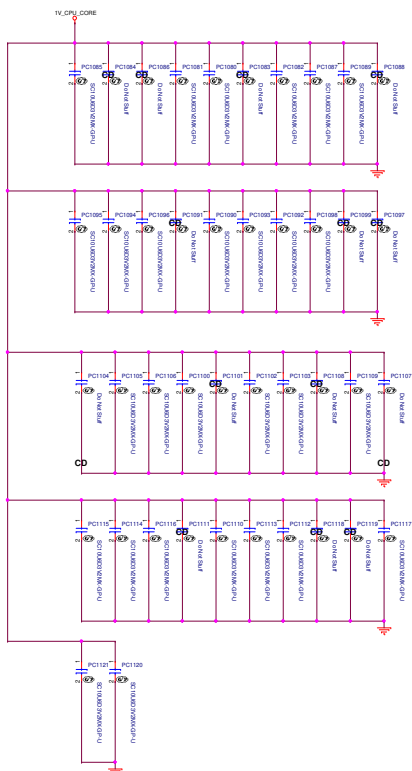


H-Line

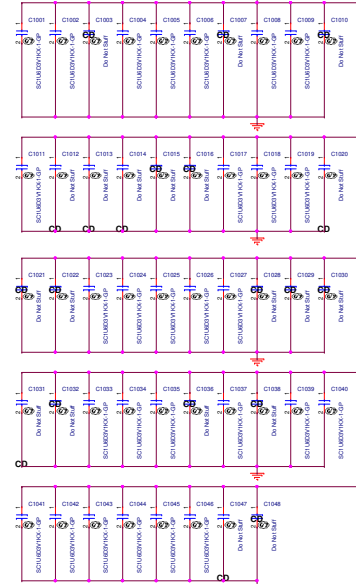
IccMax current=10mA max(A) = 11.1 A

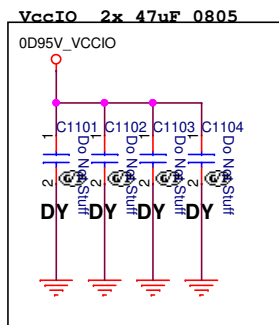
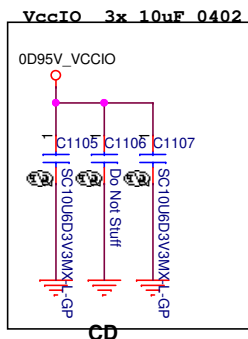
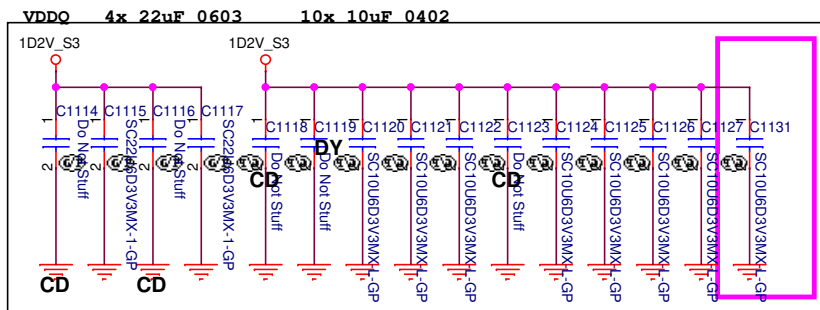


10uF 42Pcs

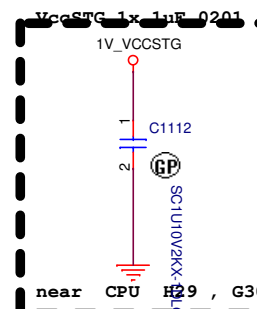
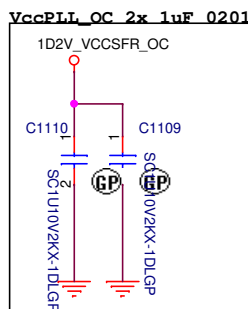
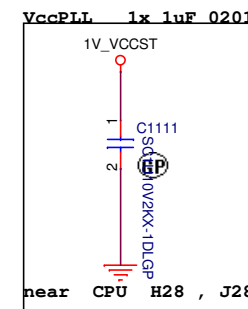
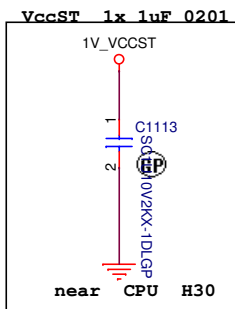


1uF 48 Pcs





VR: +/-5% or +/-50mV
Place close to VR output



JJ 20150130

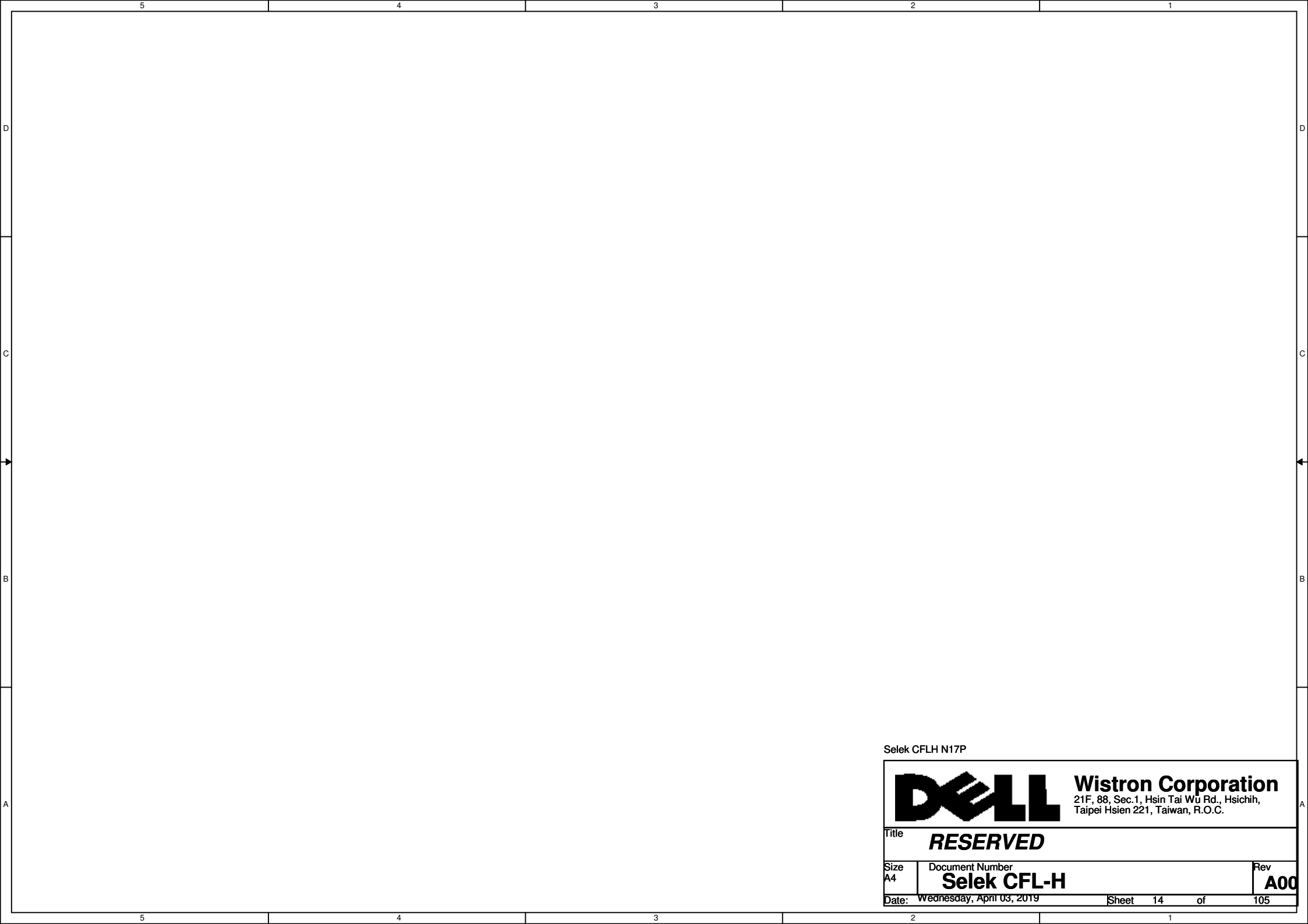
Table 50-5. Decoupling Requirements for CFL H 8+2 Processor (Sheet 1 of 2)

Domain	Board Edge cap	Backside cap	Notes
Vcc	2x 22uF 0603		
	8x 47uF 0805		
		48x 1uF 0201	
		42x 10uF 0402	
		10x 22uF 0603	
VccGT	3x 47uF 0805		Place as close to the BGA as possible
	7x 22uF 0603		
		10x 10uF 0402	
		12x 1uF 0201	
VccSA	2x 47uF 0805		
	2x 22uF 0603		
		7x 10uF 0402	
VDDQ		1x 1uF 0201	
		4x 22uF 0603	
		11x 10uF 0402	
VccIO		3x 10uF 0402	
		3x 0402 (placeholder)	Additional capacitors might be needed if the connectivity from BGAs to capacitors is not adequate.
VccST		1x 1uF 0201	Must be Ground referenced. Board routing resistance from BGA to Power gate should be less than 10mOhm. Do not route VccGT closest adjacent layer over any power net other than ground.
VccSTG		1x 1uF 0201	Must be Ground referenced. Share with 1.0V PCH rail.
VccPLL		1x 1uF 0201	Must be Ground referenced. Share with 1.0V PCH rail. Board resistance from BGA to Power gate should be less than 130mOhm.
		1x 22uF/47uF 0805 (placeholder)	*Placeholder not stuffed. To be placed as close as possible to BGA (H28, J28) and be placed either at board edge or backside.
Domain	Board Edge cap	Backside cap	Notes
VccPLL_OC		2x 1uF 0201	Must be Ground referenced. Share with VDDQ. Board resistance from BGA to Power gate should be less than 86mOhm.

Note: High Current Rail assuming 600KHz for VR bandwidth. Higher VR bandwidth assumptions results in lower quantity of MLCC (0805/0603) to meet the same AC loadline.
Note: It is important to make sure that the noise on VCCPLL rail must be limited to the +/-5% VR specification below 150KHz - as this will potentially impact the PLL failing to phase lock. Where necessary, the 0805 placeholder can be stuffed with a 22uF or 47uF to assist noise reduction. While stuffing the 0805 cap may reduce noise coupling, one should still route the PLL rail carefully (i.e. to avoid noisy and high current rail) to mitigate any potential issue.

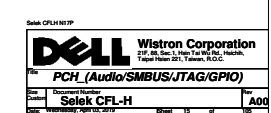
Selek CFLH N17P

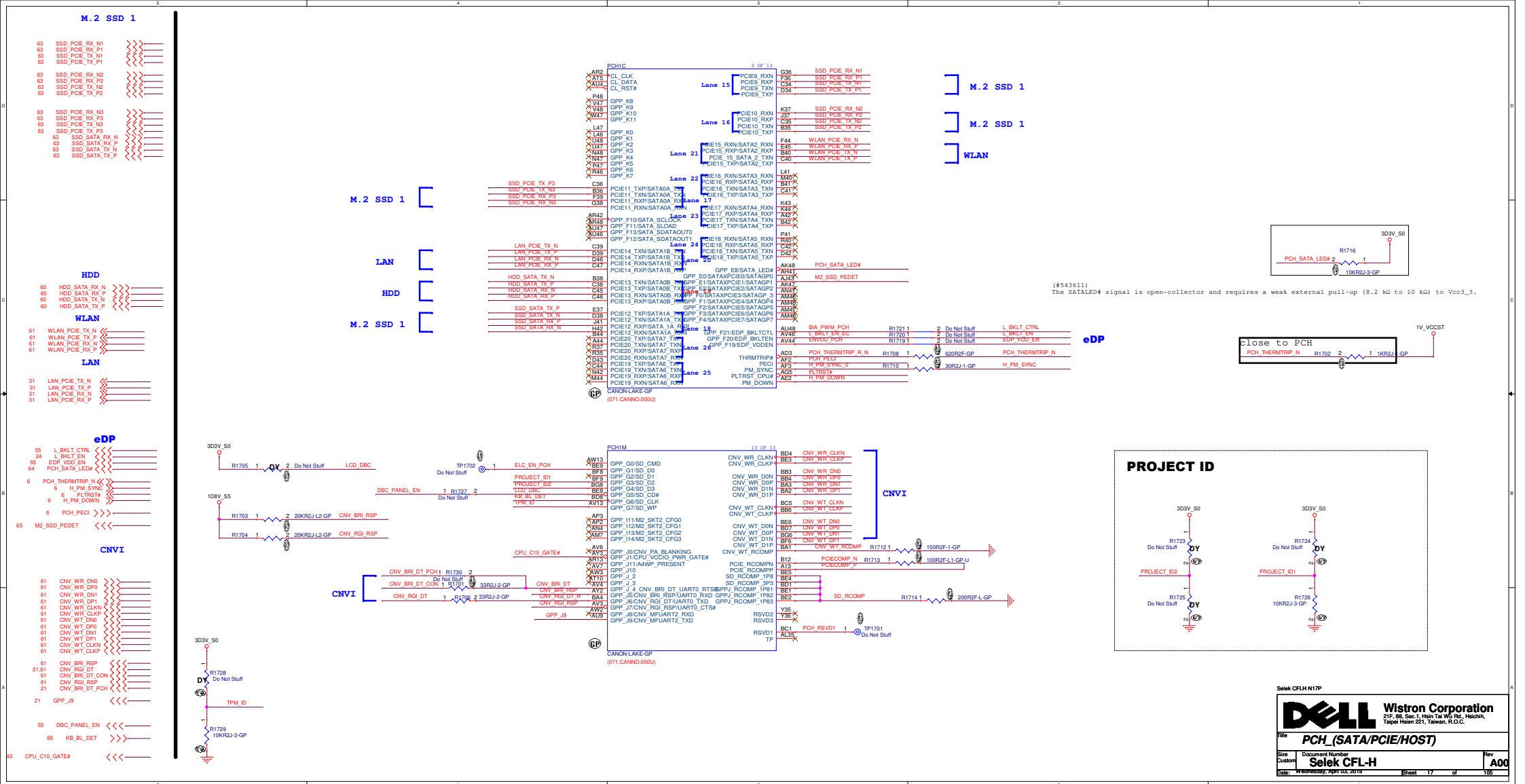
DELL		Wistron Corporation	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title CPU (Power CAP2)			
Size Custom	Document Number Selek CFL-H		Rev A00
Date: Wednesday, April 03, 2019	Sheet 11	of 105	

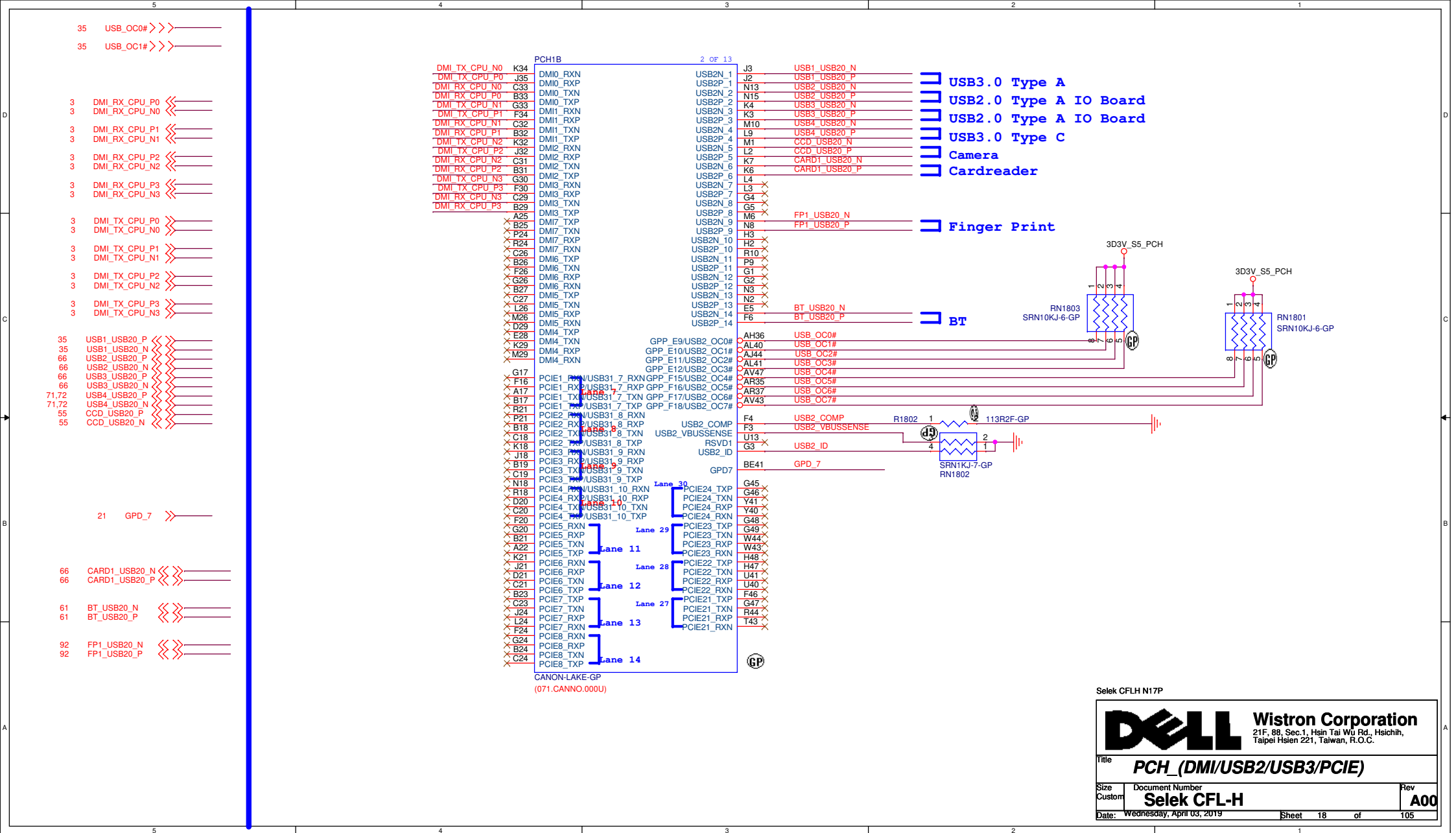


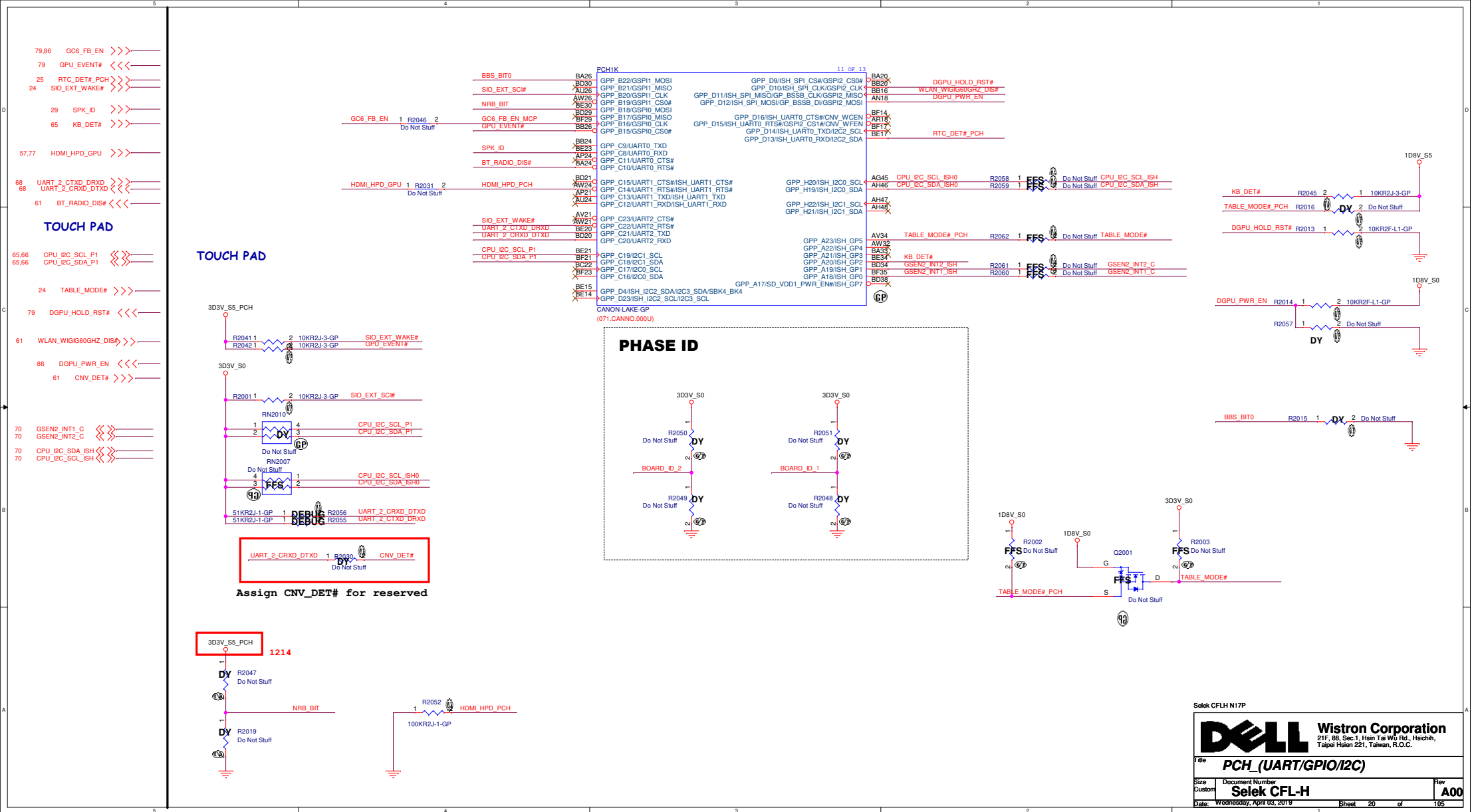
Selek CFLH N17P

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title RESERVED			
Size A4	Document Number Selek CFL-H		Rev A00
Date: Wednesday, April 03, 2019		Sheet 14	of 105









GPIO	GPP_B14 SPKR	GPP_B18 GSPIO_MOSI	GPP_C2 SMBALERT#	GPP_B22 GSPII_MOSI	GPP_C5 SMBALERT#	SPIO_MOSI SPIO_MISO	GPP_H15 SML3ALERT#
Schematic		default is internal pull down add TP at PCH side		default is internal pull down add TP at PCH side			

GPIO	GPP_B23 SML1ALERT# PCHHOT#	SPIO_IO2	SPIO_IO3	HDA_SDO/ I2S0_TXD	GPP_H12 SML2ALERT#	GPP_I6 DDPB_CTRLDATA	GPP_I8 DDPC_CTRLDATA
Schematic					internal pull down	Pull high at page 19	internal pull down

need check the latest CRB,PDG

GPIO	GPP_I10	GPP_F23/ DPPF_CTRLDATA	GPP_J4 CNV_BRI_DT UART0_RTS#	GPP_J6 CNV_RGI_DT UART0_TXD	GPP_J9	GPD7
Schematic		internal pull down				

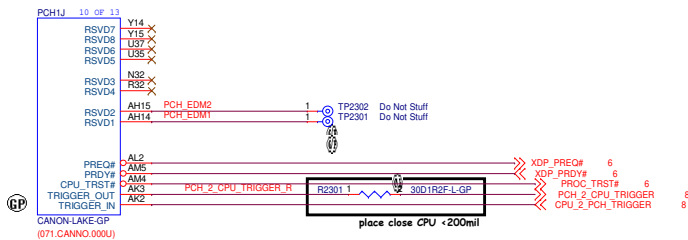
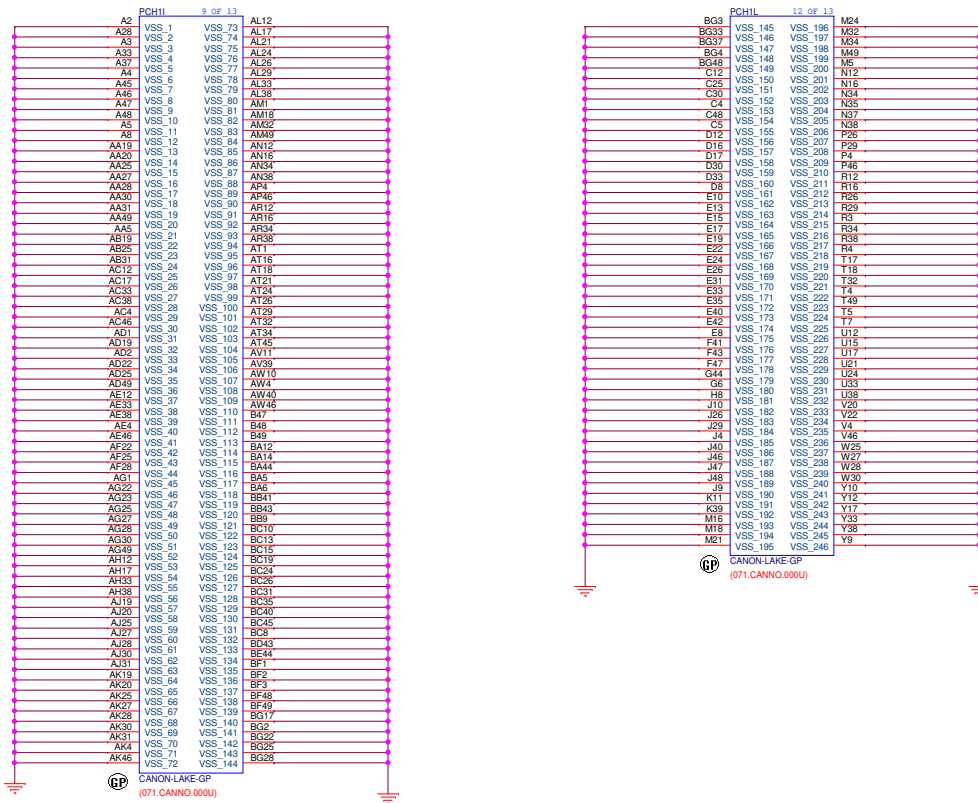
Table 9-1. Pin Straps (Sheet 1 of 4)

Signal	Usage	When Sampled	Comment
GPP_B14 / SPCR	Top level Overclock	Rising edge of PCH_PWRON	The signal has a weak internal pull-down. 1 = Disable "Top level" mode. This enables an address on-chip select (CS) and enables a pull-up resistor. The default value of the signal is pull-up. PCH will sample CS and CS# signals. The pull-up resistor is enabled when the signal is pulled up. The pull-up resistor is disabled when the signal is pulled down. 2 = Pull-up resistor is disabled. 3 = Pull-up resistor is disabled. 4 = Pull-up resistor is disabled.
GPP_B18 / GSPIO_MOSI	No device	Rising edge of PCH_PWRON	The signal has a weak internal pull-down. 1 = Disable "Top level" mode. This enables an address on-chip select (CS) and enables a pull-up resistor. The default value of the signal is pull-up. PCH will sample CS and CS# signals. The pull-up resistor is enabled when the signal is pulled up. The pull-up resistor is disabled when the signal is pulled down. 2 = Pull-up resistor is disabled. 3 = Pull-up resistor is disabled. 4 = Pull-up resistor is disabled.
GPP_C2 / SMBALERT#	1.5V Core activity	Rising edge of GSPII_MOSI	The signal has a weak internal pull-down. 1 = Disable "Top level" mode. This enables an address on-chip select (CS) and enables a pull-up resistor. The default value of the signal is pull-up. PCH will sample CS and CS# signals. The pull-up resistor is enabled when the signal is pulled up. The pull-up resistor is disabled when the signal is pulled down. 2 = Pull-up resistor is disabled. 3 = Pull-up resistor is disabled. 4 = Pull-up resistor is disabled.

Signal	Usage	When Sampled	Comment
GPP_B23 / SML1ALERT#	Top level Overclock	Rising edge of PCH_PWRON	The signal has a weak internal pull-down. 1 = Disable "Top level" mode. This enables an address on-chip select (CS) and enables a pull-up resistor. The default value of the signal is pull-up. PCH will sample CS and CS# signals. The pull-up resistor is enabled when the signal is pulled up. The pull-up resistor is disabled when the signal is pulled down. 2 = Pull-up resistor is disabled. 3 = Pull-up resistor is disabled. 4 = Pull-up resistor is disabled.
GPP_B22 / GSPII_MOSI	No device	Rising edge of PCH_PWRON	The signal has a weak internal pull-down. 1 = Disable "Top level" mode. This enables an address on-chip select (CS) and enables a pull-up resistor. The default value of the signal is pull-up. PCH will sample CS and CS# signals. The pull-up resistor is enabled when the signal is pulled up. The pull-up resistor is disabled when the signal is pulled down. 2 = Pull-up resistor is disabled. 3 = Pull-up resistor is disabled. 4 = Pull-up resistor is disabled.
GPP_C5 / SMBALERT#	1.5V Core activity	Rising edge of GSPII_MOSI	The signal has a weak internal pull-down. 1 = Disable "Top level" mode. This enables an address on-chip select (CS) and enables a pull-up resistor. The default value of the signal is pull-up. PCH will sample CS and CS# signals. The pull-up resistor is enabled when the signal is pulled up. The pull-up resistor is disabled when the signal is pulled down. 2 = Pull-up resistor is disabled. 3 = Pull-up resistor is disabled. 4 = Pull-up resistor is disabled.

Signal	Usage	When Sampled	Comment
GPP_B14 / SPCR	Top level Overclock	Rising edge of PCH_PWRON	The signal has a weak internal pull-down. 1 = Disable "Top level" mode. This enables an address on-chip select (CS) and enables a pull-up resistor. The default value of the signal is pull-up. PCH will sample CS and CS# signals. The pull-up resistor is enabled when the signal is pulled up. The pull-up resistor is disabled when the signal is pulled down. 2 = Pull-up resistor is disabled. 3 = Pull-up resistor is disabled. 4 = Pull-up resistor is disabled.
GPP_B18 / GSPIO_MOSI	No device	Rising edge of PCH_PWRON	The signal has a weak internal pull-down. 1 = Disable "Top level" mode. This enables an address on-chip select (CS) and enables a pull-up resistor. The default value of the signal is pull-up. PCH will sample CS and CS# signals. The pull-up resistor is enabled when the signal is pulled up. The pull-up resistor is disabled when the signal is pulled down. 2 = Pull-up resistor is disabled. 3 = Pull-up resistor is disabled. 4 = Pull-up resistor is disabled.
GPP_C2 / SMBALERT#	1.5V Core activity	Rising edge of GSPII_MOSI	The signal has a weak internal pull-down. 1 = Disable "Top level" mode. This enables an address on-chip select (CS) and enables a pull-up resistor. The default value of the signal is pull-up. PCH will sample CS and CS# signals. The pull-up resistor is enabled when the signal is pulled up. The pull-up resistor is disabled when the signal is pulled down. 2 = Pull-up resistor is disabled. 3 = Pull-up resistor is disabled. 4 = Pull-up resistor is disabled.

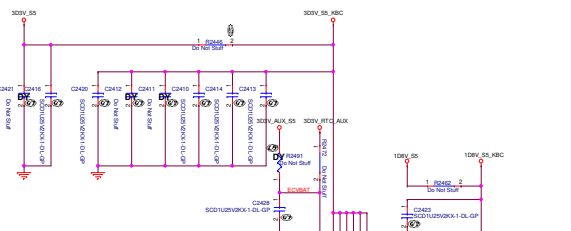
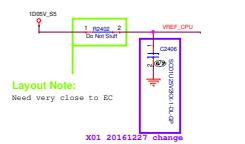
Signal	Usage	When Sampled	Comment
GPP_F23 / DPPF_CTRLDATA	Display Port 7 Detected	Rising edge of PCH_PWRON	The signal has a weak internal pull-down. 1 = Disable "Top level" mode. This enables an address on-chip select (CS) and enables a pull-up resistor. The default value of the signal is pull-up. PCH will sample CS and CS# signals. The pull-up resistor is enabled when the signal is pulled up. The pull-up resistor is disabled when the signal is pulled down. 2 = Pull-up resistor is disabled. 3 = Pull-up resistor is disabled. 4 = Pull-up resistor is disabled.
GPP_J4 / CNV_BRI_DT / UART0_RTS#	XTAL Frequency Select	Rising edge of GSPII_MOSI	The signal has a weak internal pull-down. 1 = Disable "Top level" mode. This enables an address on-chip select (CS) and enables a pull-up resistor. The default value of the signal is pull-up. PCH will sample CS and CS# signals. The pull-up resistor is enabled when the signal is pulled up. The pull-up resistor is disabled when the signal is pulled down. 2 = Pull-up resistor is disabled. 3 = Pull-up resistor is disabled. 4 = Pull-up resistor is disabled.
GPP_J6 / CNV_RGI_DT / UART0_TXD	1.2V CNV Mode Select	Rising edge of GSPII_MOSI	The signal has a weak internal pull-down. 1 = Disable "Top level" mode. This enables an address on-chip select (CS) and enables a pull-up resistor. The default value of the signal is pull-up. PCH will sample CS and CS# signals. The pull-up resistor is enabled when the signal is pulled up. The pull-up resistor is disabled when the signal is pulled down. 2 = Pull-up resistor is disabled. 3 = Pull-up resistor is disabled. 4 = Pull-up resistor is disabled.
GPP_J9	1.5V VCCSPI	Rising edge of GSPII_MOSI	The signal has a weak internal pull-down. 1 = Disable "Top level" mode. This enables an address on-chip select (CS) and enables a pull-up resistor. The default value of the signal is pull-up. PCH will sample CS and CS# signals. The pull-up resistor is enabled when the signal is pulled up. The pull-up resistor is disabled when the signal is pulled down. 2 = Pull-up resistor is disabled. 3 = Pull-up resistor is disabled. 4 = Pull-up resistor is disabled.
GPD7	Reserved	Rising edge of GSPII_MOSI	The signal has a weak internal pull-down. 1 = Disable "Top level" mode. This enables an address on-chip select (CS) and enables a pull-up resistor. The default value of the signal is pull-up. PCH will sample CS and CS# signals. The pull-up resistor is enabled when the signal is pulled up. The pull-up resistor is disabled when the signal is pulled down. 2 = Pull-up resistor is disabled. 3 = Pull-up resistor is disabled. 4 = Pull-up resistor is disabled.



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DELL		Wistron Corporation	
21F, 8B, Sec. 1, Hsin Tai Wu Rd., Hsinchu, Taipei Hsin 221, Taiwan, R.O.C.			
Title PCH_(VSS/GPIO)			
Size Custom	Document Number	Rev	
Selek CFL-H		A00	
Date: Wednesday, April 03, 2019	Sheet 23	of 105	

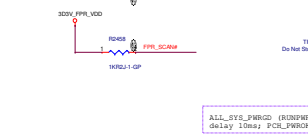
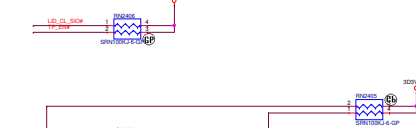
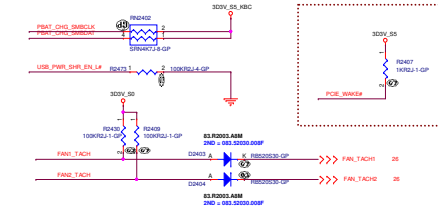
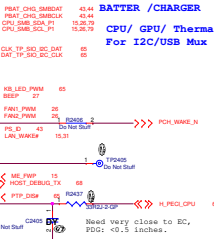
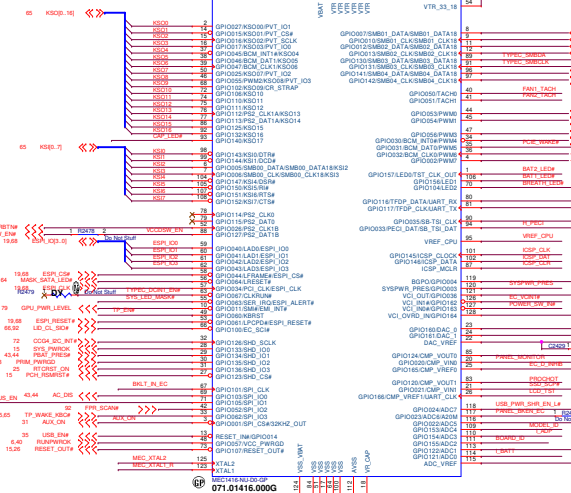
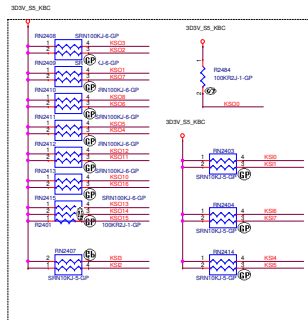
Main Func = KBC



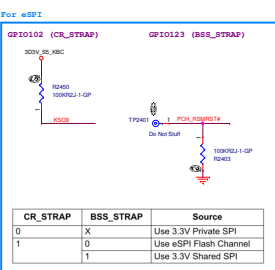
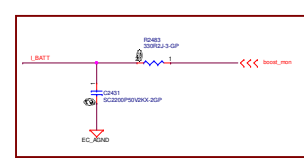
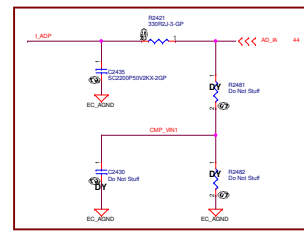
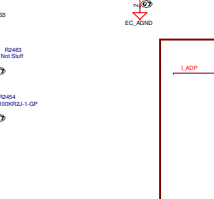
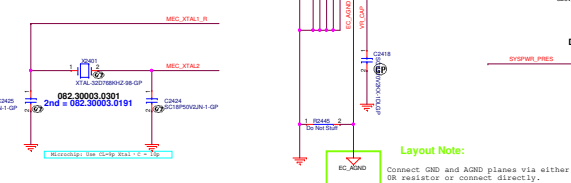
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1	X00	100.0K	10.0K	3
2	X01	100.0K	17.8K	2.801
3	X02	100.0K	27.0K	2.598
4	X03(reserve)	100.0K	37.4K	2.402
5	A00	100.0K	49.9K	2.201
6	A01	100.0K	64.9K	2.001
7	A02	100.0K	82.5K	1.808
8	A03	100.0K	107K	1.594
9	Reserve	100.0K	154K	1.299
10	Reserve	100.0K	200K	1.1
11	Reserve	100.0K	TBD	0.9
12	Reserve	100.0K	TBD	0.7
13	Reserve	100.0K	TBD	0.5
14	Reserve	100.0K	TBD	0.3



#	Model (DGP015)	PULL-LOW RESISTANCE	PULL-HIGH RESISTANCE	VOLTAGE
1	Nvala-N1PG-KG	100.0K Ω	10.0K Ω	3
2		100.0K Ω	17.8K Ω	2.801
3	Nvala-N1SP-GO	100.0K Ω	72.9K Ω	2.598
4		100.0K Ω	42.6K Ω	2.402
5	Nvala-N1SE-GO	100.0K Ω	49.9K Ω	2.201
6		100.0K Ω	64.9K Ω	2.001
7	Nvala-N1SE-G1	100.0K Ω	82.5K Ω	1.808
8		100.0K Ω	107K Ω	1.594
9		100.0K Ω	150K Ω	1.289
10		100.0K Ω	200K Ω	1.1
11	Reserve	100.0K Ω	TBD	0.9
12	Reserve	100.0K Ω	TBD	0.7
13	Reserve	100.0K Ω	TBD	0.5
14	Reserve	100.0K Ω	TBD	0.3

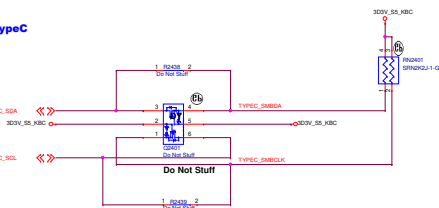
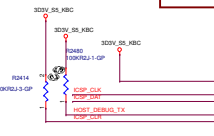
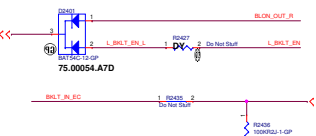


```
ALL_SYS_PWRGD (RUNPMWOK)assert,  
delay 10ms; PCH_PWROK( RESET_OUT# )assert.
```



CR_STRAP	BSS_STRAP	Source
0	X	Use 3.3V Private SPI
1	0	Use eSPI Flash Channel
	1	Use 3.3V Shared SPI

Note	Description
Note 16	If the eSPI Flash Channel is used for booting, the GPIO123/SHD_CS# pin must be used as RSMRST#. This pin will be driven high by the boot ROM code in order to activate the eSPI flash channel. If the SHD_SPI port is used for booting, then any unused GPIO may be used for RSMRST#.

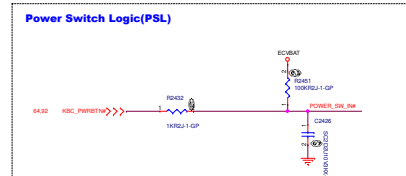
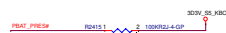
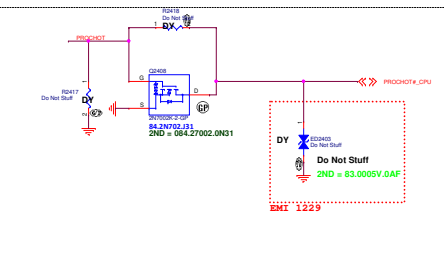


For USB TypeC

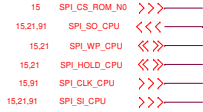
For CCG5

Need check

Follow EV project circuit DY Q2417 (R013_2017102



SSID = Flash.ROM



Main Func = RTC

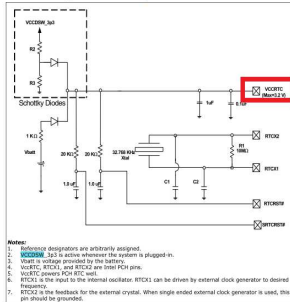
BTY RTC CR2016_30MM KTS 2PIN

1st= 23.25212.011

-1 20161118



Figure 28-2. External Circuitry for the PCH RTC - Option 1



Notes:

1. Reference designators are arbitrarily assigned.
2. **VCCDSW**, 3p3 is active whenever the system is plugged-in.
3. **VDD** is voltage provided by the battery.
4. **VccRTC**, **RTCK1**, and **RTCK2** are Intel PCH pins.
5. **VccRTC** powers PCH RTC well.
6. **RTCK1** is the input to the internal oscillator. **RTCK1** can be driven by external clock generator to desired frequency.
7. **RTCK2** is the feedback for the external crystal. When single ended external clock generator is used, this pin should be grounded.

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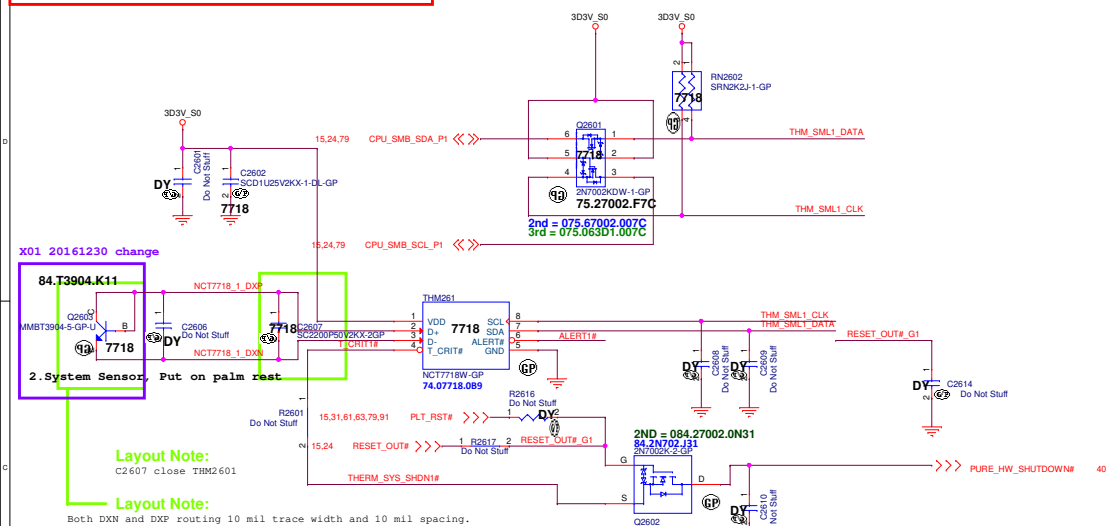
DELL **Wistron Corporation**
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title	Flash(KBC+PCH)/RTC
-------	---------------------------

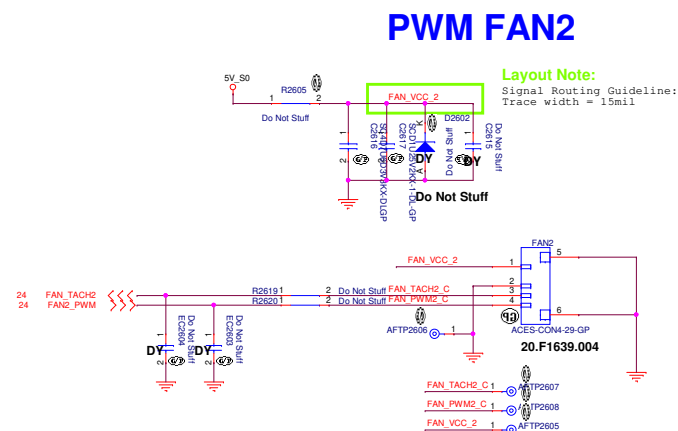
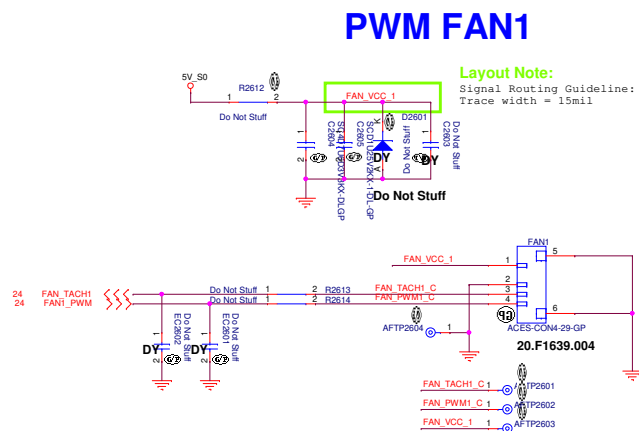
Size A2	Document Number Selek CFL-H	Rev A00
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Date: Wednesday, April 03, 2019	Sheet 25 of 105
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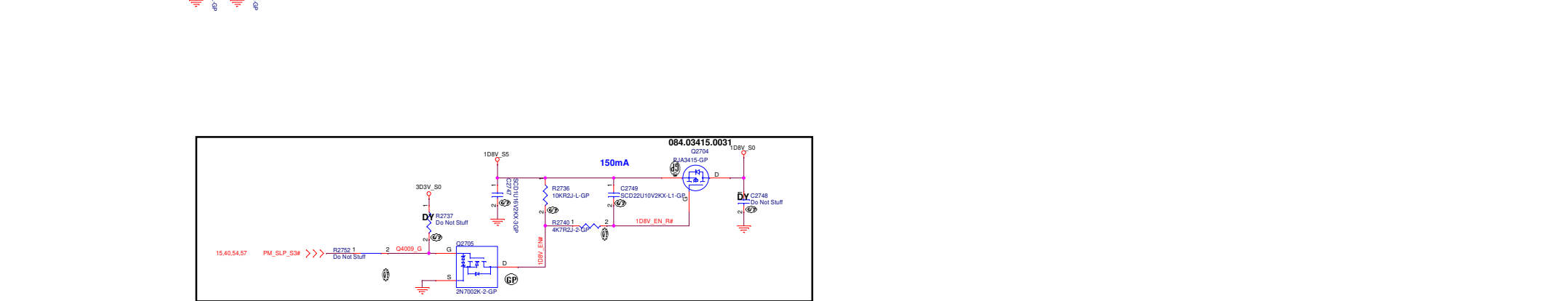
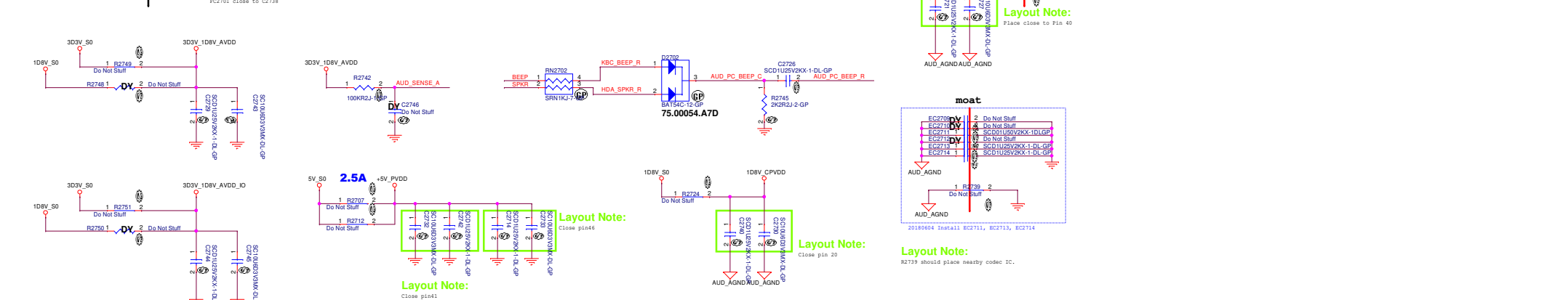
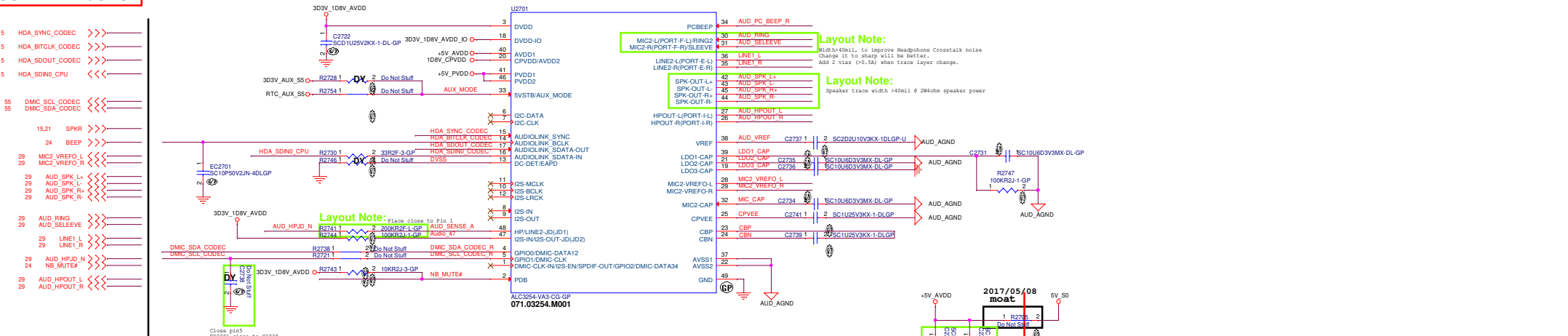
5
Main Func = Thermal Sensor

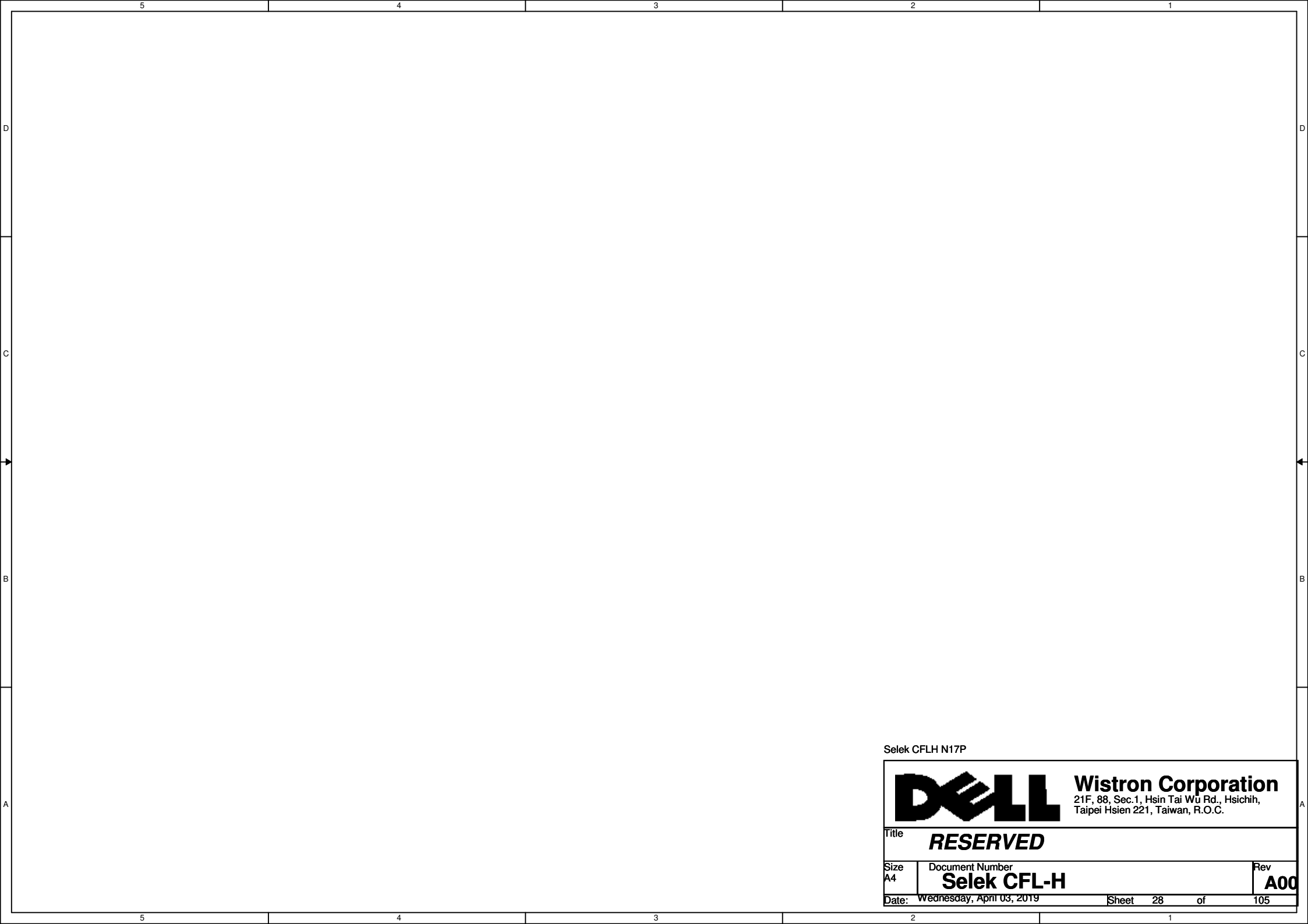


TEMPERATURE (°C)		T_CRIT#				
		2KΩ	7.5KΩ	10.5KΩ	14KΩ	18.7KΩ
ALERT#	2KΩ	77	87	97	107	117
	7.5KΩ	79	89	99	109	119
	10.5KΩ	81	91	101	111	121
	14KΩ	83	93	103	113	123
	18.7KΩ	85	95	105	115	125



SSID = Audio





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		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title RESERVED			
Size A4	Document Number Selek CFL-H		Rev A00
Date: Wednesday, April 03, 2019		Sheet 28 of	105

Main Func = Audio

20 SPK_ID <<>>

27 AUD_SPK_L+ >>>>

27 AUD_SPK_L- >>>>

27 AUD_SPK_R+ >>>>

27 AUD_SPK_R- >>>>

27 MIC2_VREFO_R >>>>

27 MIC2_VREFO_L >>>>

27 AUD_RING <<<<

27 AUD_HPOUT_L >>>>

27 LINE1_L >>>>

27 AUD_HPOUT_R >>>>

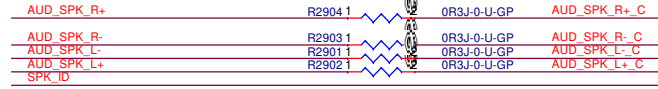
27 LINE1_R >>>>

27 AUD_SELEEVE <<<<

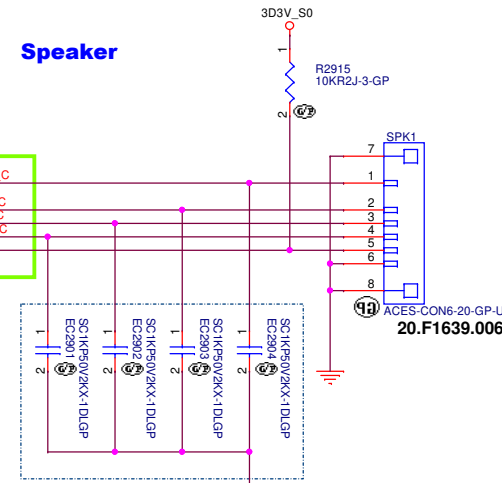
27 AUD_HPJD_N <<<<

Layout Note:

Speaker trace width >40mil @ 2W4ohm speaker power

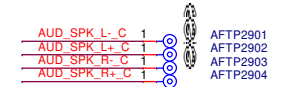


Speaker

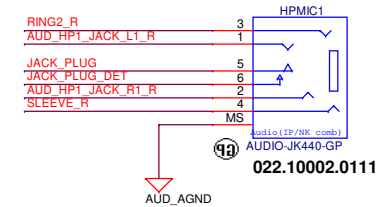
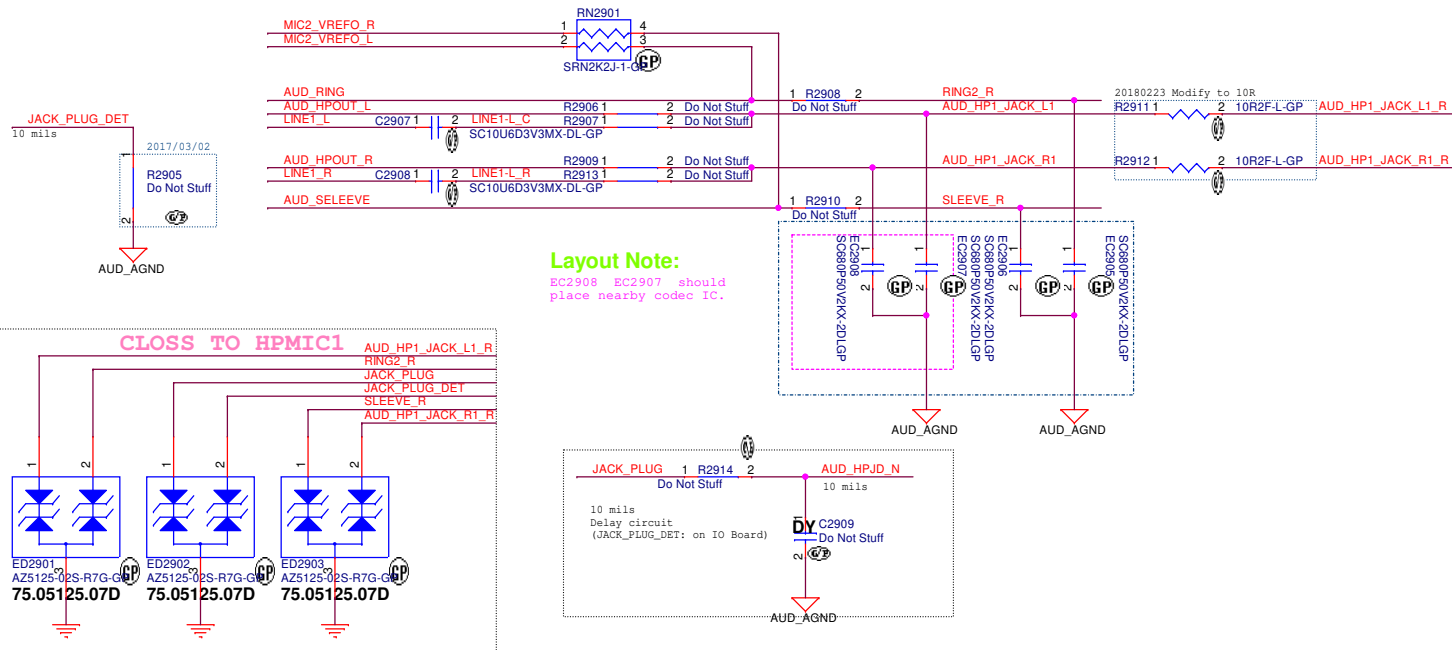


12/17 Clark move close to connector

CONN Pin	Net name
Pin1	SPK_L+
Pin2	SPK_L-
Pin3	SPK_R-
Pin4	SPK_R+
Pin5	SPK_DET#
Pin6	GND



Universal Jack (Moved to I/O Board)

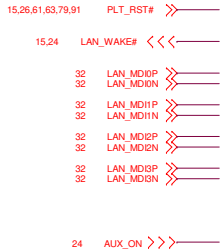


Selek CFLH N17P

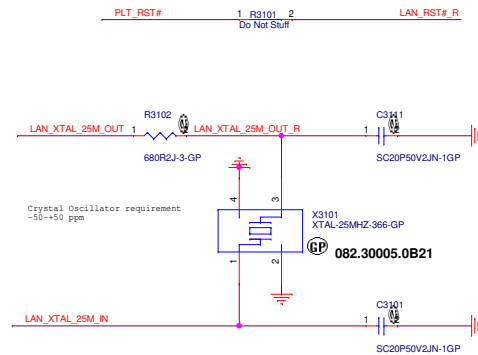
5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

Selek CFLH N17P

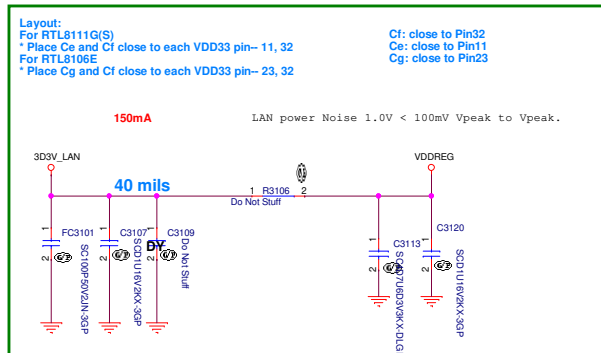
		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title (Reserved)			
Size A	Document Number Selek CFL-H		Rev A00
Date:	Wednesday, April 03, 2019	Sheet 30 of	105



Lan wake pull up on page 15

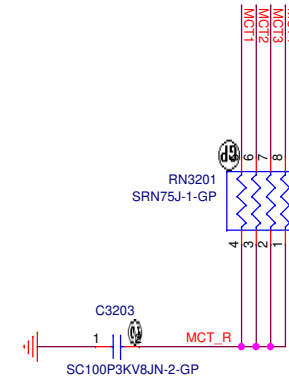
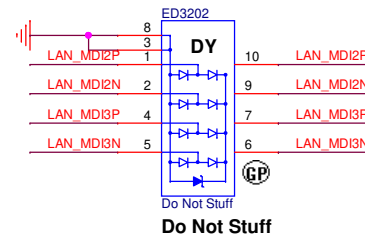
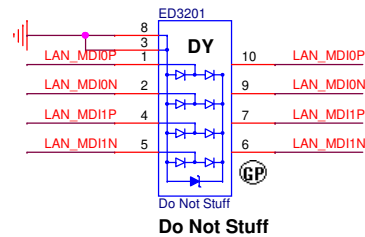
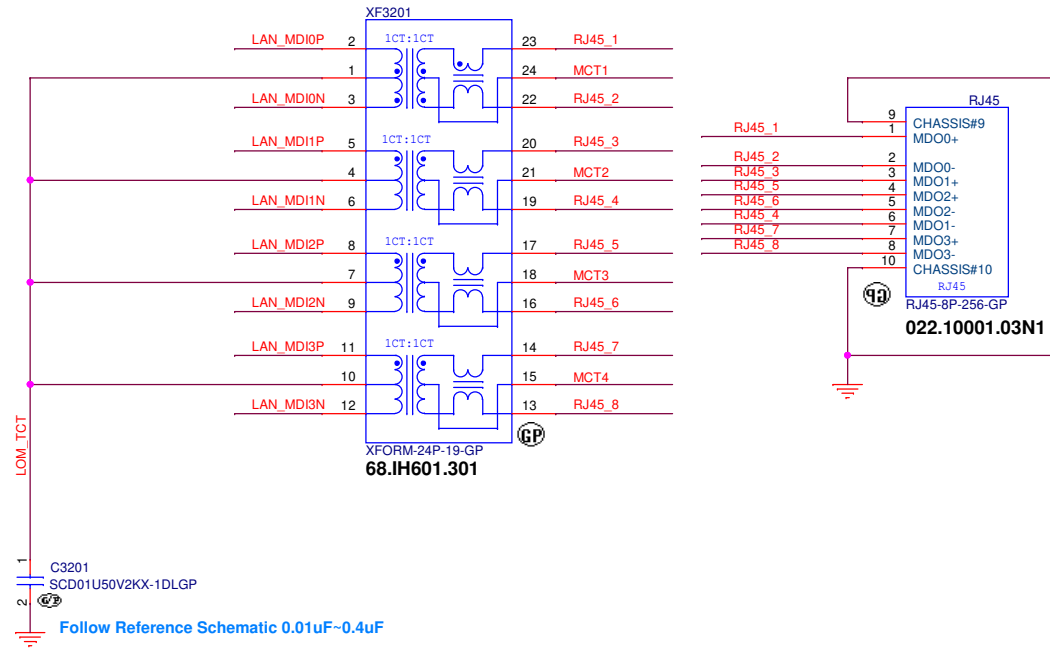


RTL8111HSD-CGT
071.8111H.M001
SWR mode
10/100/1000M



SSID = LAN

31 LAN_MDI0P
31 LAN_MDI0N
31 LAN_MDI1P
31 LAN_MDI1N
31 LAN_MDI2P
31 LAN_MDI2N
31 LAN_MDI3P
31 LAN_MDI3N



Selek CFLH N17P

DELL		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title RJ45+Transformer			
Size B	Document Number Selek CFL-H		Rev A00
Date: Wednesday, April 03, 2019		Sheet 32	of 105

SSID = Card Reader

Selek CFLH N17P



Title (Reserved)

Size A2	Document Number Selek CFL-H	Rev A00
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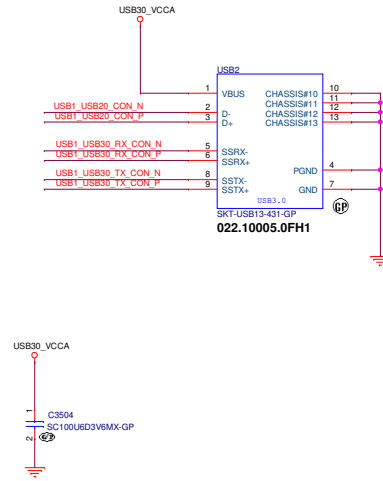
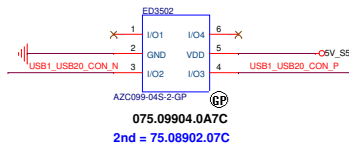
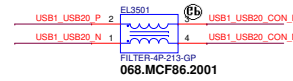
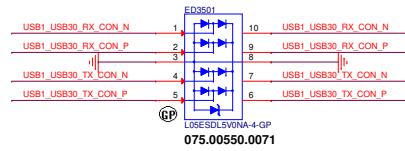
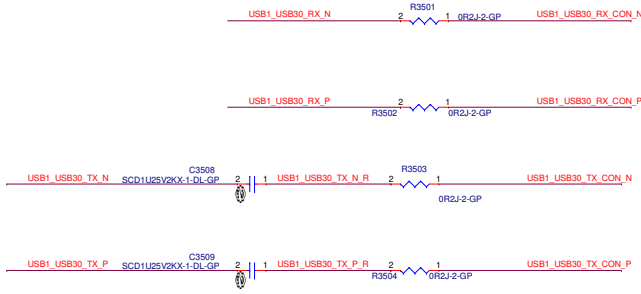
Date: Wednesday, April 03, 2019	Sheet 33 of 106
---------------------------------	-----------------

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D				D
C				C
B				B
A				A
5	4	3	2	1

Selek CFLH N17P

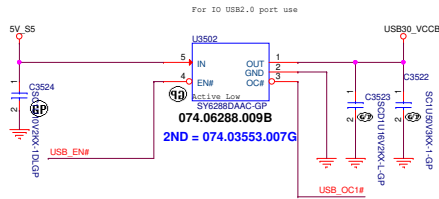
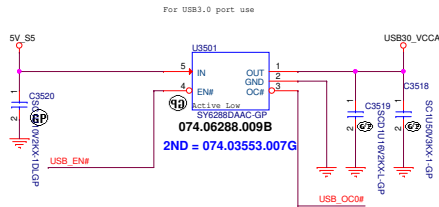
		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title (Reserved)			
Size A	Document Number Selek CFL-H		Rev A00
Date:	Wednesday, April 03, 2019	Sheet 34 of	105

19 USB1_USB30_RX_N << <<
19 USB1_USB30_RX_P >> >>
19 USB1_USB30_TX_N >> >>
19 USB1_USB30_TX_P << <<
18 USB1_USB20_P << <<
18 USB1_USB20_N << <<



USB 3.0 Connector Pin definition	
1	POWER
2	USB 2.0 D-
3	USB 2.0 D+
4	GND
5	StdA_SSRX- SuperSpeed RX
6	StdA_SSRX+ SuperSpeed RX
7	GND
8	StdA_SSTX- SuperSpeed TX
9	StdA_SSTX+ SuperSpeed TX

24,35 USB_EN# >>>
18 USB_OC0# <<<



24,35 USB_EN# >>>
18 USB_OC1# <<<

Selek CFLH N17P

DELL Wistron Corporation	
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsinchu, Taipei Hsin 221, Taiwan, P.O.C.	
Title USB3.0*2 CONN	
Size Custom	Document Number Selek CFL-H
Date: Wednesday, April 03, 2019	Rev A00
Sheet 35	of 105

5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

Selek CFLH N17P

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title (Reserved)			
Size A	Document Number Selek CFL-H		Rev A00
Date:	Wednesday, April 03, 2019	Sheet 37 of	105

SSID = USB3.0 Redrivere

USB 3.0 Re-driver Pull High / Low

Selek CFLH N17P



Wistron Corporation
21F, 8B, Sec.1, Hsin Tai Wu Rd., Hsuehshien,
Taipei Hsien 221, Taiwan, R.O.C.

Title

USB 3.0 Redriver

Size

A2

Document Number

Selek CFL-H

Rev

A00

Date

Wednesday, April 03, 2019

Sheet

38

of

106

5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

Selek CFLH N17P

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title (Reserved)			
Size A	Document Number Selek CFL-H		Rev A00
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Main Func = Power & Sequence

Selek CFLH N17P

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title		Connected_Standby(1/2)+DS3	
Size A3	Document Number Selek CFL-H		Rev A00
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D

C

B

A

Selek CFLH N17P



Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

(Reserved)

Size

A

Document Number

Selek CFL-H

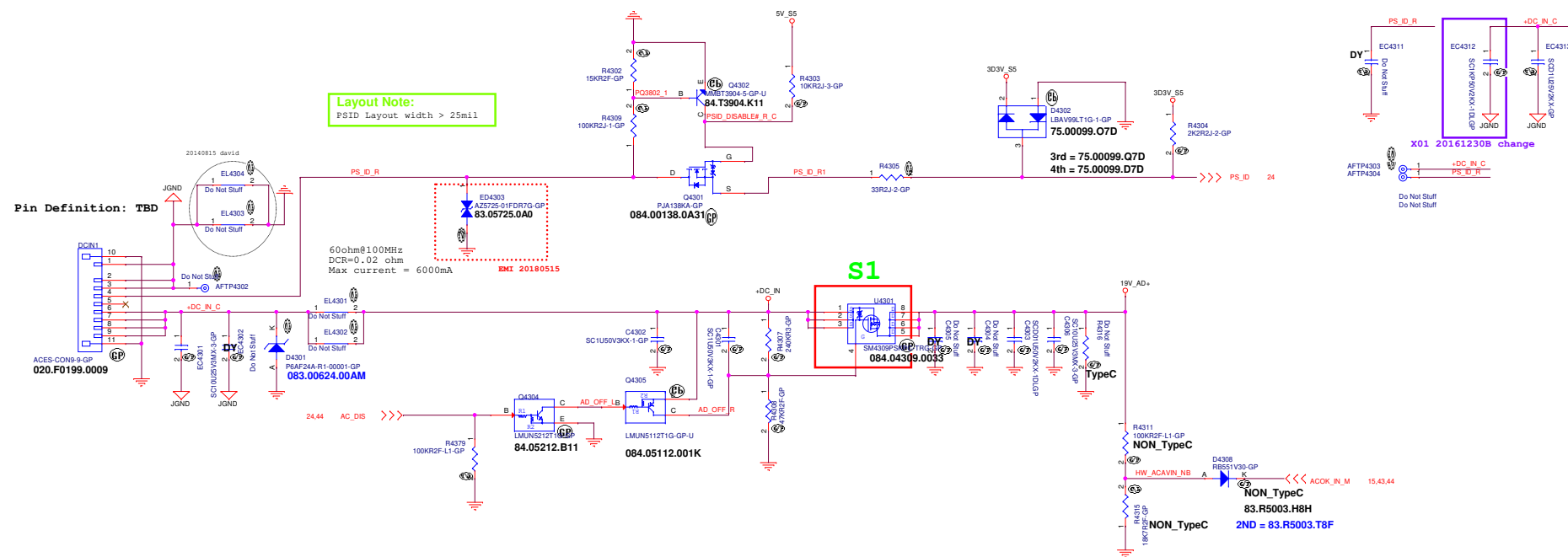
Rev

A00

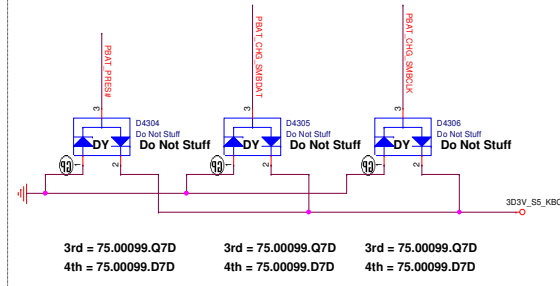
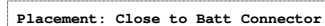
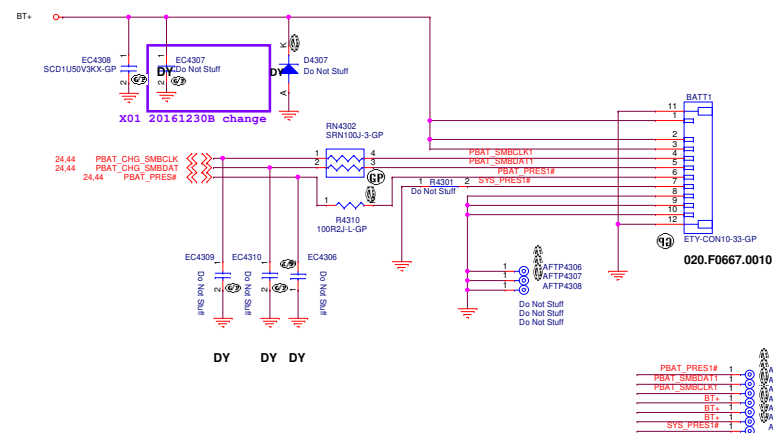
Date: Wednesday, April 03, 2019

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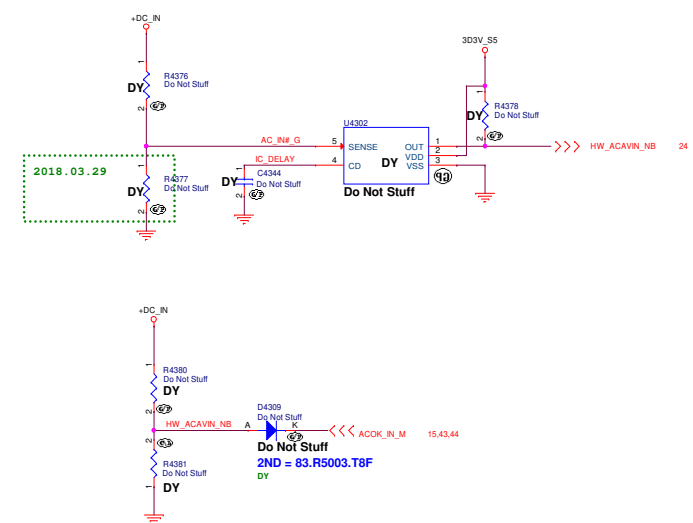
Main Func = ADT Input



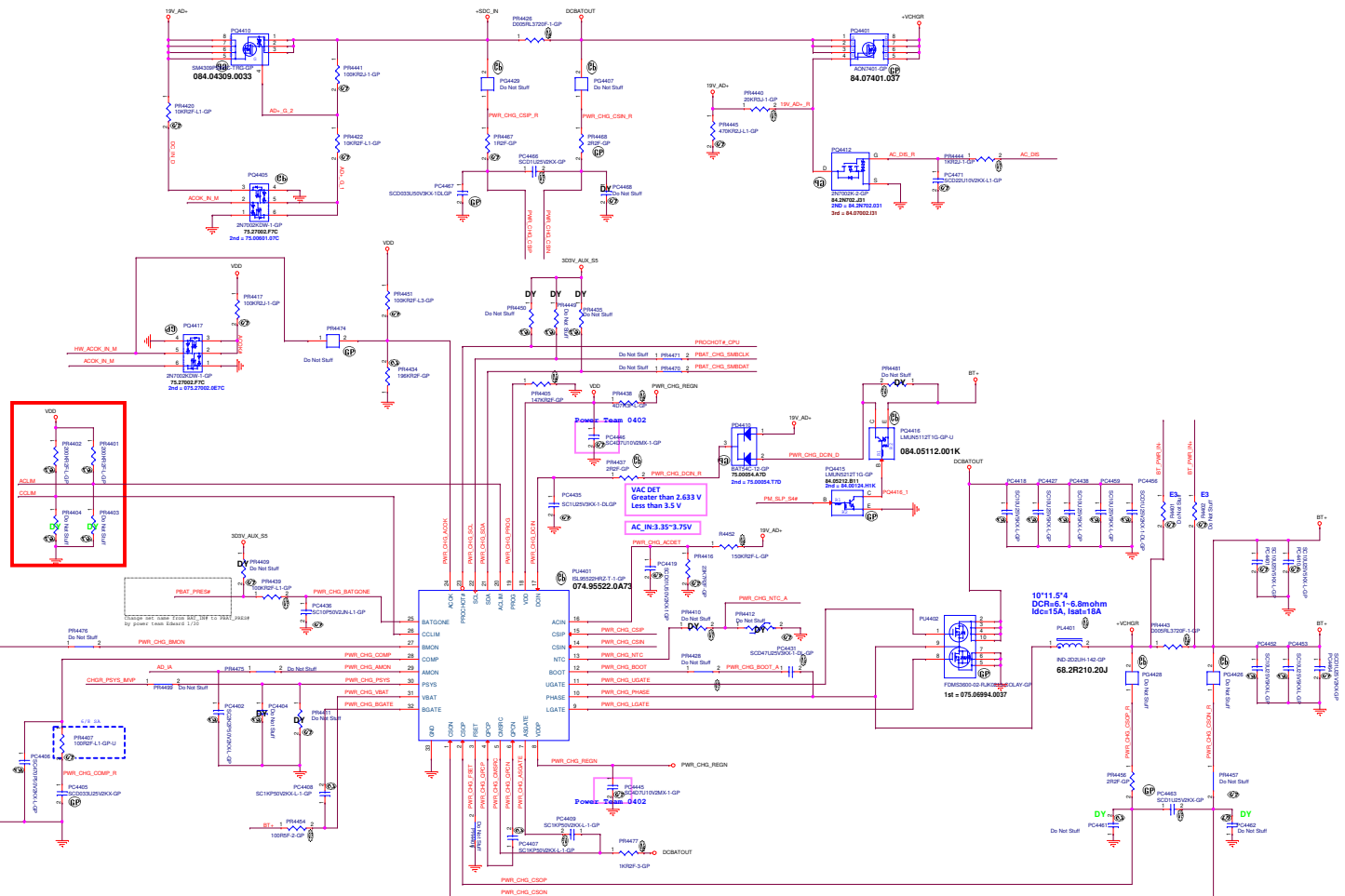
Main Func = M-BAT Input

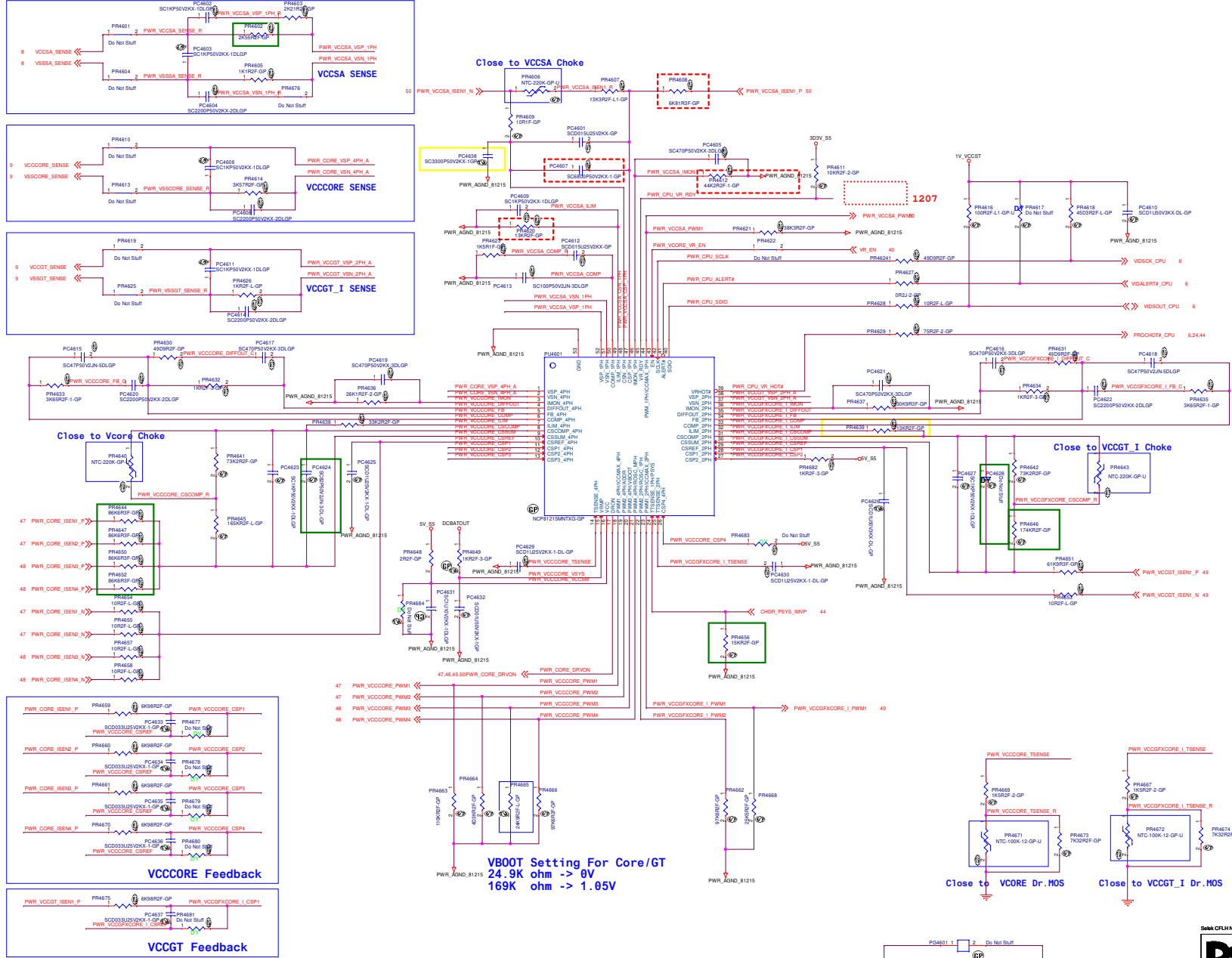


Barrel Adapter Piug-in Detect



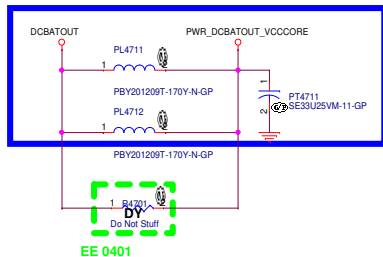
$$I_{ACLIMHW} = \frac{V_{ACLIMHW}}{32 \times PR4433}$$

$$I_{CCLIMHW} = \frac{V_{CCLIMHW}}{32 \times PR4436}$$
[illegible]



Add : PWR GAP
change GND symbol on this page ALL GND

For acousaic noise 1228



Max Current = 3.50(A)

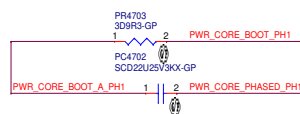
PWR_DCBATOUT_VCCCORE

MLCCs must be placed
symmetrically on Top and Bottom.

Max Current = 3.50(A)

PWR_DCBATOUT_VCCCORE

MLCCs must be placed
symmetrically on Top and Bottom.



074.30204.0AE3

074.30204.0AE3

074.30204.0AE3

074.30204.0AE3

074.30204.0AE3

074.30204.0AE3

074.30204.0AE3

074.30204.0AE3

074.30204.0AE3

074.30204.0AE3

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074.30204.0AE3

074.30204.0AE3

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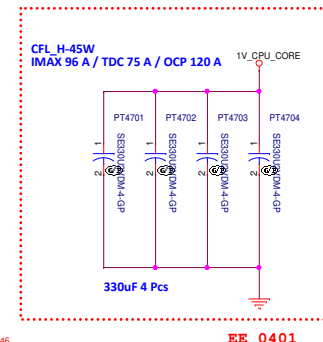
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074.30204.0AE3

074.30204.0AE3

074.30204.0AE3

074.30204.0AE3



Selek CFLH N17P

DELL Wistron Corporation
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Taippei Hsien 221, Taiwan, R.O.C.

Title
DC/DC VCCCPUCORE (1/2)

Size
C Document Number
Selek CFL-H

Rev
A00

Date: Wednesday, April 03, 2019

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Max Current = 3.50(A)

PWR_DCBATOUT_VCCCORE

MLCCs must be placed
symmetrically on Top and Bottom.

Max Current = 3.50(A)

PWR_DCBATOUT_VCCCORE

MLCCs must be placed
symmetrically on Top and Bottom.

This circuit is for Hexa core.
Please refer to the table in next page.

Selek CFLH N17P

DELL Wistron Corporation
21F, 88, Sec 1, Hsin Tai Wu Rd., Hsichih,
Taippei Hsien 221, Taiwan, R.O.C.

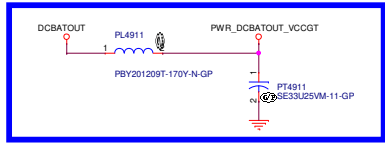
Title
DC/DC VCCCPUCORE (2/2)

Size
C Document Number
Selek CFL-H

Date: Wednesday, April 03, 2019

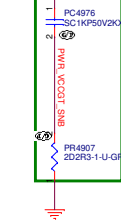
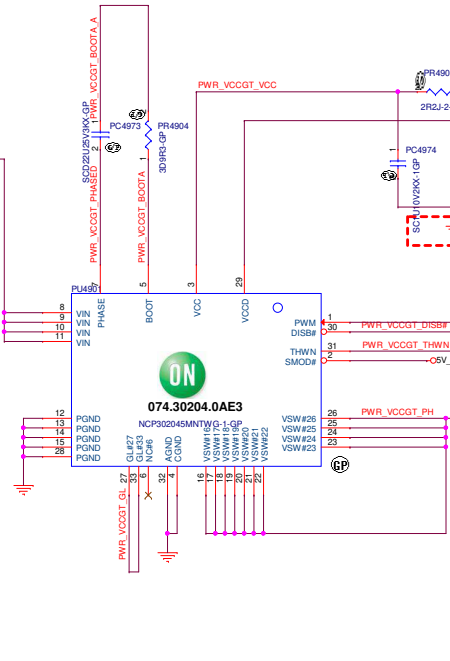
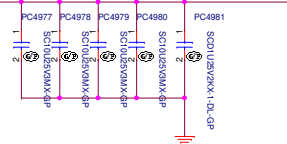
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Rev
A00



For acousaic noise 1228

PWR_DCBATOUT_VCCGT



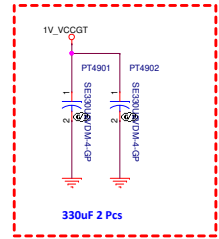
Add comment :
MLCCs (Input capacitors at charger)
must placed symmetrically on TOP and BOTTOM side

CFL_H-45W
IMAX 32 A / TDC 25 A / OCP 60 A

1V_VCCGT

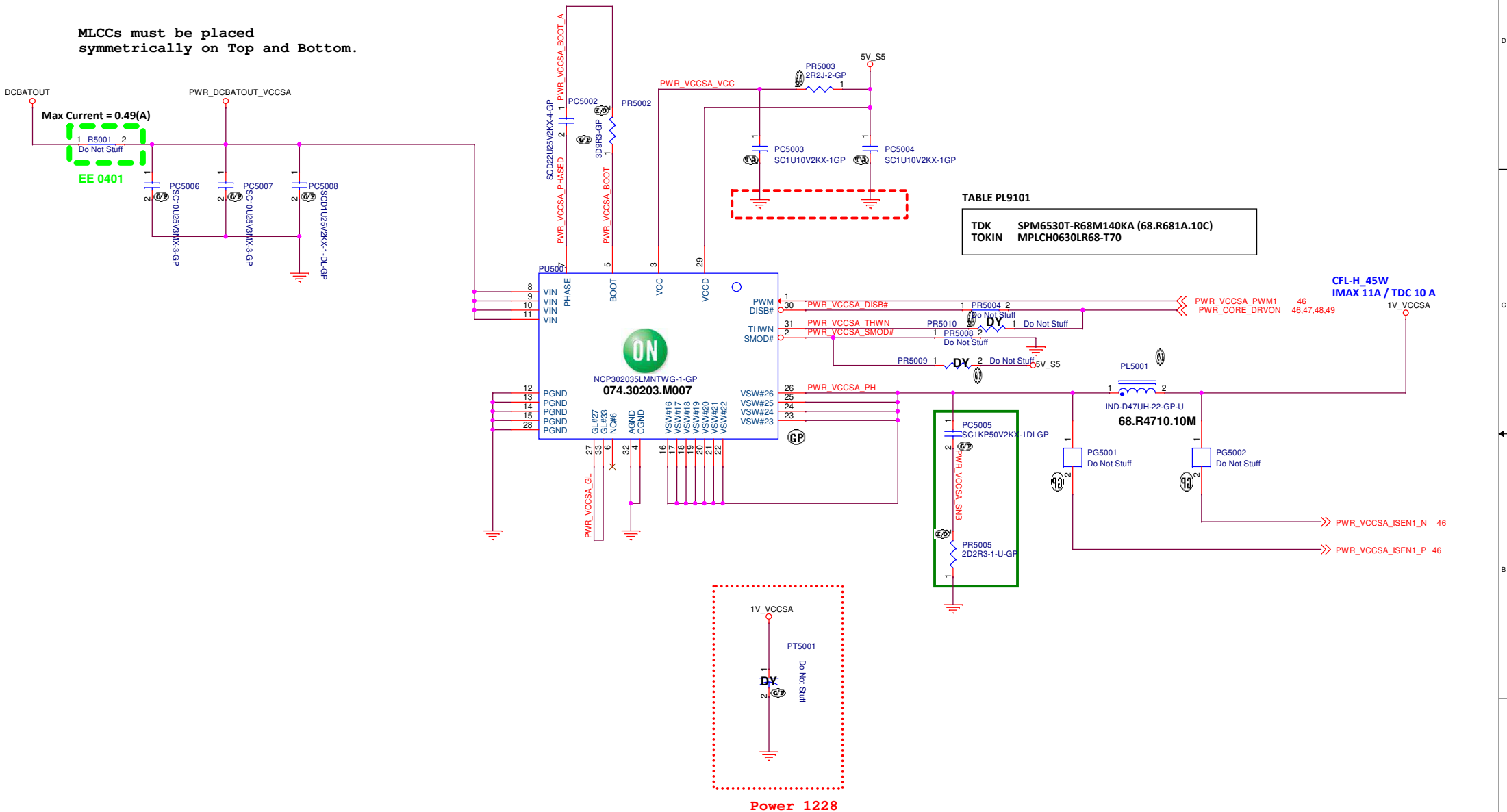
PWR_VCCGT_ISEN1_N 46
PWR_VCCGT_ISEN1_P 46

CFL_H-45W
IMAX 32 A / TDC 25 A / OCP 60 A



330uF 2 Pcs
Power 0401

MLCCs must be placed
symmetrically on Top and Bottom.



Selek CFLH N17P

SSID = PWR.Plane.Regulator_1D05V

OFFPAGE-Signal

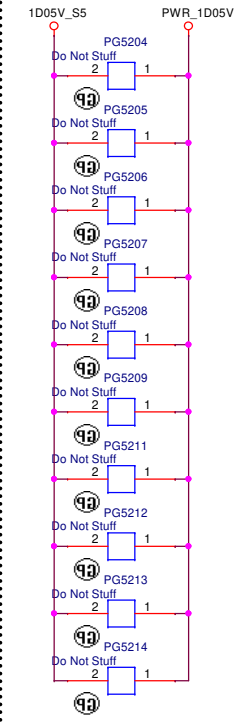
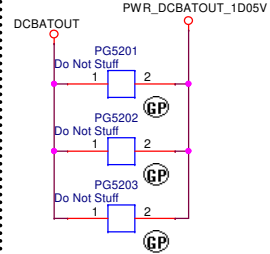
PH on EE Side

PWR_1D05V_PG

3V_5V_DSW_OK

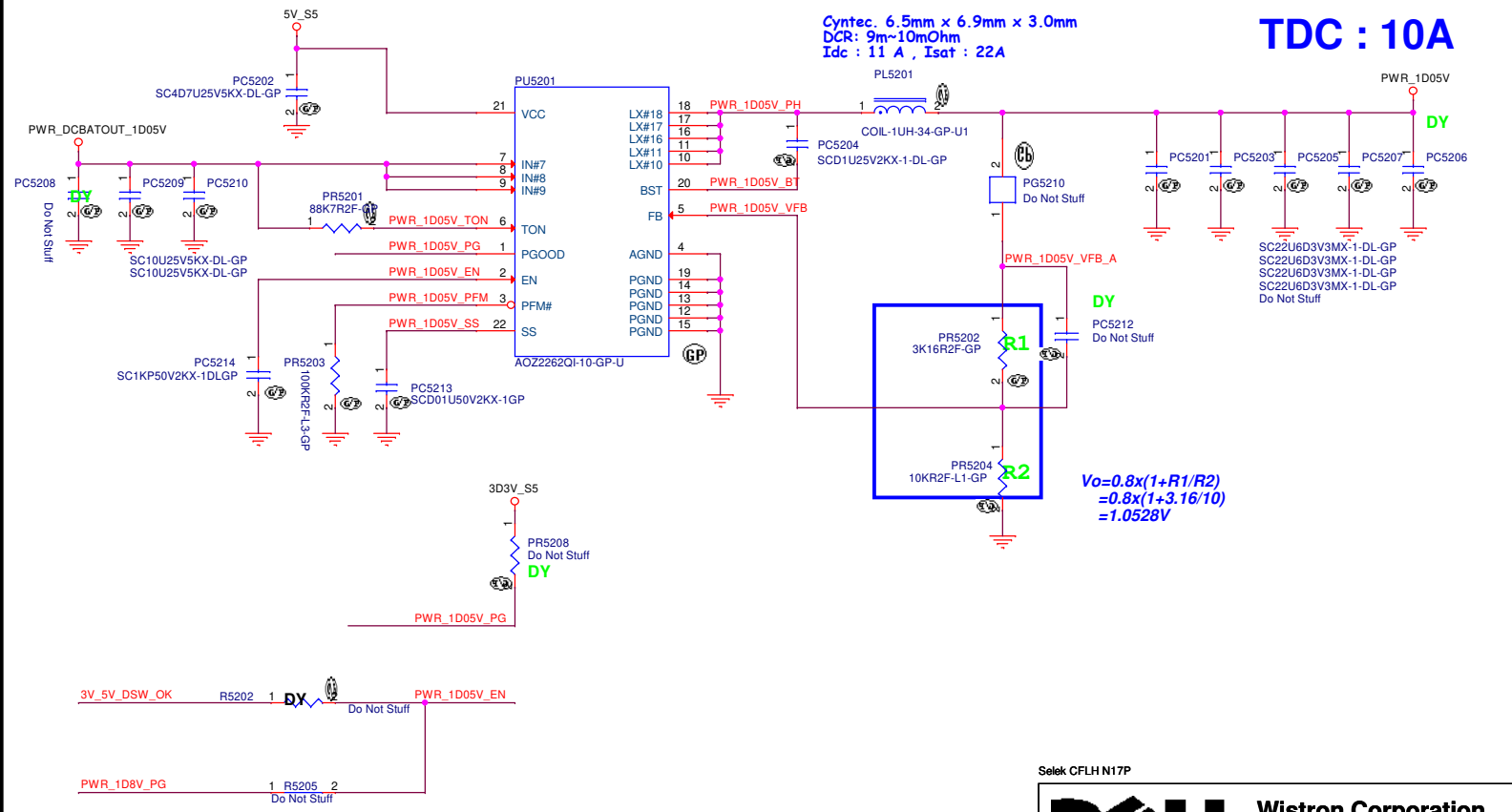
PWR_1D8V_PG

OFFPAGE-GAP



AOZ2262 For 1D05V

COM	IC	AOZ2262 (10A)	AOZ2261 (8A)	AOZ2260 (6A)
		074.02262.0043	074.02261.0A73	074.02260.0043
Chock		68.1R01A.20B IDC : 10A	68.1R01A.20B IDC : 10A	68.1R01A.20B IDC : 10A
Output CAP		22uF/6.3V * 5pcs DY*1	22uF/6.3V * 4pcs DY*1	22uF/6.3V * 4pcs DY*1



TDC : 10A

$$V_o = 0.8x(1+R1/R2) = 0.8x(1+3.16/10) = 1.0528V$$

Selek CFLH N17P



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title **POWER (AOZ2262_1D05V)**

Size A3	Document Number Selek CFL-H	Rev A00
Date: Wednesday, April 03, 2019	Sheet 52 of	105

Main Func = 1D8V

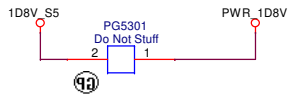
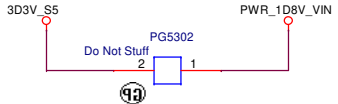
OFFPAGE

25,52 3V_5V_DSW_OK >>



52 PWR_1D8V_PG <<

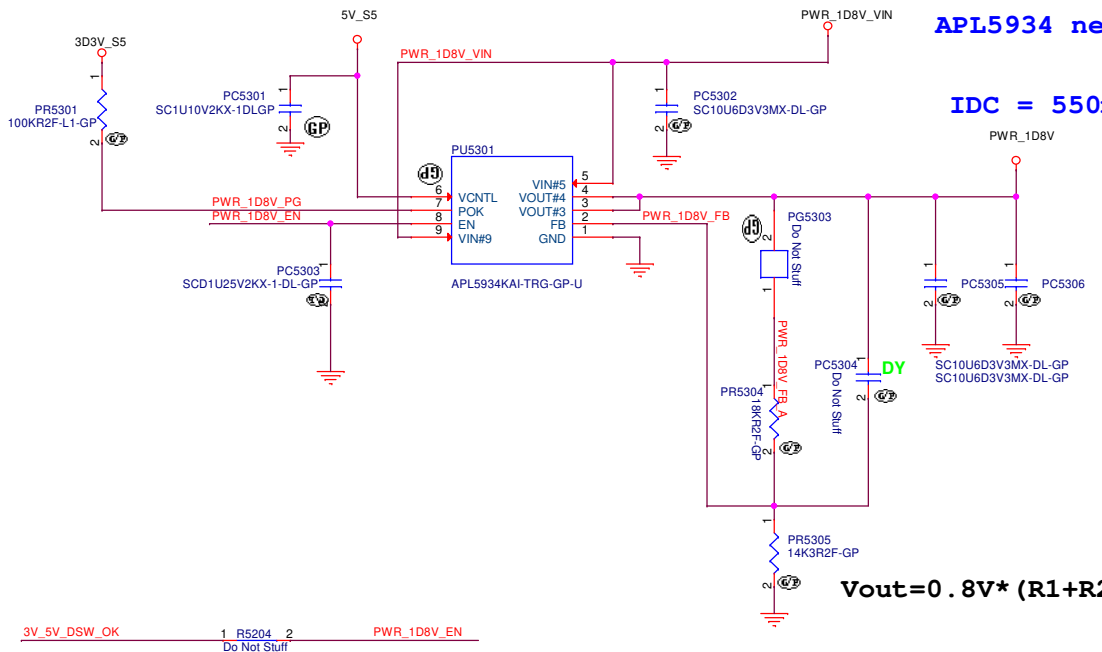
OFFPAGE_GAP



APL5934 for 1D8V

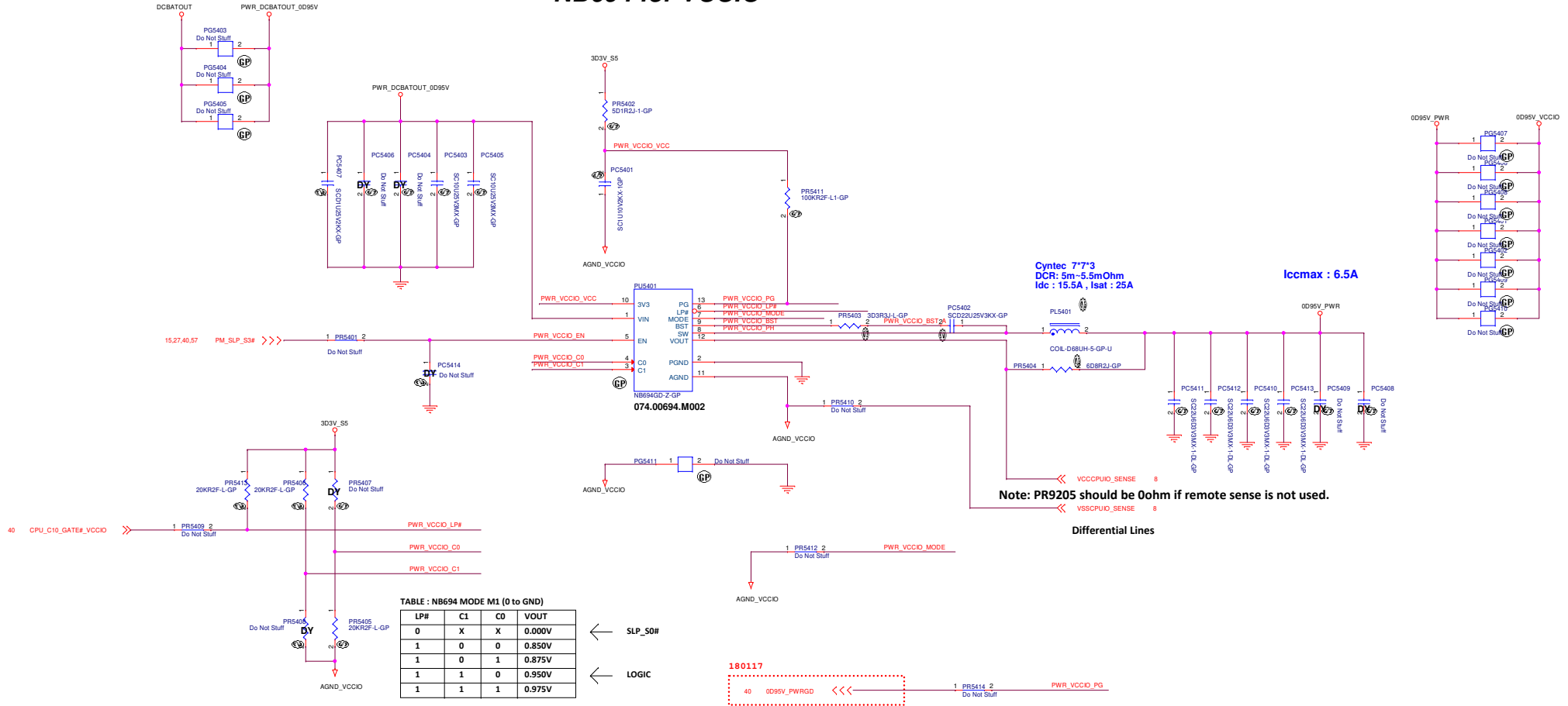
APL5934 need <1.8W

IDC = 550mA

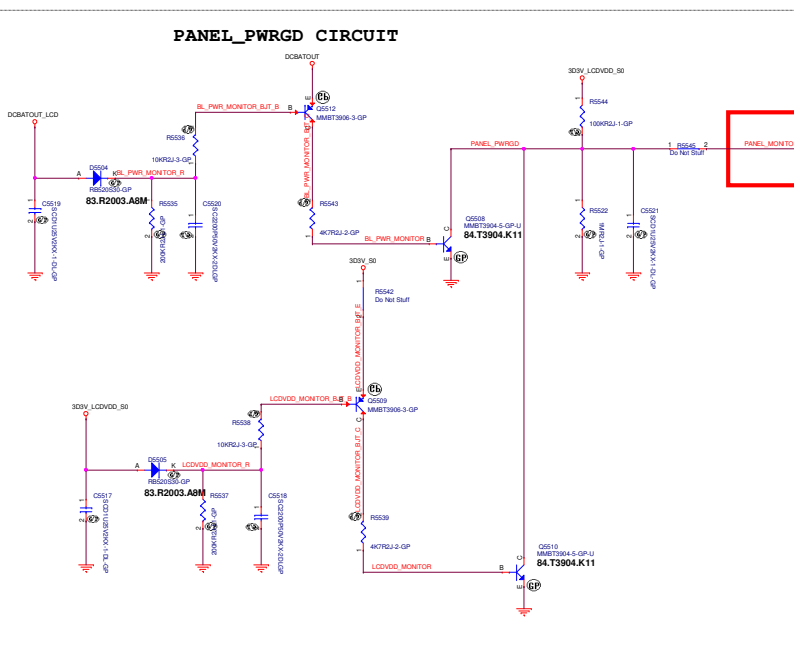


$$V_{out} = 0.8V * (R1 + R2) / R2$$

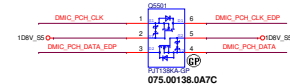
NB694 for VCCIO



Selek CFLH N17P



Reserved for one time fuse: 69.43001.201
303V_S0



D

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C

1.

5

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A

1

1

Selek CFLH N17P



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title **LCD/Inverter Connector**

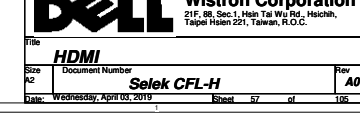
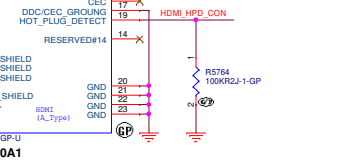
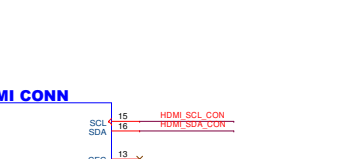
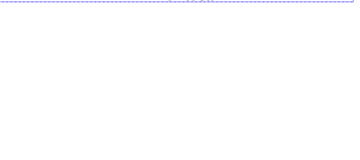
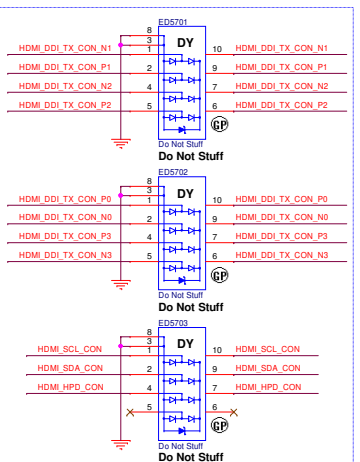
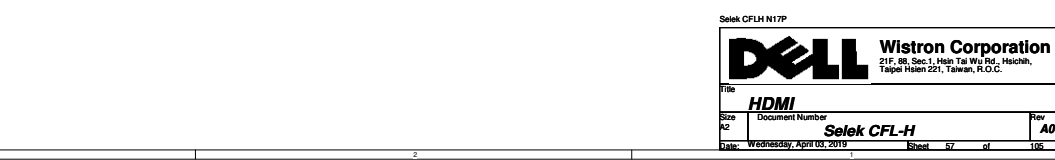
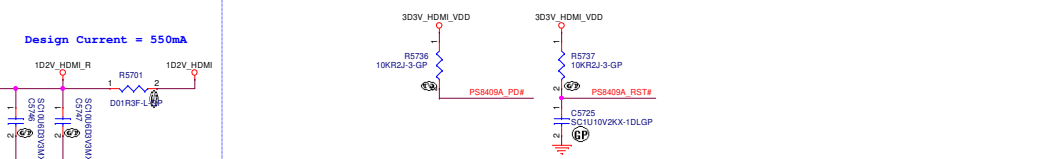
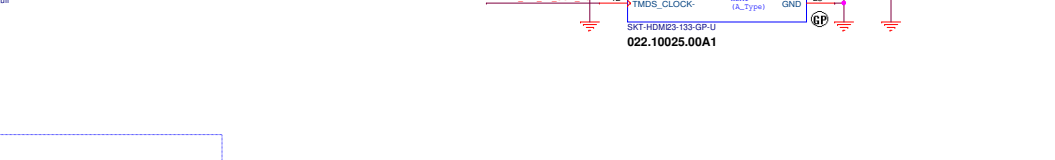
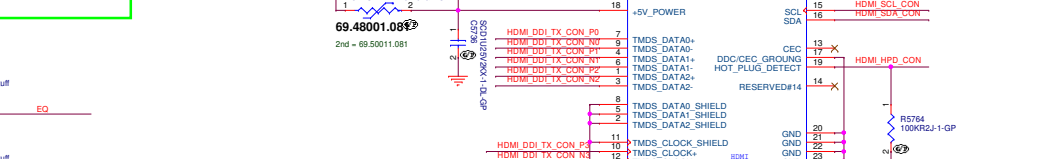
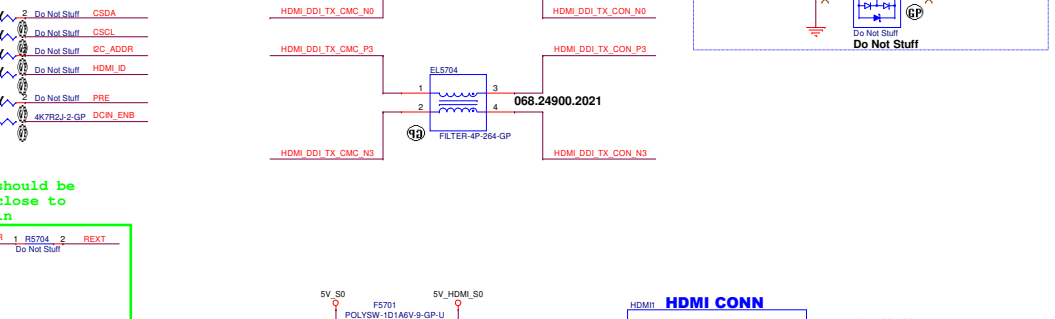
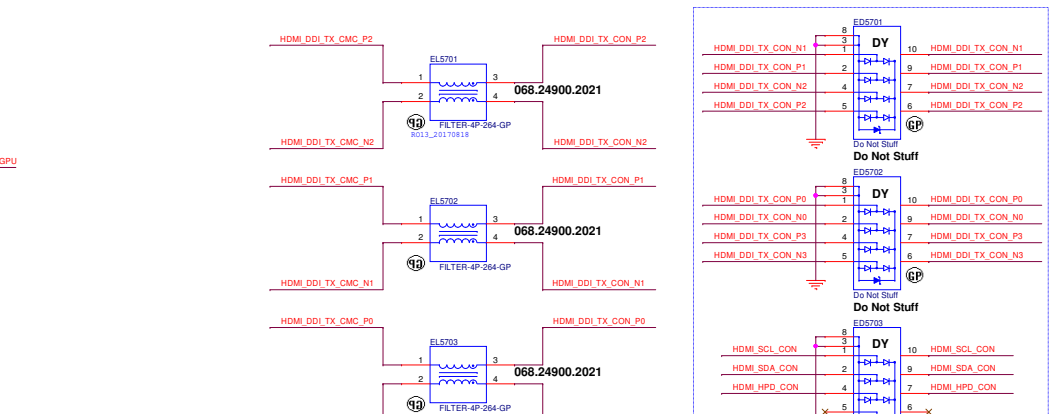
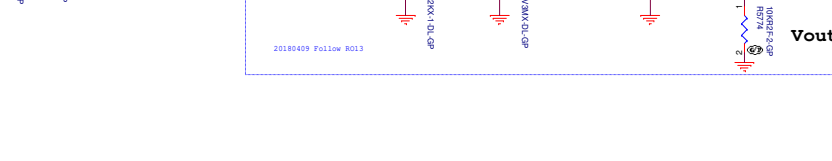
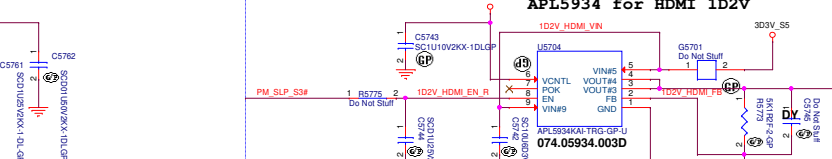
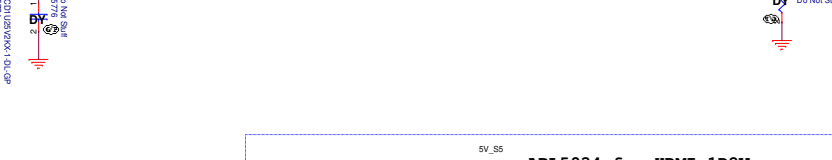
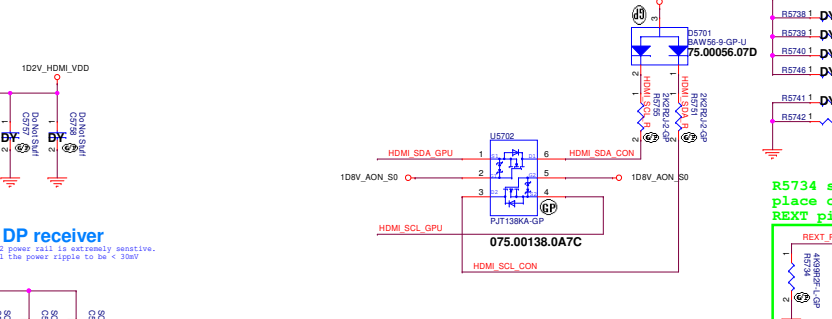
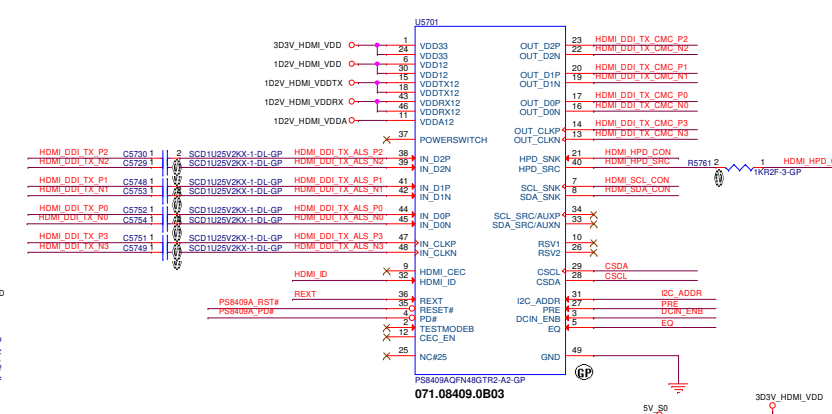
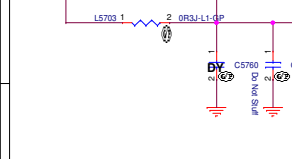
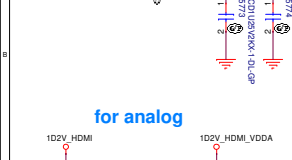
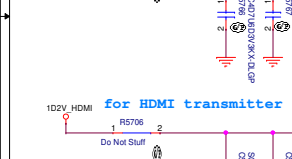
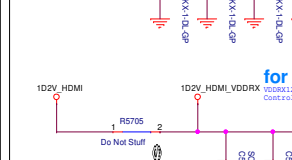
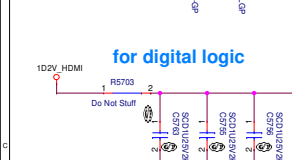
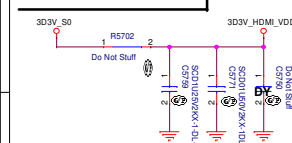
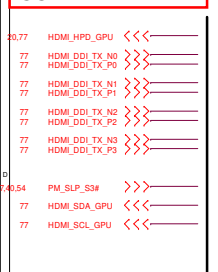
Size
Custom
Date:

Document Number
Selek CFL-H

Rev	A00
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SSID = HDMI



	5	4	3	2	1
D					D
C					C
B					B
A					A
	5	4	3	2	1

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Title (Reserved)			
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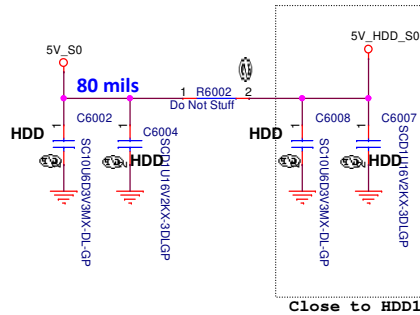
5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

Selek CFLH N17P

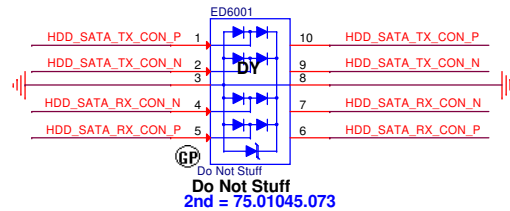
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Title (Reserved)			
Size A	Document Number Selek CFL-H		Rev A00
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Main Func = HDD

17 HDD_SATA_TX_P >>>
17 HDD_SATA_TX_N <<<
17 HDD_SATA_RX_N <<<
17 HDD_SATA_RX_P >>>
19 HDD_DEVSLP >>>
70 FFS_INT2_Q >>>
24.63 SSD_SCP# >>>



Layout Note:
Place near HDD1



SATA HDD Connector

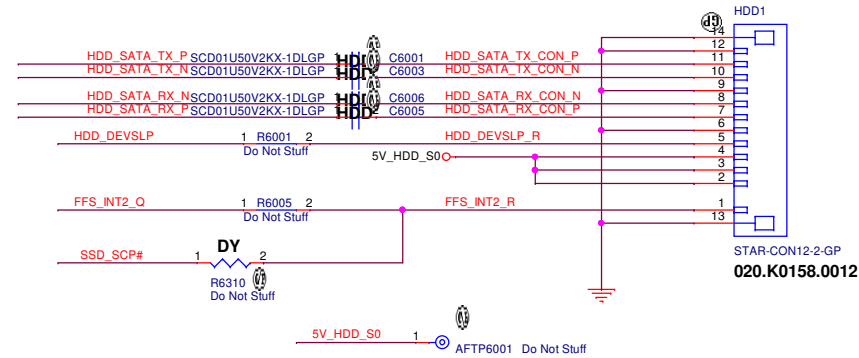


Table 16-5. SATA / PCI Express* Gen 2 and Gen 3 Capacitor Values

Condition	PCI Express* Gen 2 Only	PCI Express* Gen 3 Only	SATA Only	PCI Express* Gen 2/ SATA	PCI Express* Gen 3/ SATA
Processor Tx	100 nF	220 nF	10 nF	100 nF	220 nF
Processor Rx	None	None	10 nF ¹	None ²	None ³

Notes:

- This option supports all SATA devices. However, the Rx 10 nF capacitor can be removed if DC coupled ODDs / devices are NOT used.
- For PCIe* Gen 2/ SATA multiplexed configuration, motherboard Tx requires a 100 nF AC capacitor and NO AC capacitor is required for motherboard Rx channel. **This option DOES NOT support DC coupled ODDs / Devices.**
- For PCIe* Gen 3/ SATA multiplexed configuration, motherboard Tx requires a 220 nF AC capacitor and NO AC capacitor is required for motherboard Rx channel. **This option DOES NOT support DC coupled ODDs / Devices.**
- Design Constraint: For PCIe* lane that needs to support either PCIe* Gen2 devices or PCIe* Gen3 devices, follow the PCIe* Gen 3/ SATA multiplexed configuration, motherboard Tx requires a 220 nF AC capacitor and NO AC capacitor is required for motherboard Rx channel. **This option DOES NOT support DC coupled ODDs / Devices.**
- Use a non-interleaved breakout to isolate Tx and Rx.

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Title **SATA HDD**

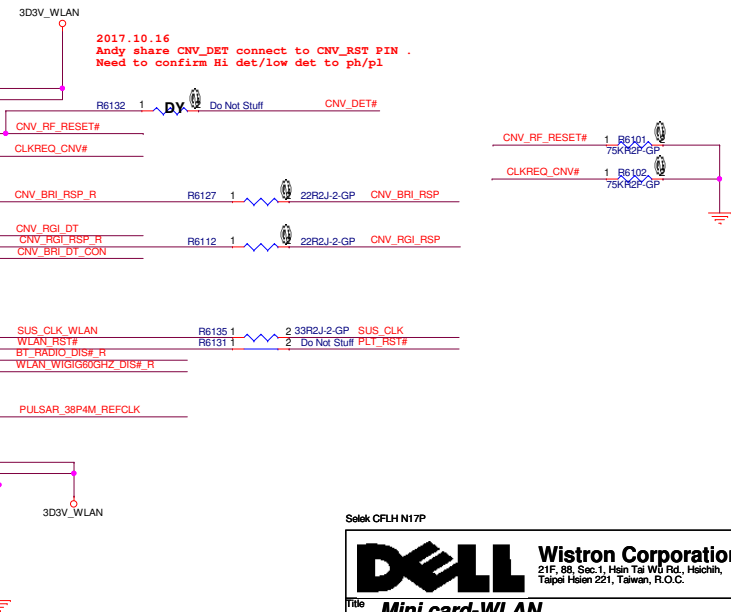
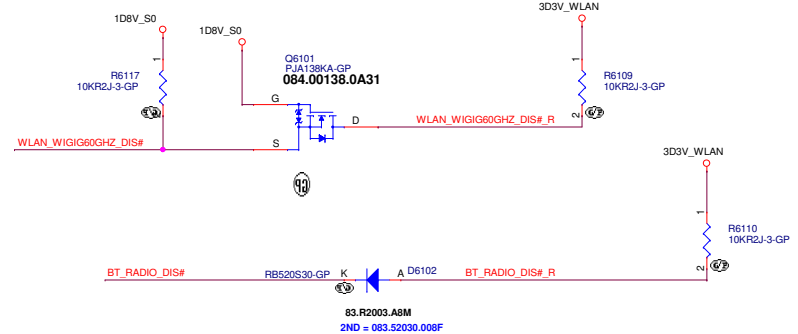
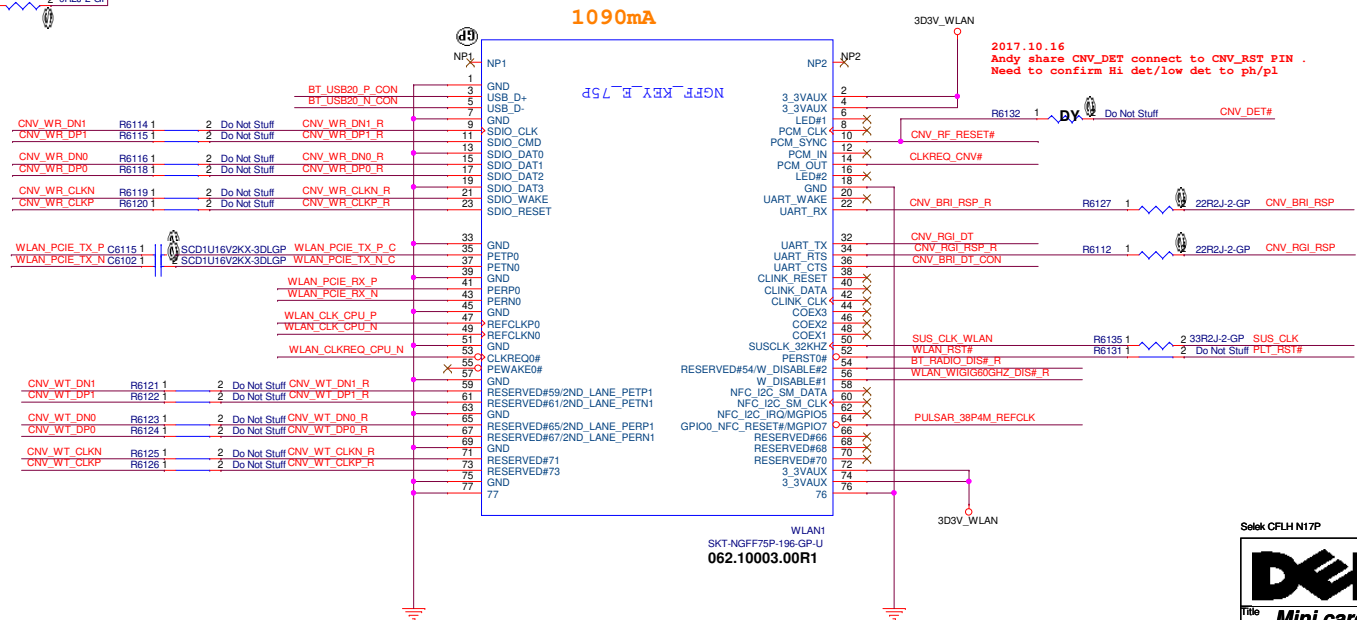
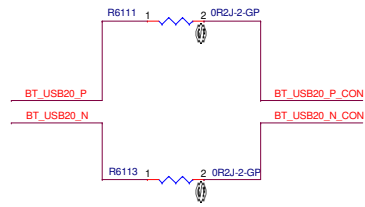
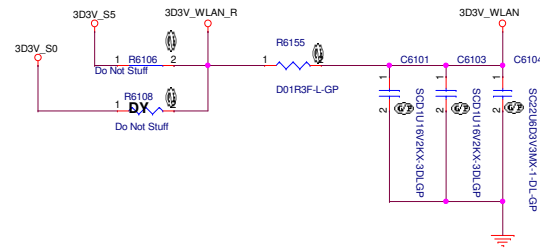
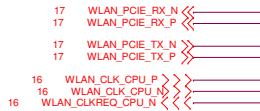
Size Custom Document Number **Selek CFL-H**

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Rev **A00**

Main Func = WLAN

**Selek CFLH N17P**

Title	Mini card-WLAN
-------	-----------------------

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SSID = Wireless

Selek CFLH N17P



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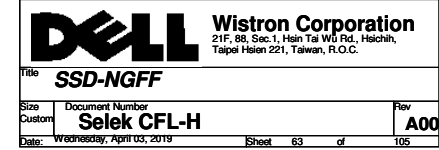
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title **(Reserved)WWAN**

Size A	Document Number Selek CFL-H	Rev A00
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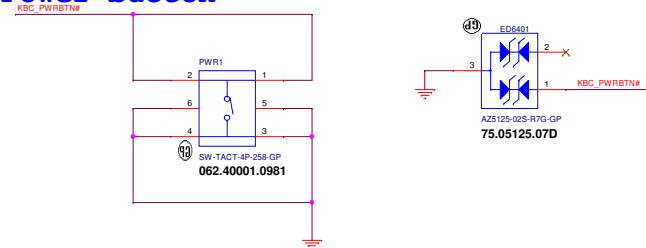
Mini Card Connector (NGFF m-SATA)



SSID = User.Interface

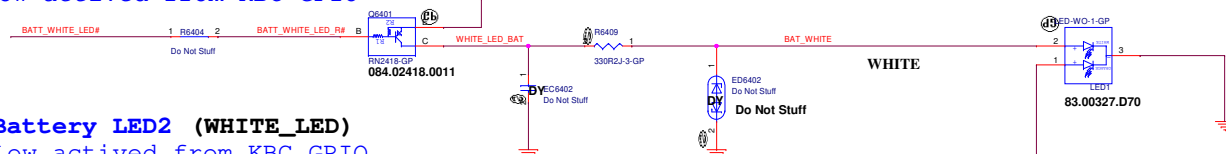
Power button

NONE FINGER PRINT 才會上件



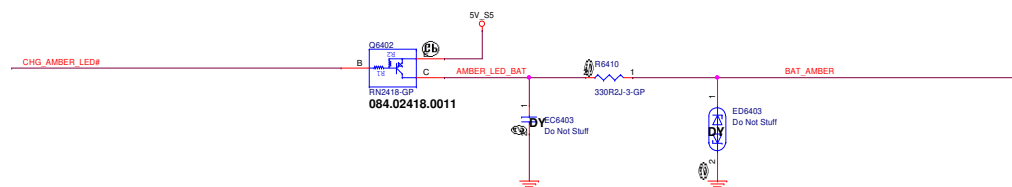
Battery LED1 (AMBER_LED)

Low activated from KBC GPIO

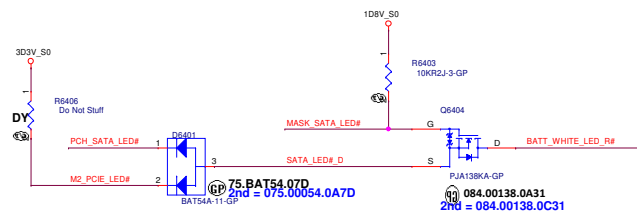


Battery LED2 (WHITE_LED)

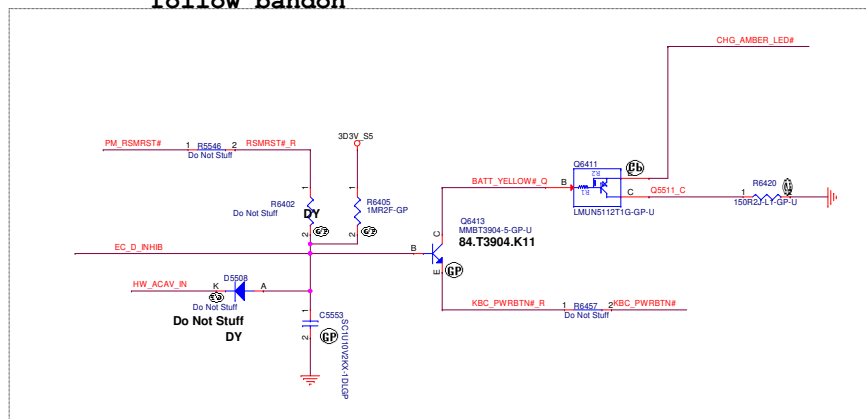
Low activated from KBC GPIO



SATA LED

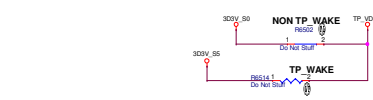
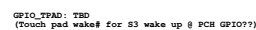


M-BIST for G10 (Proposed schematic) follow bandon

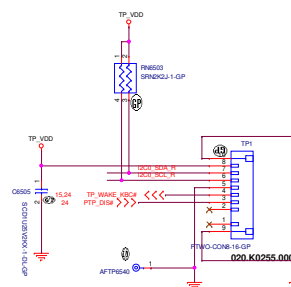
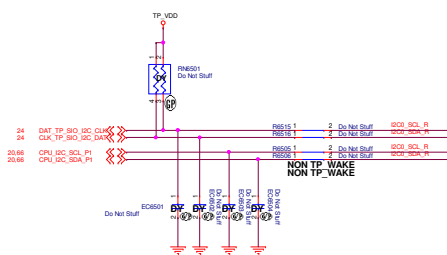


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Main Func = TPAD

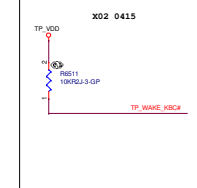


GPIO_TPAD: TBD
(Touch pad wake# for S3 wake up @ PCH GPIO??)



Change pindefine DWT1 0210 1330

Need to check if it is Active High or Active Low
~~and check if there is PH on TPAD side.~~



Pin number	Pin name
1	VDD
2	DAT (I2C)
3	CLK (I2C)
4	GND
5	ATTN
6	GPIO
7	DAT (PS2)
8	CLK (PS2)

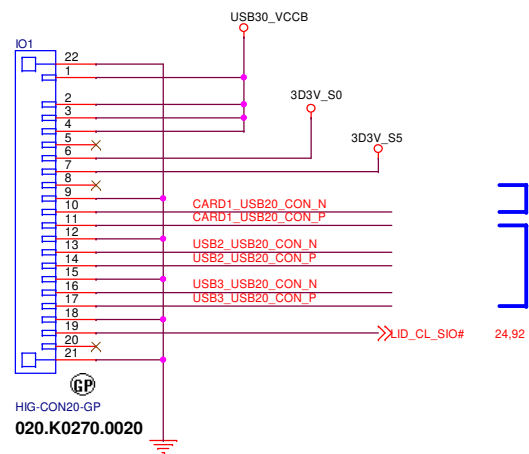


18 USB3_USB20_P
18 USB3_USB20_N
18 USB2_USB20_P
18 USB2_USB20_N

18 CARD1_USB20_N
18 CARD1_USB20_P

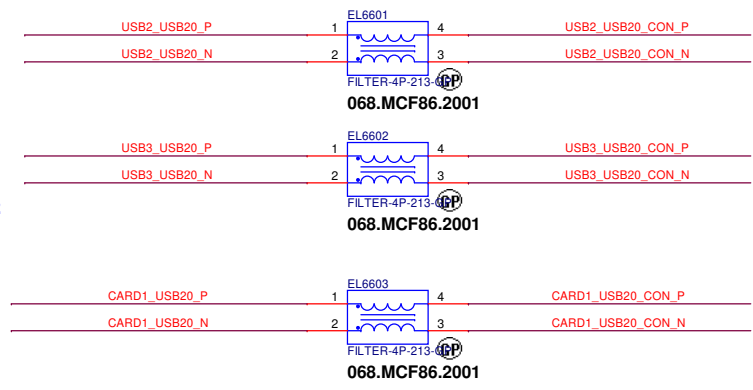
20.65 CPU_I2C_SCL_P1
20.65 CPU_I2C_SDA_P1

44 BT_PWR_IN-
44 BT_PWR_IN+

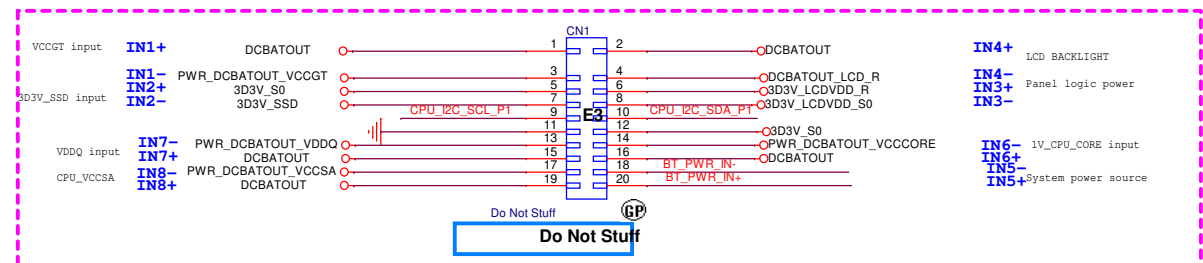


Cardreader

USB 2.0 Gen1 *2



E3 reserve



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IO Board Connector

Size
A3

Document Number
Selek CFL-H

Rev
A00

Date: Wednesday, April 03, 2019

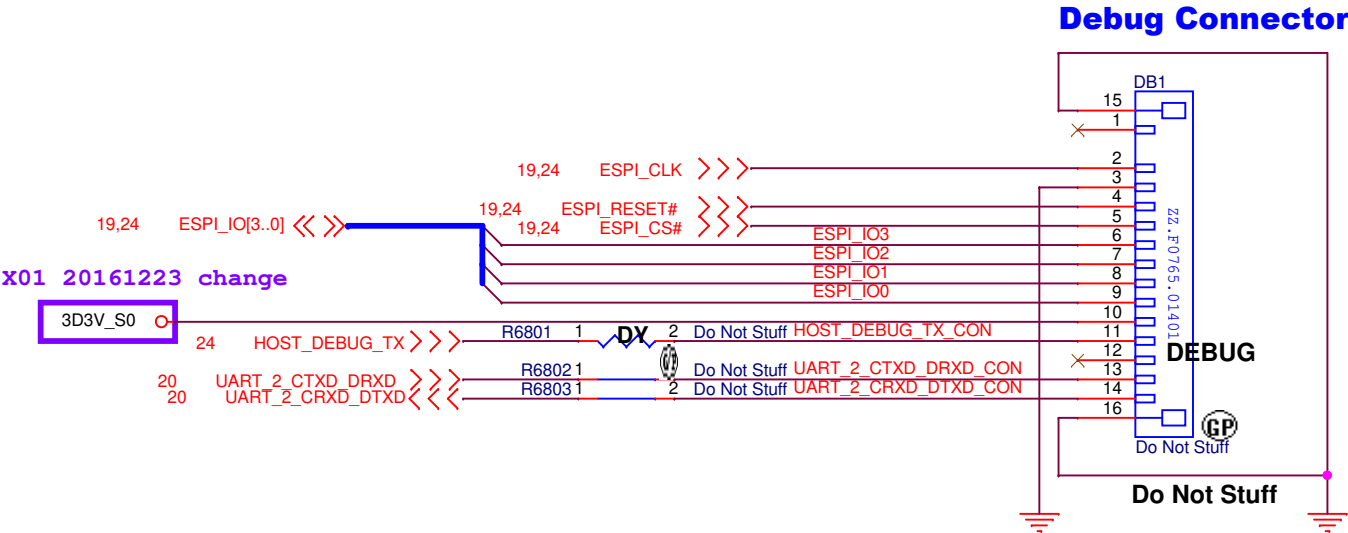
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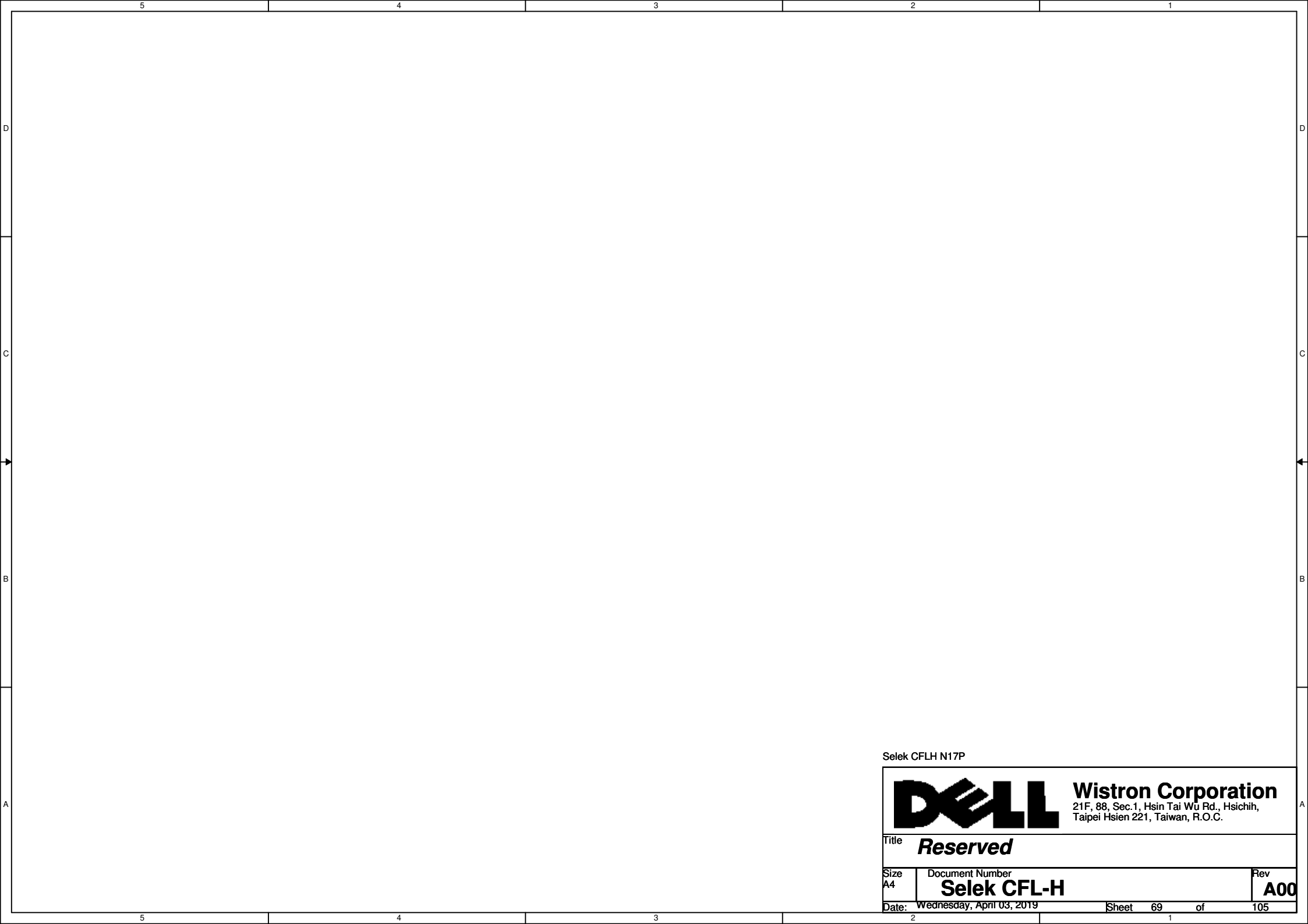
Main Func = Hall Sensor

Selek CFLH N17P

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title Hall Sensor			
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Main Func = Debug





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Title <i>Reserved</i>		
Size A4	Document Number Selek CFLH-H	Rev A00
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```

20      GSEN2_INT1_C  <<<=====
20      GSEN2_INT2_C  <<<=====

20  CPU_I2C_SDA_ISH  <<<=====
20  CPU_I2C_SCL_ISH  <<<=====

60      FFS_INT2_Q  <<<=====

```

The timing diagram shows three digital signals over time:

- GSEN2_INT1_C**: A blue signal that transitions from low to high at approximately 0.8 ns.
- GSEN2_INT2_C**: A red signal that transitions from low to high at approximately 1.6 ns.
- INT2_SELECT**: A purple signal that transitions from low to high at approximately 2.4 ns.

Each transition is annotated with a checkmark icon, a value of "2", and the text "Do Not Stuff". The signals are shown against a background grid with vertical lines every 0.4 ns and horizontal lines every 0.2 V.

From USB HOST



From CPU



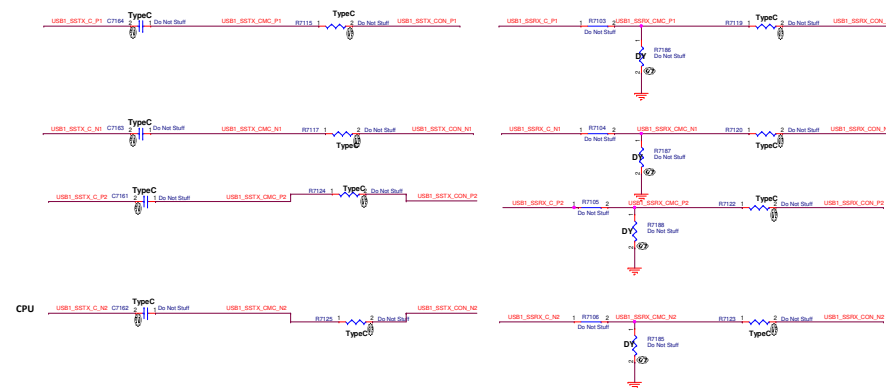
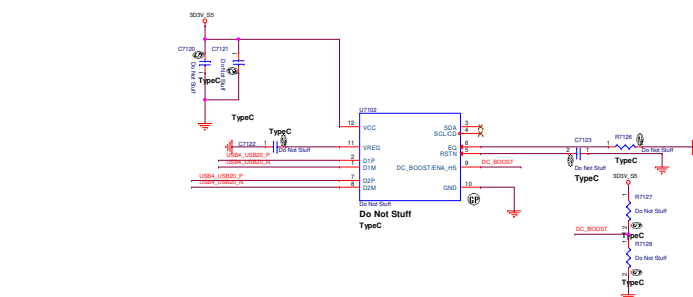
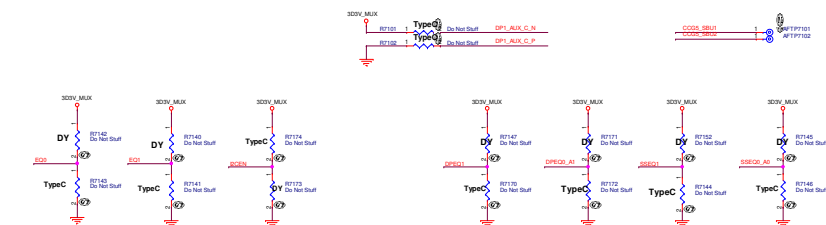
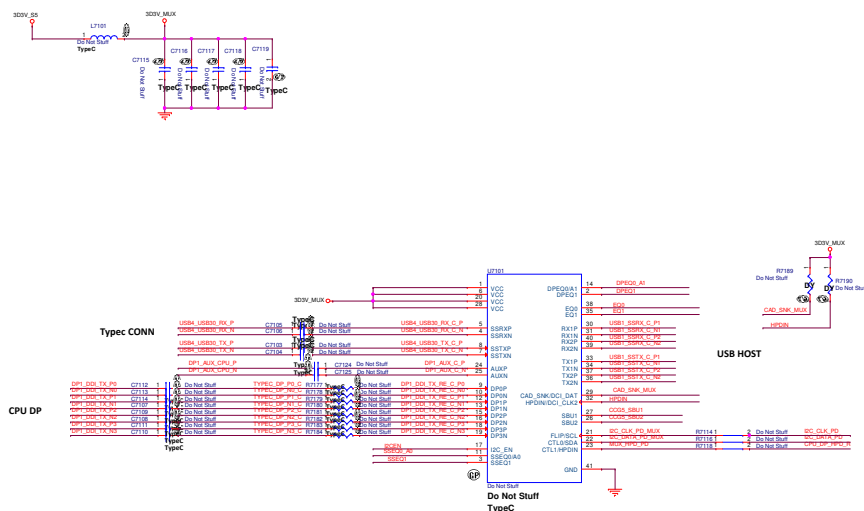
From CCG4



From CCG5 to MUX



To Type-C CONNECTOR



From 1

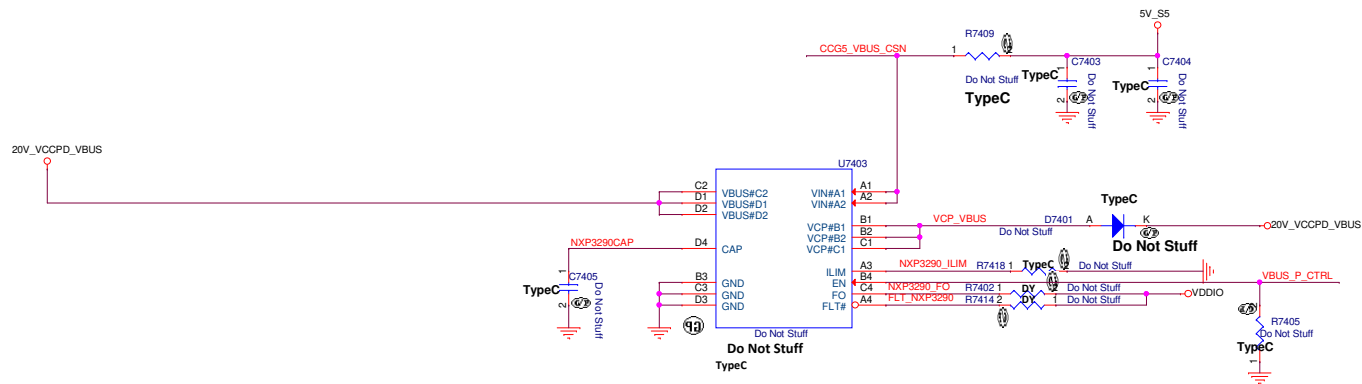


Main Func = LPS

72 VBUS_P_CTRL >>>

72 NXP3290_FO <<<

72 CCG5_VBUS_CSN <<<



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DELL Wistron Corporation 21F, 88, Sec.1, Hsin Tai W6 Rd., Hsichih, Taipai Hsien 221, Taiwan, R.O.C.		
File		
LPS		
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	5	4	3	2	1
D					D
C					C
B					B
A					A
	5	4	3	2	1

Selek CFLH N17P

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title <i>(Reserved)Thunderbolt (5/5)</i>			
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• PEX_HVDD and PEX_PLL_HVDD rails must be shared with 1V8_AON for GC6 2.1

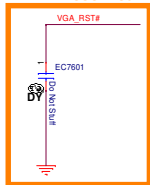
GPU	Capacitor Type	Footprint	N18	N17	Location
PEX_DVDD Supply Rail					
GB4C-128, GB4D-128	1.0 μ F	X65	0402 or 0201W	0	Under GPU
	0.47 μ F	X65	0201W	12	Under GPU
	4.7 μ F	X65	0603	0	Near GPU
	4.7 μ F	X65	0603	3	Under GPU
	10 μ F	X5R	0805	0	Midway between GPU and power supply
	10 μ F	X65	0805	3	Near GPU
	22 μ F	X5R	0805	0	Midway between GPU and power supply
	22 μ F	X65	0805	2	Near GPU

PEX_HVDD Supply Rail									
GB4C-128, GB4D-128	1.0 μ F	X65	0402 or 0201W	0	4	Under GPU			
	0.47 μ F	X65	0201W	13	0	Under GPU			
	4.7 μ F	X65	0603	0	2	Near GPU			
	4.7 μ F	X65	0603	3	0	Under GPU			
	10 μ F	X5R	0805	0	2	Midway between GPU and power supply			
	10 μ F	X65	0805	3	0	Near GPU			
	22 μ F	X5R	0805	0	1	Midway between GPU and power supply			
	22 μ F	X65	0805	2	0	Near GPU			

Note:

1. Design may alternatively use two 0201W 0.47 μ F X65 for each 0201W 1 μ F.

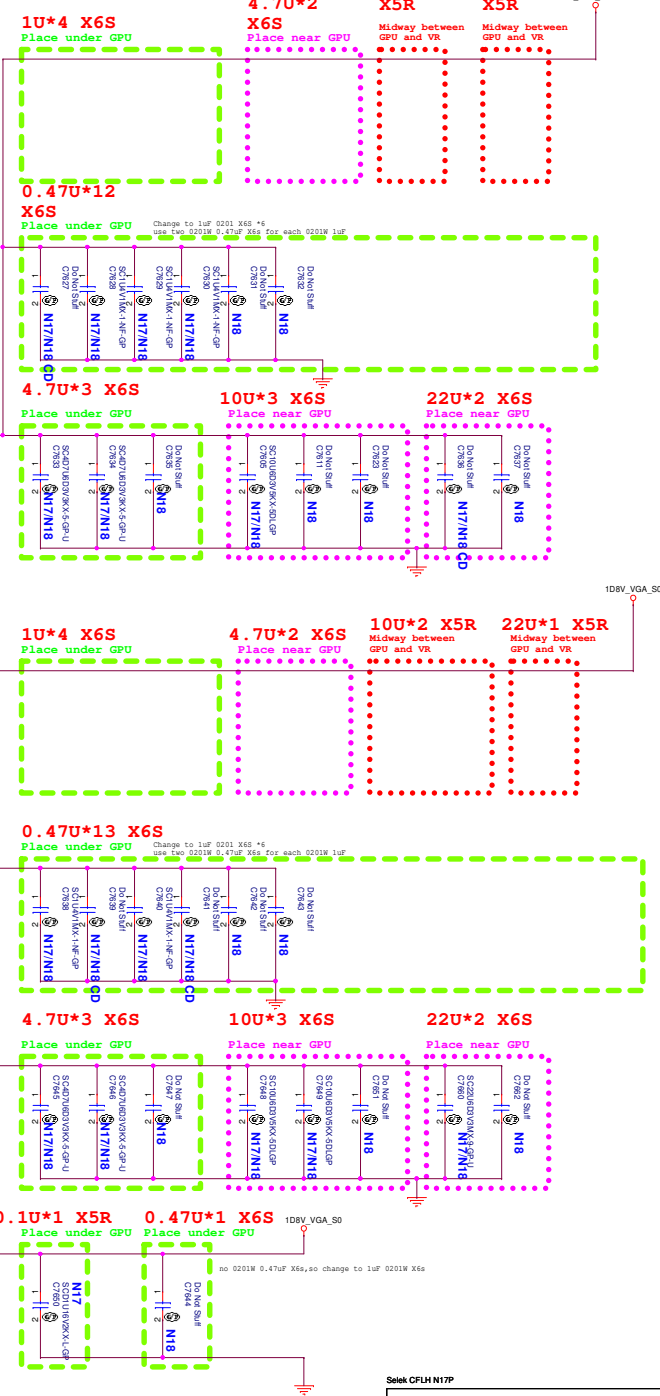
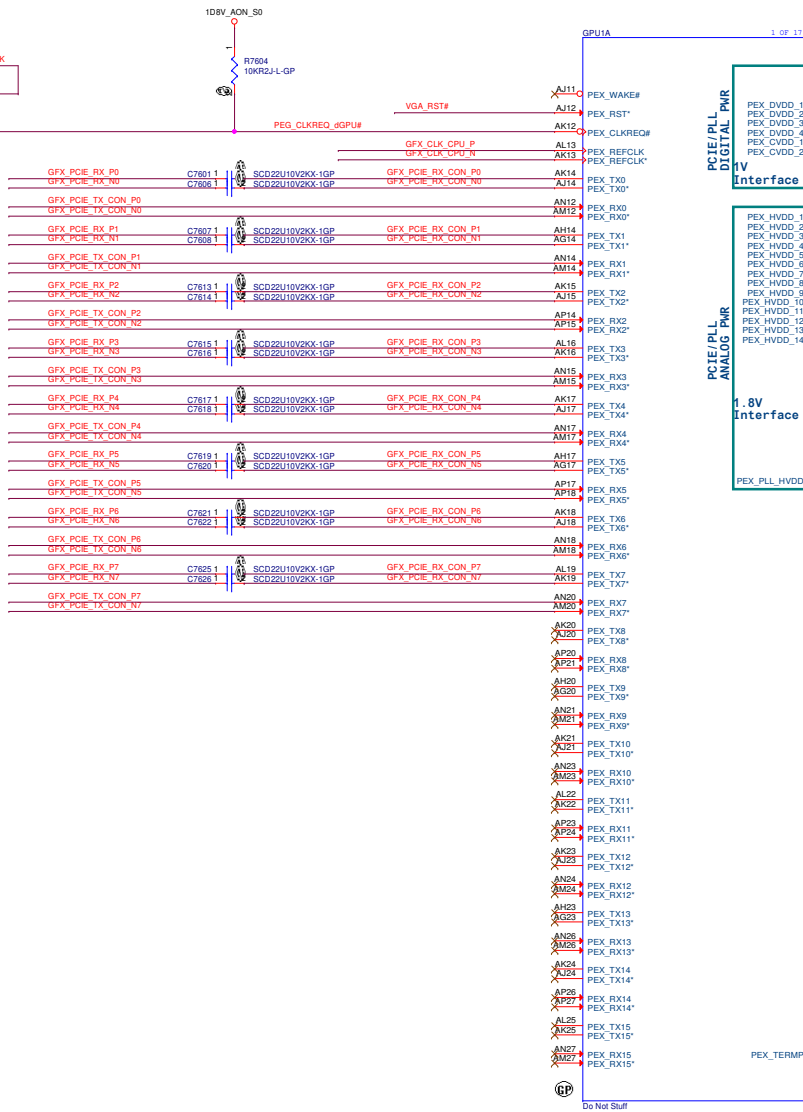
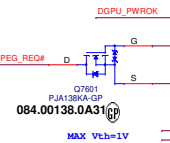
EMI Reserved



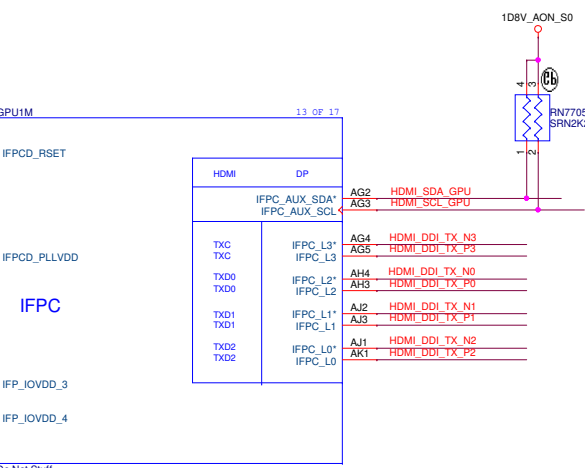
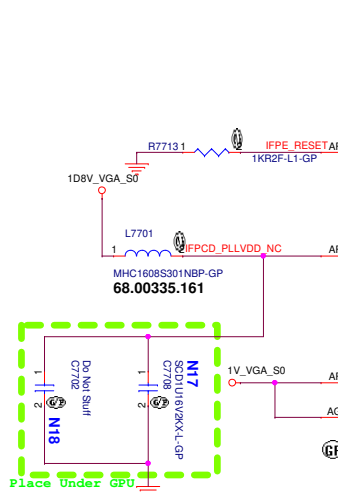
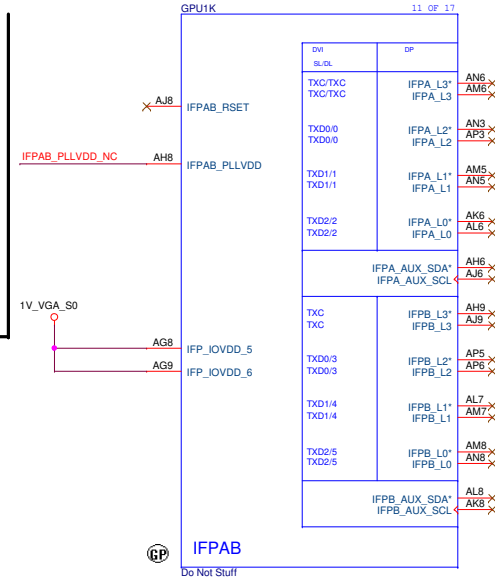
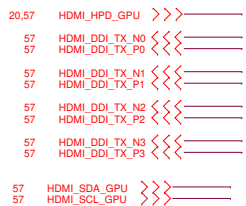
15,24,86 DGPU_PWROK
16 CLK_PCIE_PEG_REQ#
79 VGA_RST#

3 GFX_PCIE_RX_P7
3 GFX_PCIE_RX_N7
3 GFX_PCIE_RX_P8
3 GFX_PCIE_RX_N8
3 GFX_PCIE_RX_P9
3 GFX_PCIE_RX_N9
3 GFX_PCIE_RX_P10
3 GFX_PCIE_RX_N10
3 GFX_PCIE_RX_P11
3 GFX_PCIE_RX_N11
3 GFX_PCIE_RX_P12
3 GFX_PCIE_RX_N12
3 GFX_PCIE_RX_P13
3 GFX_PCIE_RX_N13
3 GFX_PCIE_RX_P14
3 GFX_PCIE_RX_N14
3 GFX_PCIE_RX_P15
3 GFX_PCIE_RX_N15
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3 GFX_PCIE_RX_P17
3 GFX_PCIE_RX_N17

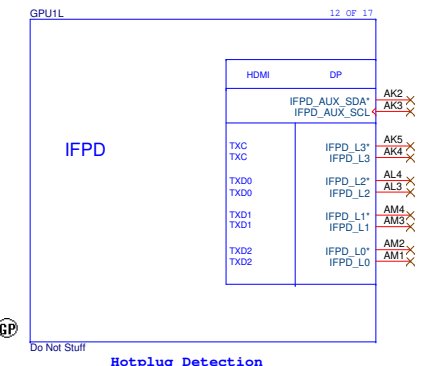
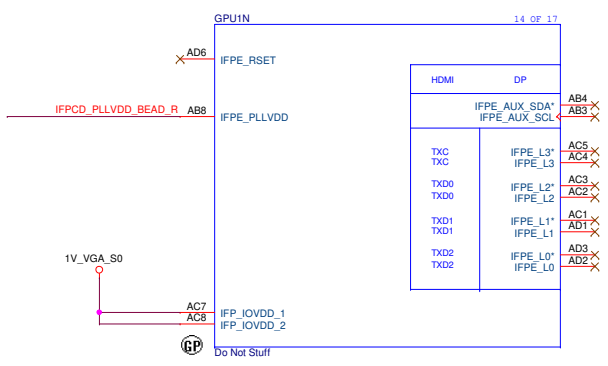
3 GFX_PCIE_TX_CON_P7
3 GFX_PCIE_TX_CON_N7
3 GFX_PCIE_TX_CON_P8
3 GFX_PCIE_TX_CON_N8
3 GFX_PCIE_TX_CON_P9
3 GFX_PCIE_TX_CON_N9
3 GFX_PCIE_TX_CON_P10
3 GFX_PCIE_TX_CON_N10
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3 GFX_PCIE_TX_CON_N11
3 GFX_PCIE_TX_CON_P12
3 GFX_PCIE_TX_CON_N12
3 GFX_PCIE_TX_CON_P13
3 GFX_PCIE_TX_CON_N13
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3 GFX_PCIE_TX_CON_N14
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3 GFX_PCIE_TX_CON_P16
3 GFX_PCIE_TX_CON_N16
3 GFX_PCIE_TX_CON_P17
3 GFX_PCIE_TX_CON_N17



Selek CFLM N17P



follow CRB



Hotplug Detection

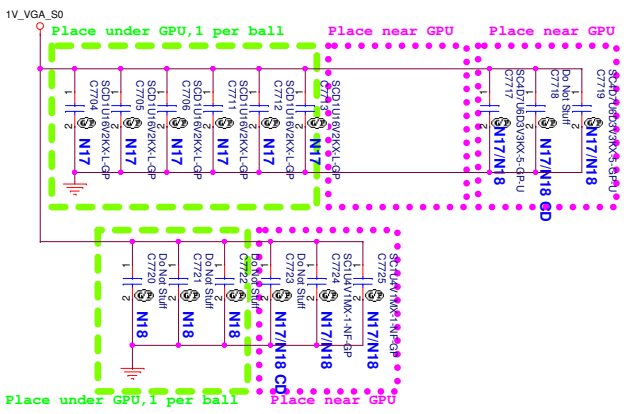
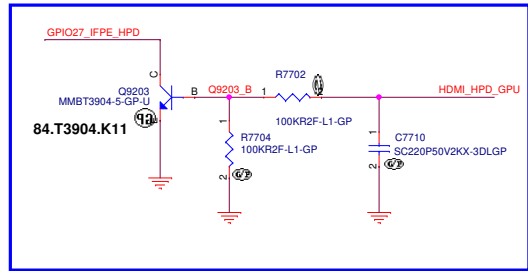


Table 7. IFPy_JOVDD Decoupling and Filtering

GPU	Type	Footprint	Population	N18	N17	Location
IFPy_JOVDD Supply Rails						
GB4C-128, GB4D-128	0.1 μ F	X78	0402	0	6	Under GPU; 1 per ball
	0.47 μ F	X65	0201W	0	0	Under GPU; 1 per ball
	1.0 μ F	X65	0402	0	3	Near GPU
	0.47 μ F	X65	0201W	6	0	Near GPU
	4.7 μ F	X65	0603	3	3	Near GPU
Bead Type						
180 Ω @ 100 MHz (ESR=0.2 Ω)			0603	0	0	Near GPU

Note:
 1. Design may alternatively use one 0201W 0.47 μ F X65 for each 0201W 1 μ F.
 2. Design may alternatively use two 0201W 0.47 μ F X65 for each 0201W 1 μ F.



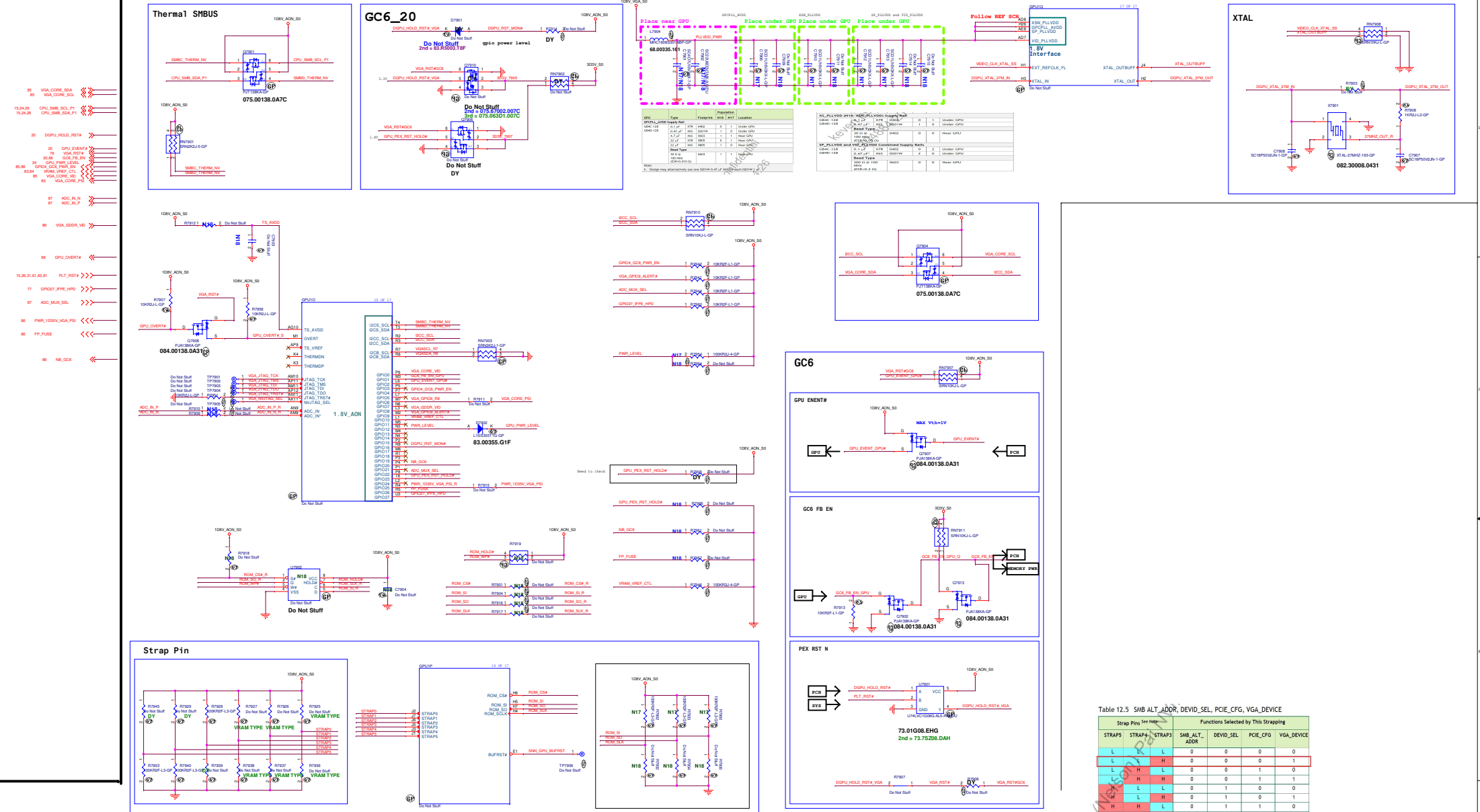
Selek CFL N17P



Title: GPU_DIGITALOUT (2/5)

Size: Custom
 Document Number: Selek CFL-H
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Change to 1uF 0201 X65 *3 from 0201 X650.47u*6
 use two 0201W 0.47uF X65 for each 0201W 1uF



Strap2	Strap1	Strap0	Vendor	Vendor number	wistron P/N	Strap	GPU
L	L	L	Samsung	K4G80325FB-HC28	N1MMHSA	0x0	N17P
L	L	H	Micron	MT51J256M32HF-80-B	MHVDXSAA	0x1	N18P
L	H	L	Hynix	H5GCS824AJR-R2C	GVK6KSA	0x2	N18P
L	L	L	Samsung	K4G80325FC-HC25	J62CNSAA	0x0	N18P

Table 3. N17P-G1/G0-K1 GDDR5 Recommended Memories									
Memory Density	Allowed Memory Configuration	Manufacturer	Part Number	Die Revision	Strap	Memory Speed Grade	Date Code	Alert	Status
8 Gb	256Mb/32	Samsung	K4G80325FB-HC28	B-die	0x0	8 Gbps	N/A	Full	Production ready
		Micron	MT51J256M32HF-80-B	A-die	0x1	8 Gbps	N/A	Full	Production ready
		Micron	MT51J256M32HF-80-B	A-die	0x2	8 Gbps	N/A	Full	Production ready
		Hynix	H5GCS824AJR-R2C	A-die	0x2	8 Gbps	N/A	Full	Production ready
		Micron	MT51J256M32HF-80-B	A-die	0x0	8 Gbps	N/A	Full	Production ready
		Micron	MT51J256M32HF-80-B	A-die	0x1	8 Gbps	N/A	Full	Production ready
	1.35V and 1.55V	Samsung	K4G80325FC-HC25	D-die	0x0	8 Gbps	N/A	Full	Production ready
		Micron	MT51J256M32HF-80-B	A-die	0x1	8 Gbps	N/A	Full	Production ready
		Micron	MT51J256M32HF-80-B	A-die	0x2	8 Gbps	N/A	Full	Production ready
		Hynix	H5GCS824AJR-R2C	A-die	0x2	8 Gbps	N/A	Full	Production ready
		Micron	MT51J256M32HF-80-B	A-die	0x0	8 Gbps	N/A	Full	Production ready
		Micron	MT51J256M32HF-80-B	A-die	0x1	8 Gbps	N/A	Full	Production ready

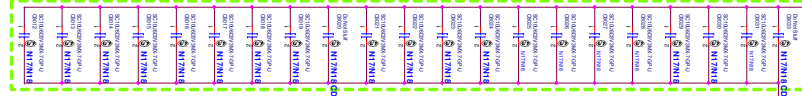
Table 4. N18P-G0 GDDR5 Recommended Memories									
Memory Density	Allowed Memory Configuration	FBVDD/Q	Vendor	Manufacturer Part Number	Die Revision	Strap	Memory Speed Grade	Date Code	Status
8 Gb	256Mb/32	1.35V and 1.55V	Micron	MT51J256M32HF-80-B	B-die	0x1	8 Gbps	N/A	Production candidate
		1.35V	Hynix	H5GCS824AJR-R2C	A-die	0x2	8 Gbps	N/A	Production candidate
		1.35V and 1.55V	Samsung	K4G80325FC-HC25	C-die	0x0	8 Gbps	N/A	Production candidate

Table 5. N18P-G0 GDDR5 Recommended Memories									
Strap2	Strap1	Strap0	Vendor	Manufacturer Part Number	Die Revision	Strap	Memory Speed Grade	Date Code	Status
L	L	L	Samsung	K4G80325FB-HC28	B-die	0x0	8 Gbps	N/A	Production candidate
L	L	H	Micron	MT51J256M32HF-80-B	A-die	0x1	8 Gbps	N/A	Production candidate
L	H	L	Hynix	H5GCS824AJR-R2C	A-die	0x2	8 Gbps	N/A	Production candidate
L	L	L	Samsung	K4G80325FC-HC25	C-die	0x0	8 Gbps	N/A	Production candidate

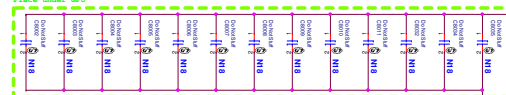
Table 12.5 SMB ALT_ADOR, DEVID_SEL, PCIE_CFG, VGA_DEVICE				
Strap Pins	See Note	Functions Selected by This Strapping	SMB_ALT_ADOR	DEVID_SEL
STRAP2	STRAP1	STRAP0	SMB_ALT_ADOR	DEVID_SEL
L	L	L	0	0
L	L	H	0	0
L	H	L	0	1
L	H	H	0	1
H	L	L	1	0
H	L	H	1	0
H	H	L	1	1
H	H	H	1	1
L	L	L	1	0
L	L	H	1	0
L	H	L	1	0
L	H	H	1	0

Wistron Corporation
CPU, GPU, RAM, Storage, Power Supply, Keyboard, Mouse, Monitor, etc.
GPU_GPIO/STRAP
CPU: Intel Core i7-7700K
GPU: NVIDIA GeForce GTX 1080
RAM: 16GB DDR4
Storage: 1TB SSD
Power Supply: 650W
Keyboard: Backlit
Mouse: Wireless
Monitor: 27" 4K
OS: Windows 10
Date: 2017-12-21
Model: 27-7700K
Page: 1 of 1

10U*21
Place under GPU



10U*13
Place under GPU



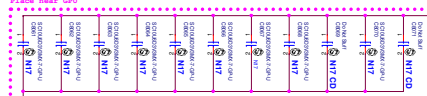
1U*13
Place under GPU



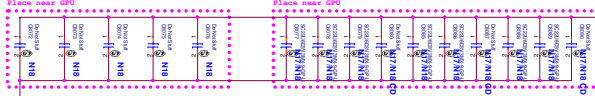
0.47U*26
Place under GPU



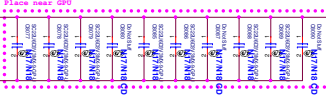
10U*11
Place near GPU



22U*5
Place near GPU



22U*10
Place near GPU



330U*1 4.7U*2
Place near GPU



Table 2. NVVDD Decoupling and Filtering

GPU	Capacitor Type		Footprint	Population		Location
	Supply Net	Qty		N18	N17	
NVVDD GB4C-128 GB4D-128	10 μ F	X65	0603	34	21	Under GPU
	1 μ F ¹	X65	0402 or 0201W	0	13	Under GPU
	0.47 μ F ¹	X65	0402 or 0201W	26	0	Under GPU
	10 μ F	X65	0603	0	11	Near GPU
	22 μ F	X65	0805	15	10	Near GPU
	4.7 μ F	X65	0603	0	2	Near GPU
	330 μ F	POS	7343	1	1	Near GPU

Note:

1. Design may alternatively use two 0201W 0.47 μ F X65 for each 0201W 1 μ F.

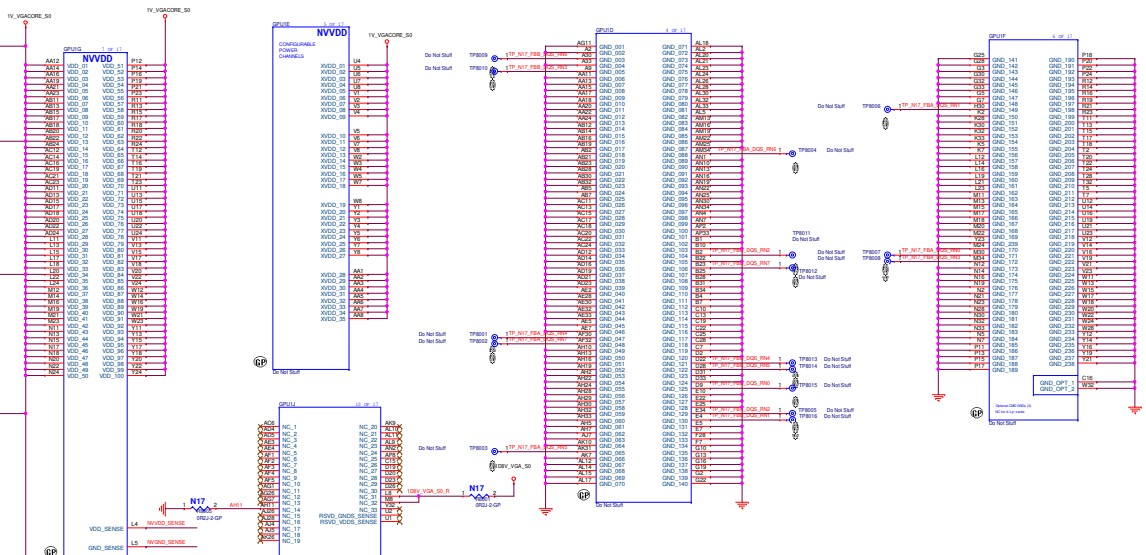


Table 9. VDD_AON and VDD_MAIN Decoupling

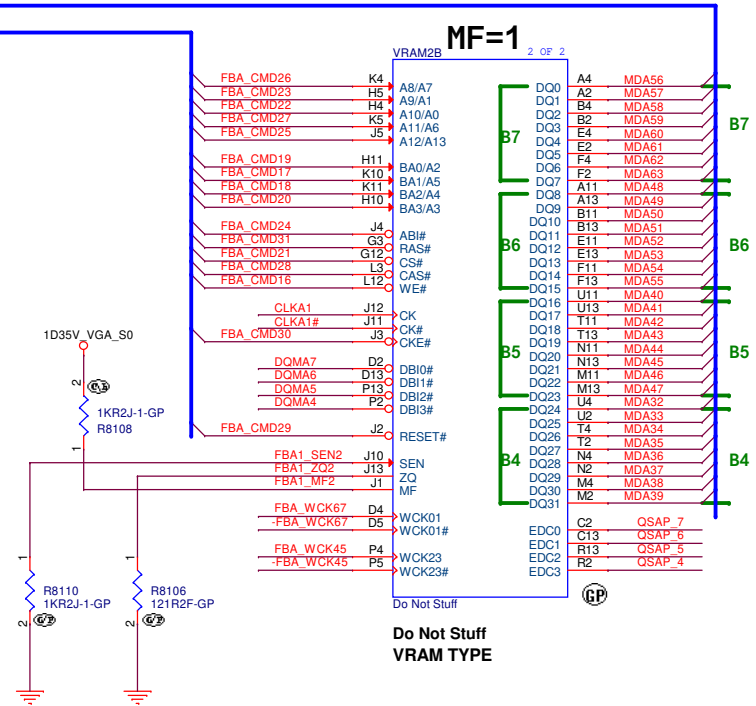
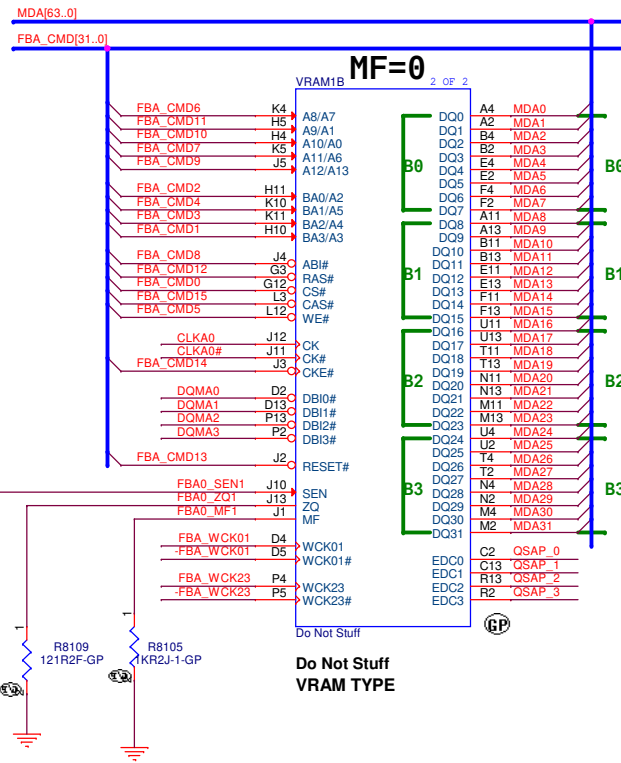
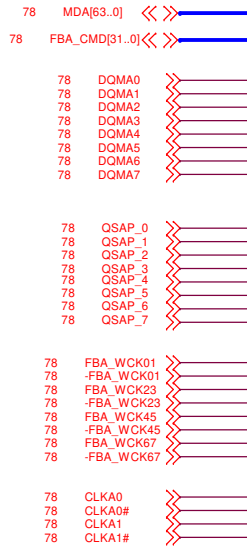
GPU	Capacitor Type	Footprint	Population		Location
			N18	N17	
N17 VDD18 (N18 NC) Supply Rail					
GB4C-128, GB4D-128	0.1 μ F	X78	0402	N/A	2
	1.0 μ F	X65	0603	N/A	1
	4.7 μ F	X65	0603	N/A	1
1V8_AON Supply Rail					
GB4C-128, GB4D-128	0.1 μ F	X78	0402	0	2
	0.47 μ F	X65	0201W	4	0
	1.0 μ F	X65	0402 or 0201W	0	1
	0.47 μ F	X65	0201W	6	0
	4.7 μ F	X65	0603	3	1

Note:

1. Design may alternatively use two 0201W 0.47 μ F X65 for each 0201W 1 μ F.

Note:

1. Design may alternatively use two 0201W 0.47 μ F X65 for each 0201W 1 μ F.



GDDR5 Data Mapping							
BYTE0 (BYTE4)		BYTE1 (BYTE5)		BYTE2 (BYTE6)		BYTE3 (BYTE7)	
MF=0	MF=1	MF=0	MF=1	MF=0	MF=1	MF=0	MF=1
DQ0	DQ24 (DQ32)	DQ8	DQ16 (DQ40)	DQ16	DQ8 (DQ48)	DQ24	DQ0 (DQ56)
DQ1	DQ25 (DQ33)	DQ9	DQ17 (DQ41)	DQ17	DQ9 (DQ49)	DQ25	DQ1 (DQ57)
DQ2	DQ26 (DQ34)	DQ10	DQ18 (DQ42)	DQ18	DQ10 (DQ50)	DQ26	DQ2 (DQ58)
DQ3	DQ27 (DQ35)	DQ11	DQ19 (DQ43)	DQ19	DQ11 (DQ51)	DQ27	DQ3 (DQ59)
DQ4	DQ28 (DQ36)	DQ12	DQ20 (DQ44)	DQ20	DQ12 (DQ52)	DQ28	DQ4 (DQ60)
DQ5	DQ29 (DQ37)	DQ13	DQ21 (DQ45)	DQ21	DQ13 (DQ53)	DQ29	DQ5 (DQ61)
DQ6	DQ30 (DQ38)	DQ14	DQ22 (DQ46)	DQ22	DQ14 (DQ54)	DQ30	DQ6 (DQ62)
DQ7	DQ31 (DQ39)	DQ15	DQ23 (DQ47)	DQ23	DQ15 (DQ55)	DQ31	DQ7 (DQ63)
DBI0	DBI3 (DB4)	DBI1	DBI2 (DB5)	DBI2	DBI1 (DB6)	DBI3	DBI0 (DB7)
EDC0	EDC3 (EDC4)	EDC1	EDC2 (EDC5)	EDC2	EDC1 (EDC6)	EDC3	EDC0 (EDC7)
GDDR5 CLK Mapping							
WCK01	WCK23 (WCK45)			WCK23	WCK01 (WCK67)		
WCK01#	WCK23# (WCK45#)			WCK23#	WCK01# (WCK67#)		
CK	CK						
CK#	CK#						
Others							
MF	MF	SEN	SEN				
ZQ	ZQ	RESET#	RESET#				

Table 9.4 GDDR5 Command Mapping (GB4C-128 packages)

Command Ball on GPU		DRAM Signal Definition
For DRAM(s) tied to DQ[31:0]	For DRAM(s) tied to DQ[63:32]	
FBA_CMD0	FBA_CMD16	CS*
FBA_CMD1	FBA_CMD17	A3_BA3
FBA_CMD2	FBA_CMD18	A2_BA0
FBA_CMD3	FBA_CMD19	A4_BA2
FBA_CMD4	FBA_CMD20	A5_BA1
FBA_CMD5	FBA_CMD21	WE*
FBA_CMD6	FBA_CMD22	A7_A8
FBA_CMD7	FBA_CMD23	A6_A11
FBA_CMD8	FBA_CMD24	ABI*
FBA_CMD9	FBA_CMD25	A12_RFU
FBA_CMD10	FBA_CMD26	A0_A10
FBA_CMD11	FBA_CMD27	A1_A9
FBA_CMD12	FBA_CMD28	RAS*
FBA_CMD13	FBA_CMD29	RST*
FBA_CMD14	FBA_CMD30	CKE*
FBA_CMD15	FBA_CMD31	CAS*

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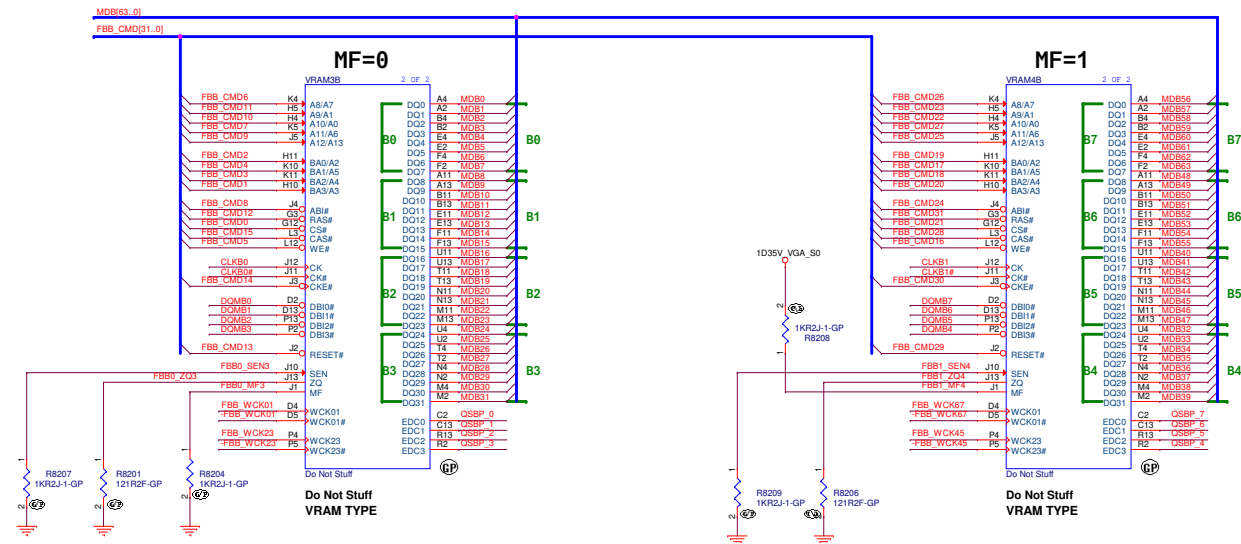
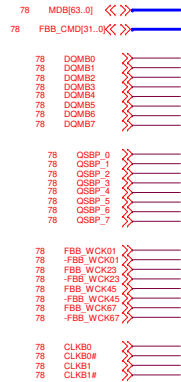


Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title **VRAM 1,2 (1/4)**

Size Custom Document Number **Selek CFL-H** Rev **A00**

Date: Wednesday, April 03, 2019 Sheet 81 of 105

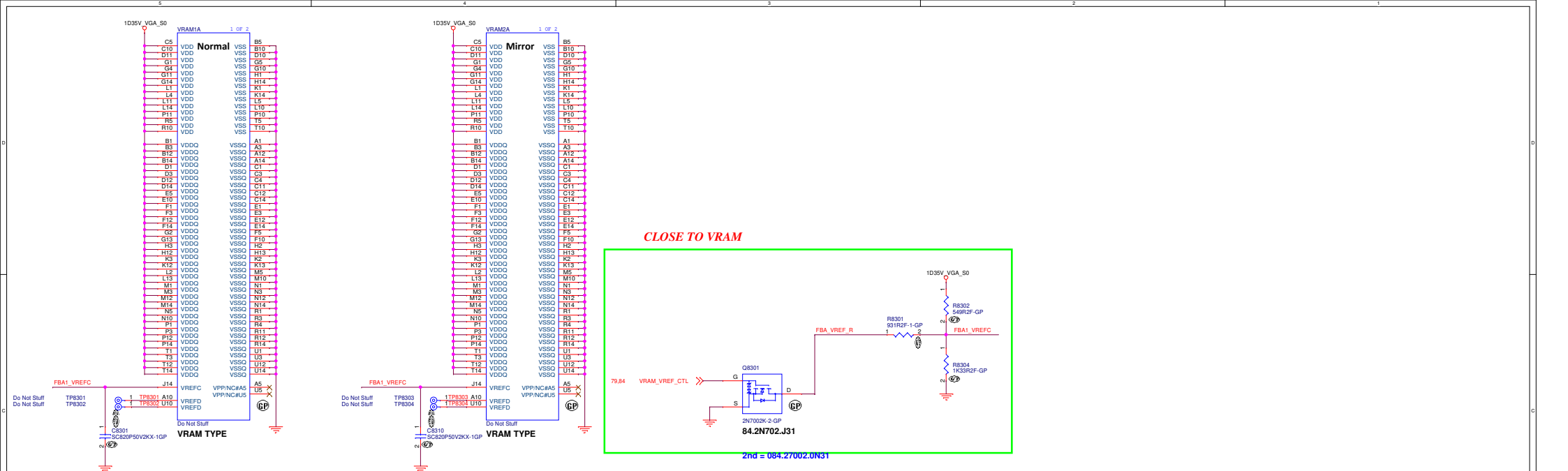


GDDR5 Data Mapping									
BYTE0 (BYTEA)		BYTE1 (BYTEB)		BYTE2 (BYTEC)		BYTE3 (BYTER)			
MF=0	MF=1	MF=0	MF=1	MF=0	MF=1	MF=0	MF=1		
DQ0	DQ24 (DQ02)	DQ8	DQ16 (DQ04)	DQ16	DQ8 (DQ04)	DQ24	DQ0 (DQ06)		
DQ1	DQ25 (DQ03)	DQ9	DQ17 (DQ01)	DQ17	DQ9 (DQ01)	DQ25	DQ1 (DQ07)		
DQ2	DQ26 (DQ04)	DQ10	DQ18 (DQ02)	DQ18	DQ10 (DQ02)	DQ26	DQ2 (DQ08)		
DQ3	DQ27 (DQ05)	DQ11	DQ19 (DQ03)	DQ19	DQ11 (DQ03)	DQ27	DQ3 (DQ09)		
DQ4	DQ28 (DQ06)	DQ12	DQ20 (DQ04)	DQ20	DQ12 (DQ04)	DQ28	DQ4 (DQ10)		
DQ5	DQ29 (DQ07)	DQ13	DQ21 (DQ05)	DQ21	DQ13 (DQ05)	DQ29	DQ5 (DQ11)		
DQ6	DQ30 (DQ08)	DQ14	DQ22 (DQ06)	DQ22	DQ14 (DQ06)	DQ30	DQ6 (DQ12)		
DQ7	DQ31 (DQ09)	DQ15	DQ23 (DQ07)	DQ23	DQ15 (DQ07)	DQ31	DQ7 (DQ13)		
DBI0	DBI3 (DB0)	DBI1	DBI2 (DB5)	DBI2	DBI1 (DB5)	DBI3	DBI0 (DB7)		
EDC0	EDC3 (EDC4)	EDC1	EDC2 (EDC5)	EDC2	EDC1 (EDC5)	EDC3	EDC0 (EDC7)		
GDDR5 CLK Mapping									
WCK01	WCK23 (WCK45)	WCK23 WCK01 (WCK67)							
WCK01#	WCK23# (WCK45#)	WCK23# WCK01# (WCK67#)							
CK	CK								
CK#	CK#								
Others									
MF	MF	SEN	SEN						
ZQ	ZQ	RESET#	RESET#						

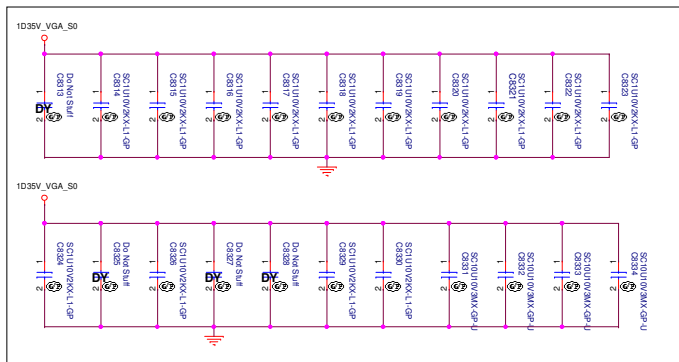
Table 9.4 GDDR5 Command Mapping (GB4C-128 packages)

Command Ball on GPU		DRAM Signal Definition
For DRAM(s) tied to DQ[31:0]	For DRAM(s) tied to DQ[63:32]	
FBA_CMD0	FBA_CMD16	CS*
FBA_CMD1	FBA_CMD17	A3_BA3
FBA_CMD2	FBA_CMD18	A2_BA0
FBA_CMD3	FBA_CMD19	A4_BA2
FBA_CMD4	FBA_CMD20	A5_BA1
FBA_CMD5	FBA_CMD21	WE*
FBA_CMD6	FBA_CMD22	A7_A8
FBA_CMD7	FBA_CMD23	A6_A11
FBA_CMD8	FBA_CMD24	AB1*
FBA_CMD9	FBA_CMD25	A12_RFU
FBA_CMD10	FBA_CMD26	A0_A10
FBA_CMD11	FBA_CMD27	A1_A9
FBA_CMD12	FBA_CMD28	RAS*
FBA_CMD13	FBA_CMD29	RST*
FBA_CMD14	FBA_CMD30	CKE*
FBA_CMD15	FBA_CMD31	CAS*

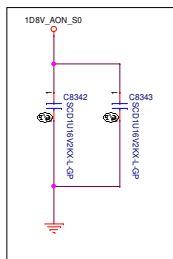
Selek CFLH N17P



FOR VRAM1/ VRAM2

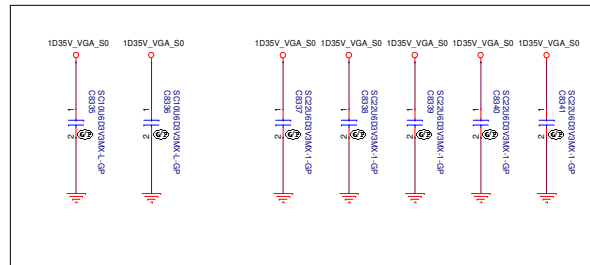


UNDER THE MEMORY



UNDER THE MEMORY

FOR VRAM1/ VRAM2



CLOSE TO THE MEMORY

Selek CFLH N17P

DELL Wistron Corporation
21F, 88, Sec.1, Main Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title **VGA Power A**

Size A0 Document Number **Selek CFLH** Rev **A00**
Date: 06/03/2007, April 2010 Sheet 00 of 100

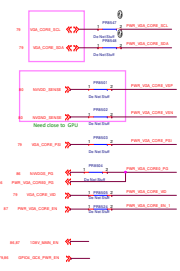


Table 7.8 PWM-VID Spec and Component Values

PWM-VID Specification		Unit	Config
Number of Voltage Levels N	level	160	
PWM Frequency F_pwm	MHz	475	
PWM Minimum Pulse Width T_pwm_min	ns	1.5	
VID Transient Time T	us	1000	
Component Value			
R1 (1S)	MO	6.19	
R2 (1S)	MO	20.5	
R3 (1S)	MO	4.32	
R4 (1S)	MO	16.5	
R5 (1S)	MO	8.0	
C	uF	0.001	

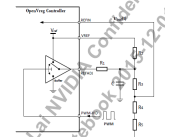
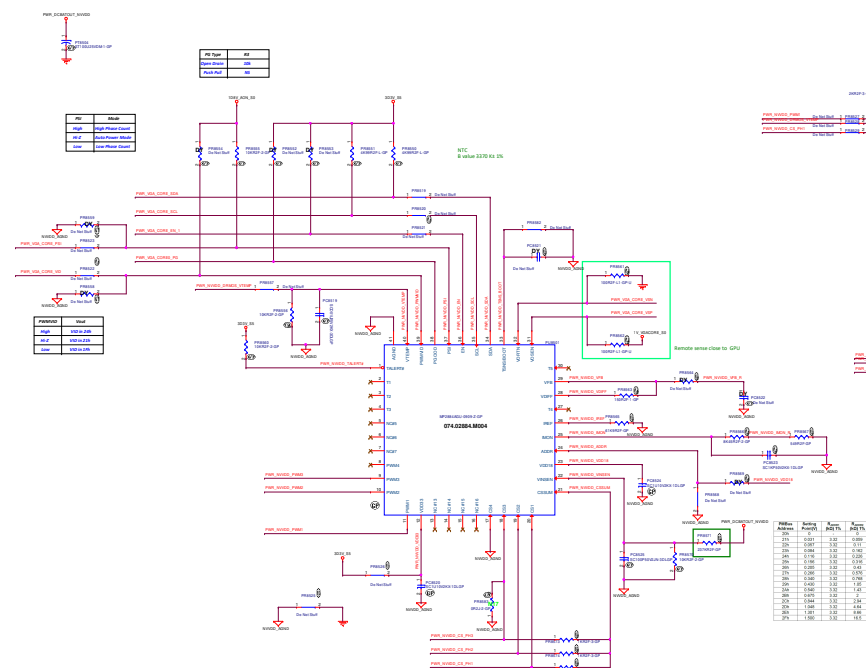
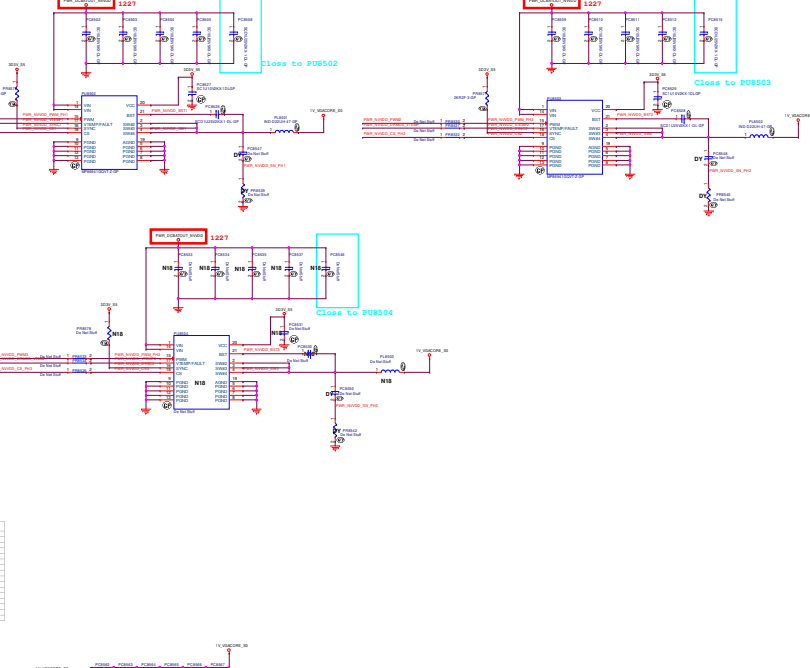


Table 7.9 PWM-VID Spec and Component Values

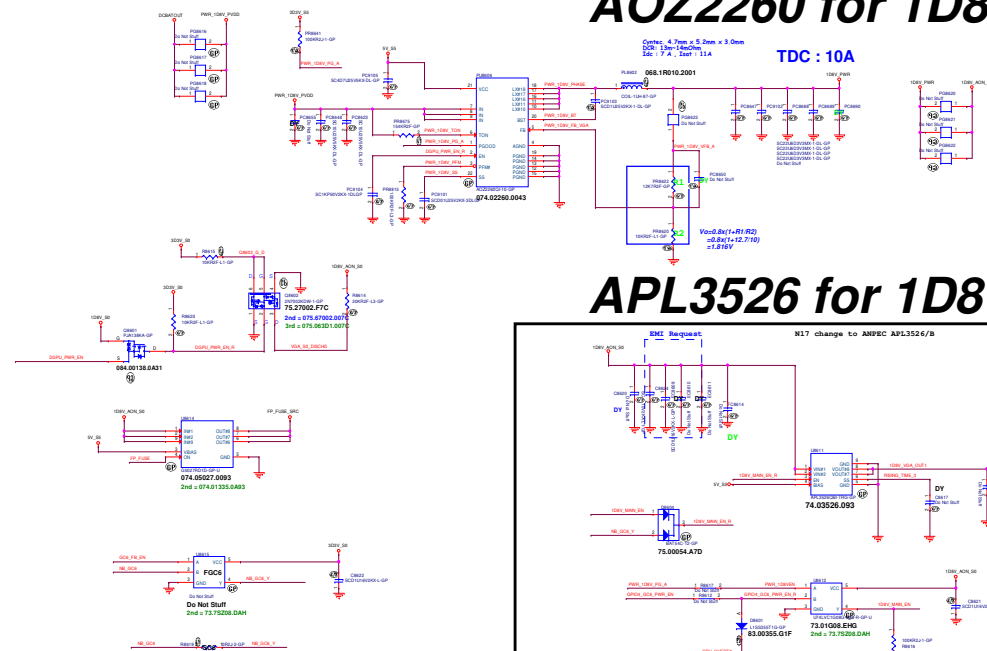
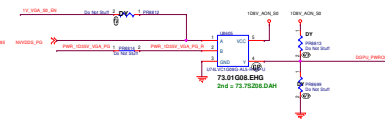
PWM-VID Specification		Unit	Config
Vmin	V	0.3	
Vmax	V	1.3	
Vboot	V	0.8	
Voltage Step Width	mV	6.25	
Number of Voltage Levels N	level	160	
PWM Frequency F_pwm	MHz	475	
PWM Minimum Pulse Width T_pwm_min	ns	1.5	
VID Transient Time T	us	1000	
Component Value			
R1 (1S)	MO	6.19	
R2 (1S)	MO	20.5	
R3 (1S)	MO	4.32	
R4 (1S)	MO	16.5	
R5 (1S)	MO	8.0	
C	uF	0.001	



PWM-VID Spec and Component Values		Unit	Config
Number of Voltage Levels N	level	160	
PWM Frequency F_pwm	MHz	475	
PWM Minimum Pulse Width T_pwm_min	ns	1.5	
VID Transient Time T	us	1000	
Component Value			
R1 (1S)	MO	6.19	
R2 (1S)	MO	20.5	
R3 (1S)	MO	4.32	
R4 (1S)	MO	16.5	
R5 (1S)	MO	8.0	
C	uF	0.001	

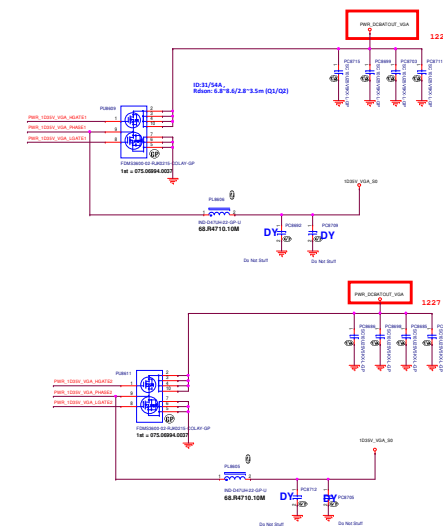
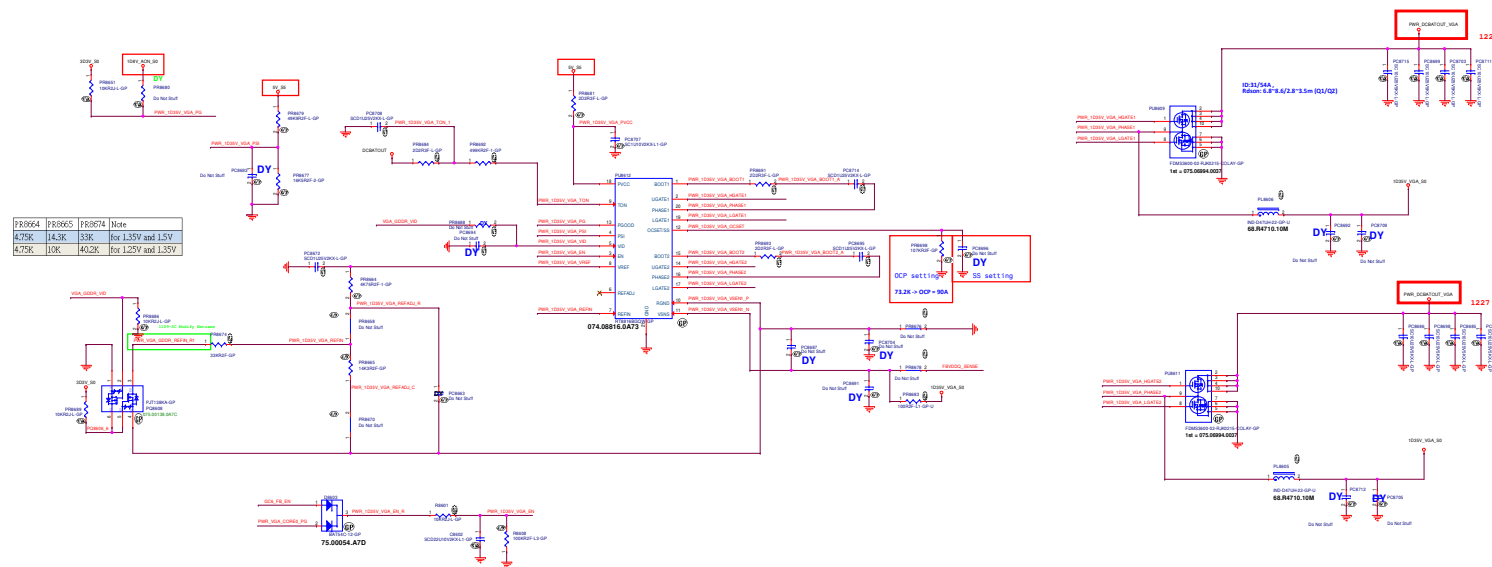
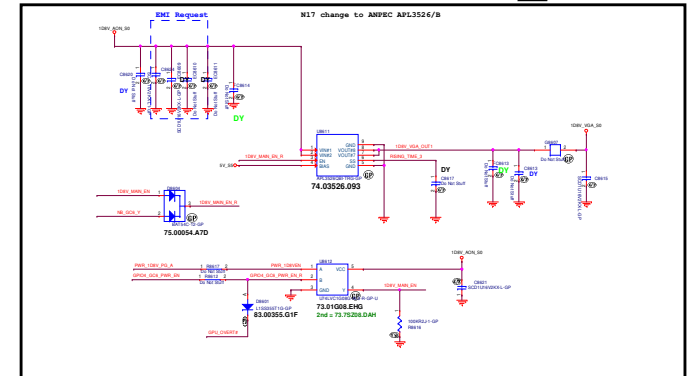


PWM-VID Spec and Component Values		Unit	Config
Number of Voltage Levels N	level	160	
PWM Frequency F_pwm	MHz	475	
PWM Minimum Pulse Width T_pwm_min	ns	1.5	
VID Transient Time T	us	1000	
Component Value			
R1 (1S)	MO	6.19	
R2 (1S)	MO	20.5	
R3 (1S)	MO	4.32	
R4 (1S)	MO	16.5	
R5 (1S)	MO	8.0	
C	uF	0.001	



AOZ2260 for 1D8V_AON

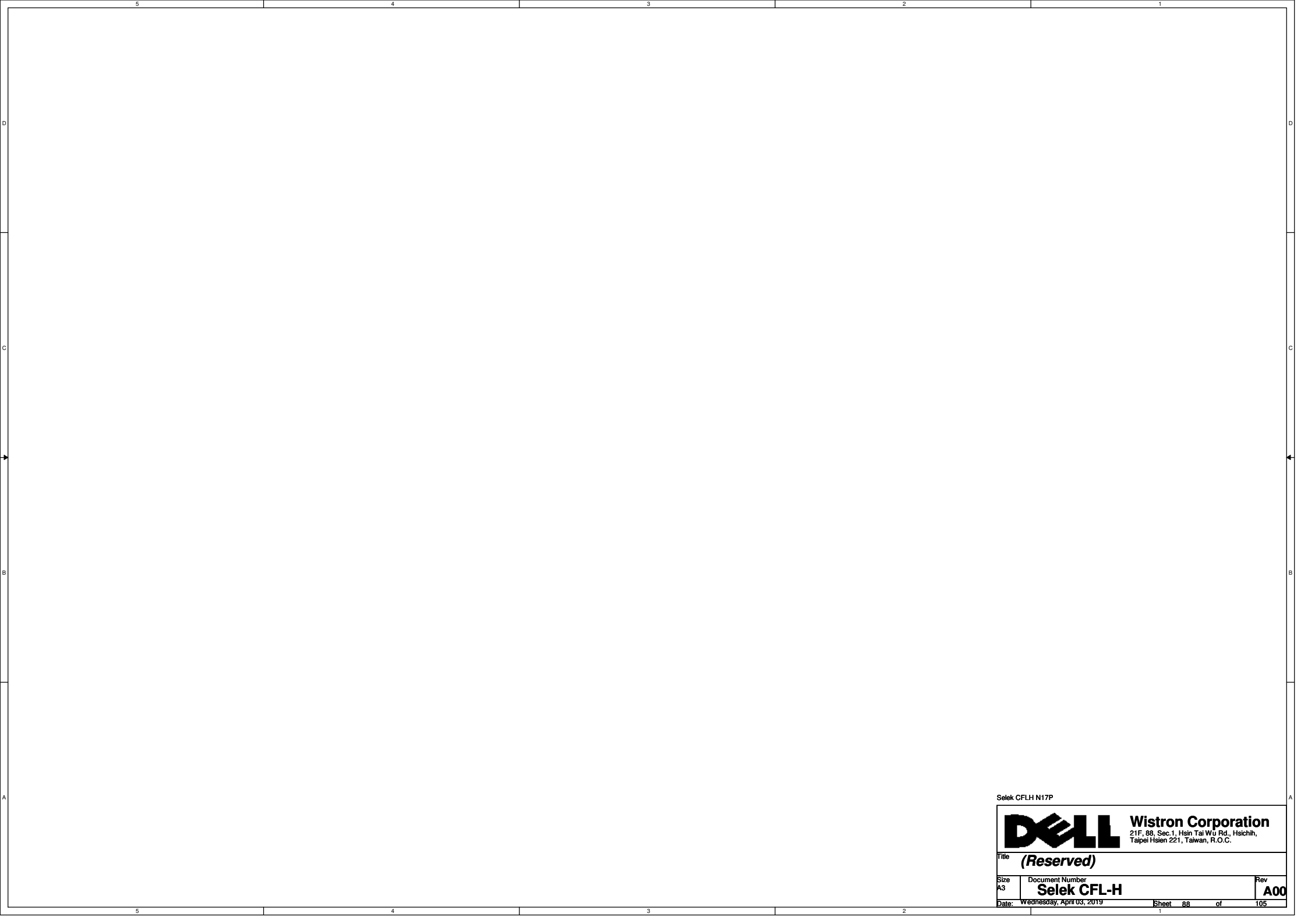
APL3526 for 1D8V_MAIN



Design Current : 32.8A
OCP : 59.4A

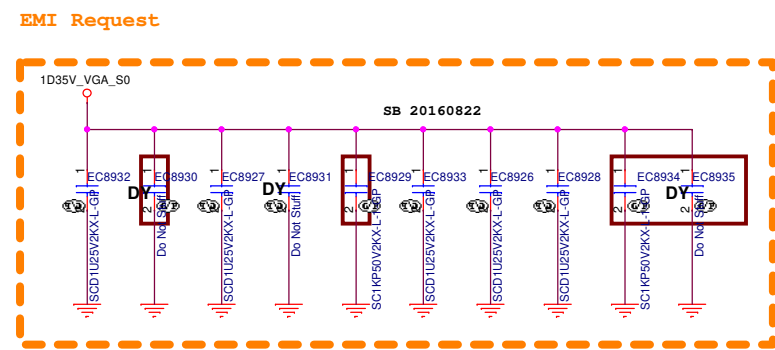
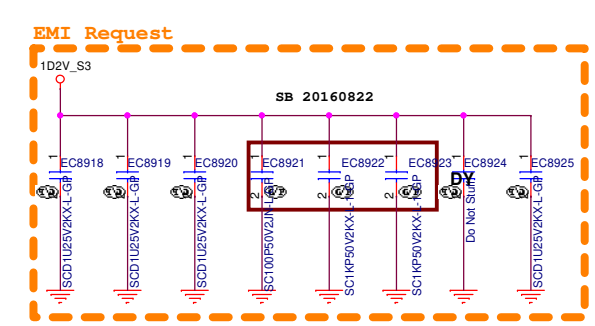
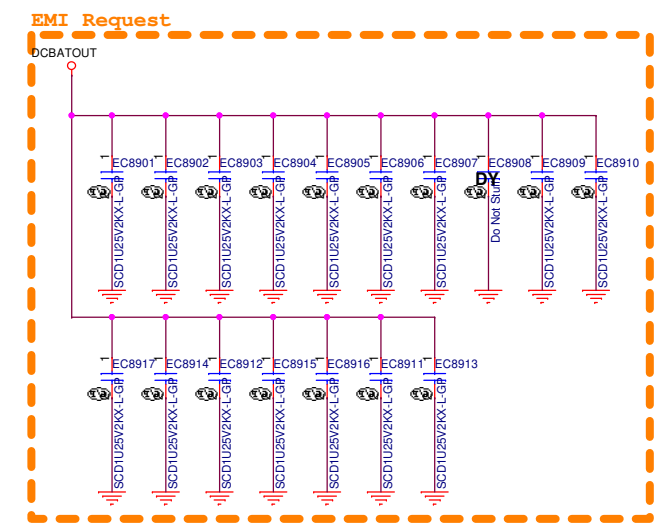
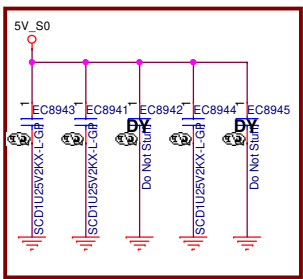
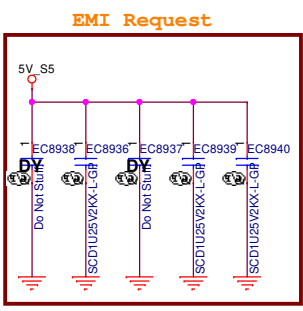
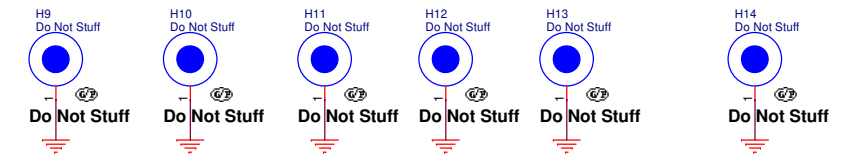
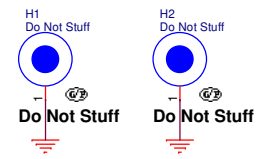
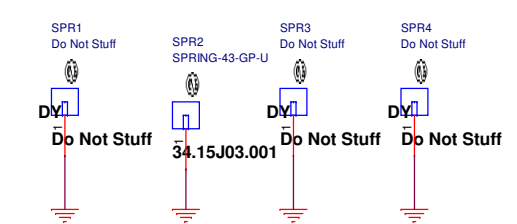
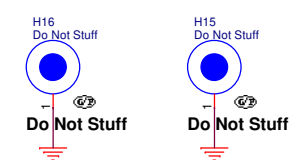
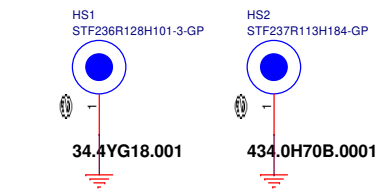


Power 1228



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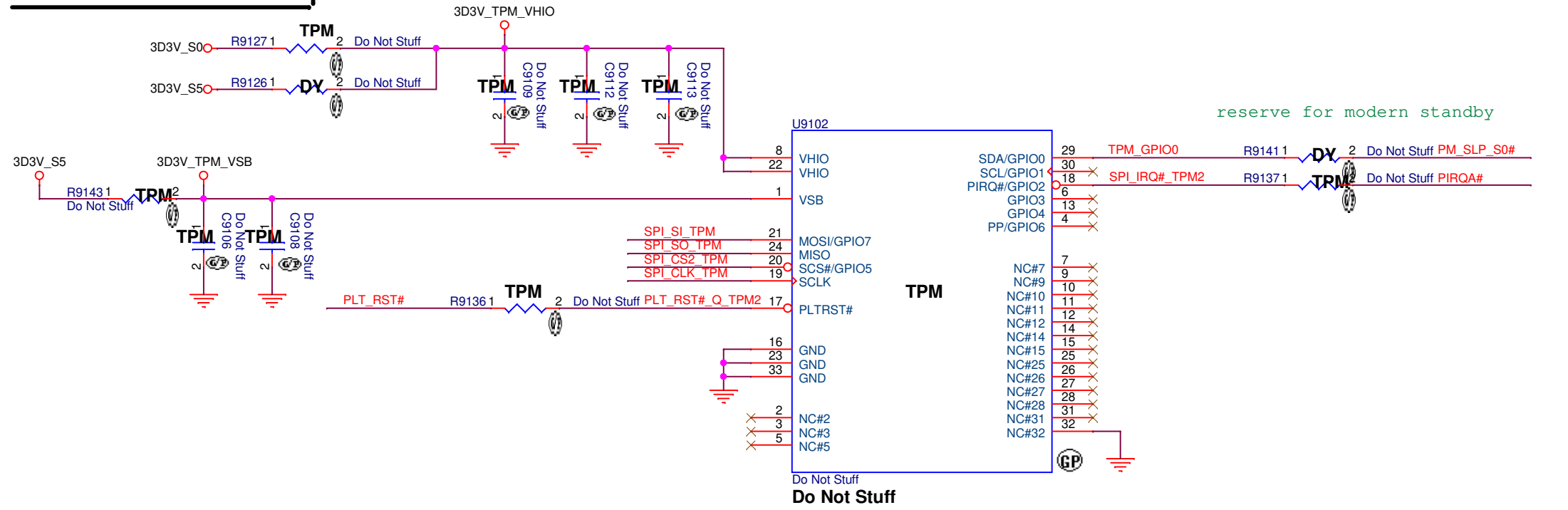
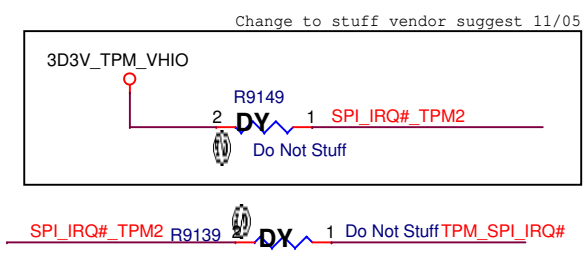
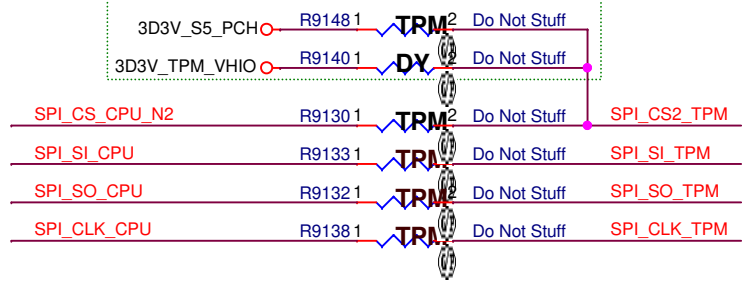
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SSID = TPM

19	PIRQA#	>>>	
15	TPM_SPI_IRQ#	>>>	
31,61,63,79	PLT_RST#	>>>	
15,40	PM_SLP_S0#	>>>	
15	SPI_CS_CPU_N2	>>>	
15,21,25	SPI_SO_CPU	<<<	
15,21,25	SPI_SI_CPU	>>>	
15,25	SPI_CLK_CPU	>>>	

reserve RTC Gen 9 reset circuit_20170814
leakage issue



reserve for modern standby

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Title

TPM2.0

Size
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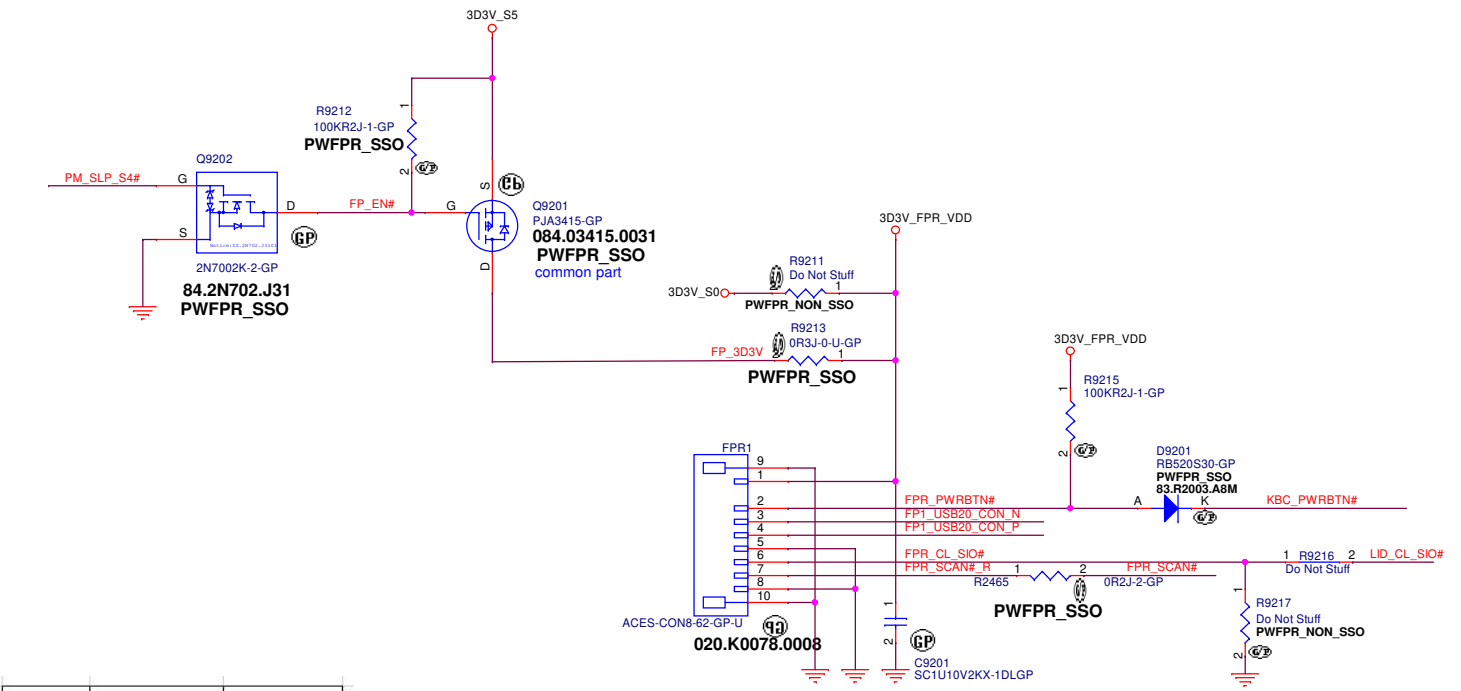
Rev
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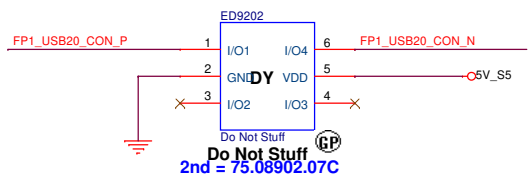
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Main Func = FPR

- 24 FPR_SCAN# >>>
- 15,40,44,51 PM_SLP_S4# >>>
- 24,64 KBC_PWRBTN# <<<
- 24,66 LID_CL_SIO# >>>
- 18 FP1_USB20_N <<<
- 18 FP1_USB20_P <<<



	PM_SLP_S4#	FP_3D3V
S0	1	1
S3	1	1
S4	0	0
S5	0	0



FBR(Botton side finger Print Sensor)

PWFPR_SSO: GOODIX module
PWFPR_NON_SSO: ELAN module(R9211 R9214 R9217)

GF5288WN1+GF128A+GM168 Module design

Pin Definition

CN PIN MAP	
PIN NO.	INFO
1	VCC-3.3V
2	Power button
3	USB_N
4	USB_P
5	GND
6	LID closed
7	GPIO_key shielding
8	GND(ID pin)

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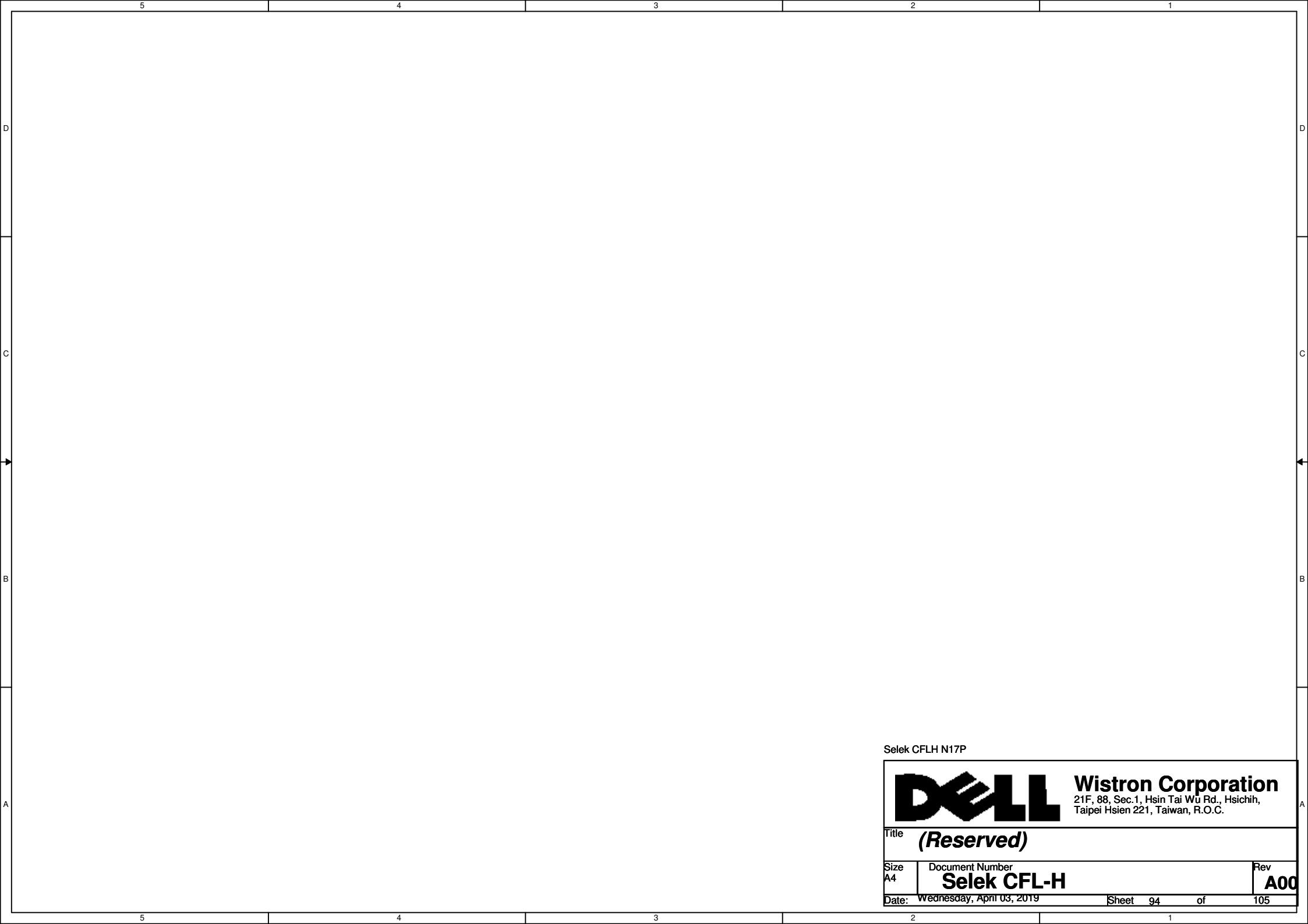
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Main Func = XDP

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Title **CPU_XDP;PCH_XDP**

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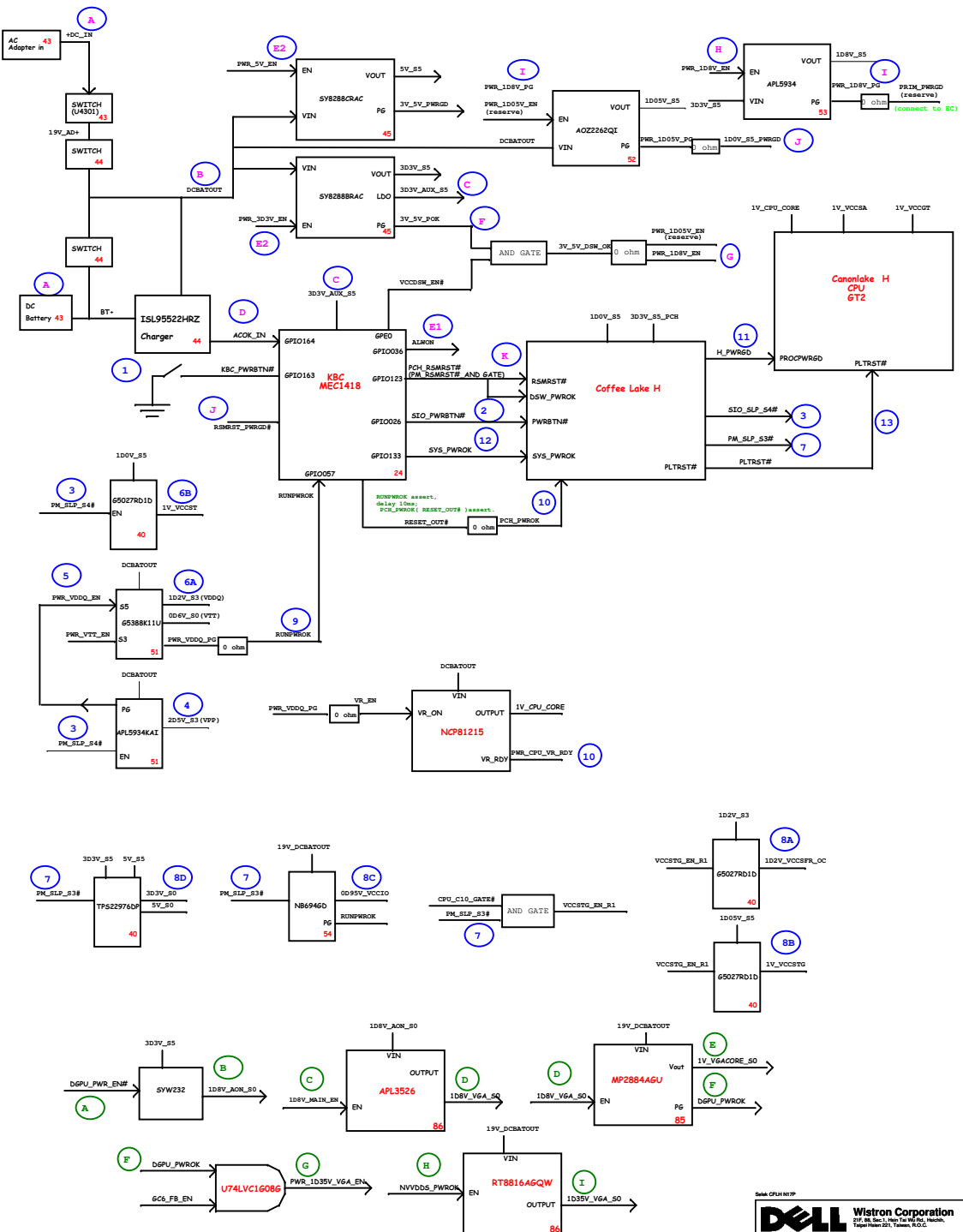
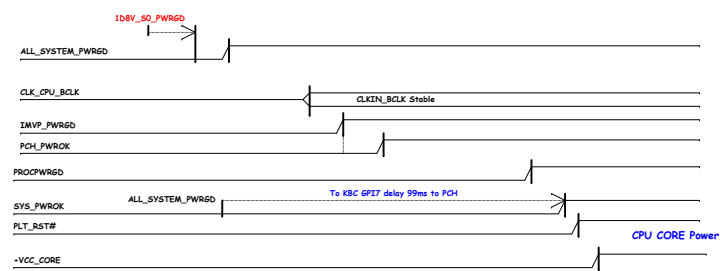
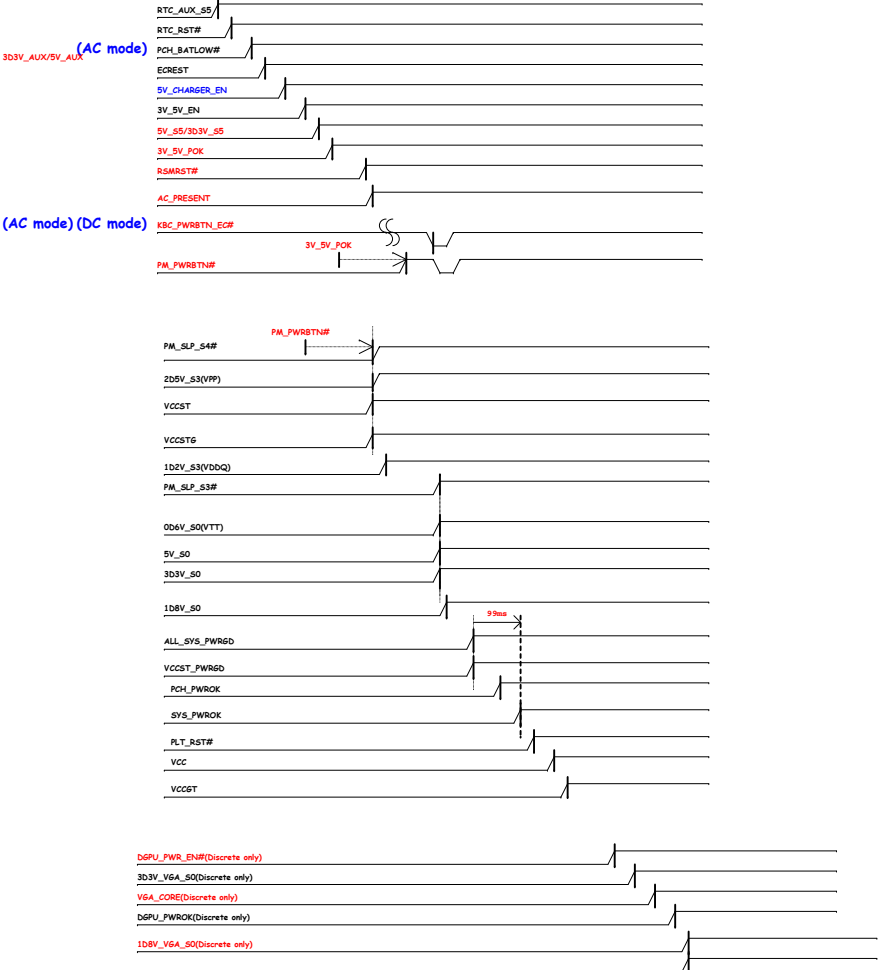
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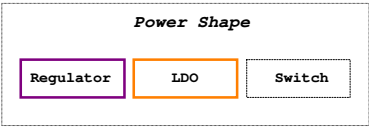
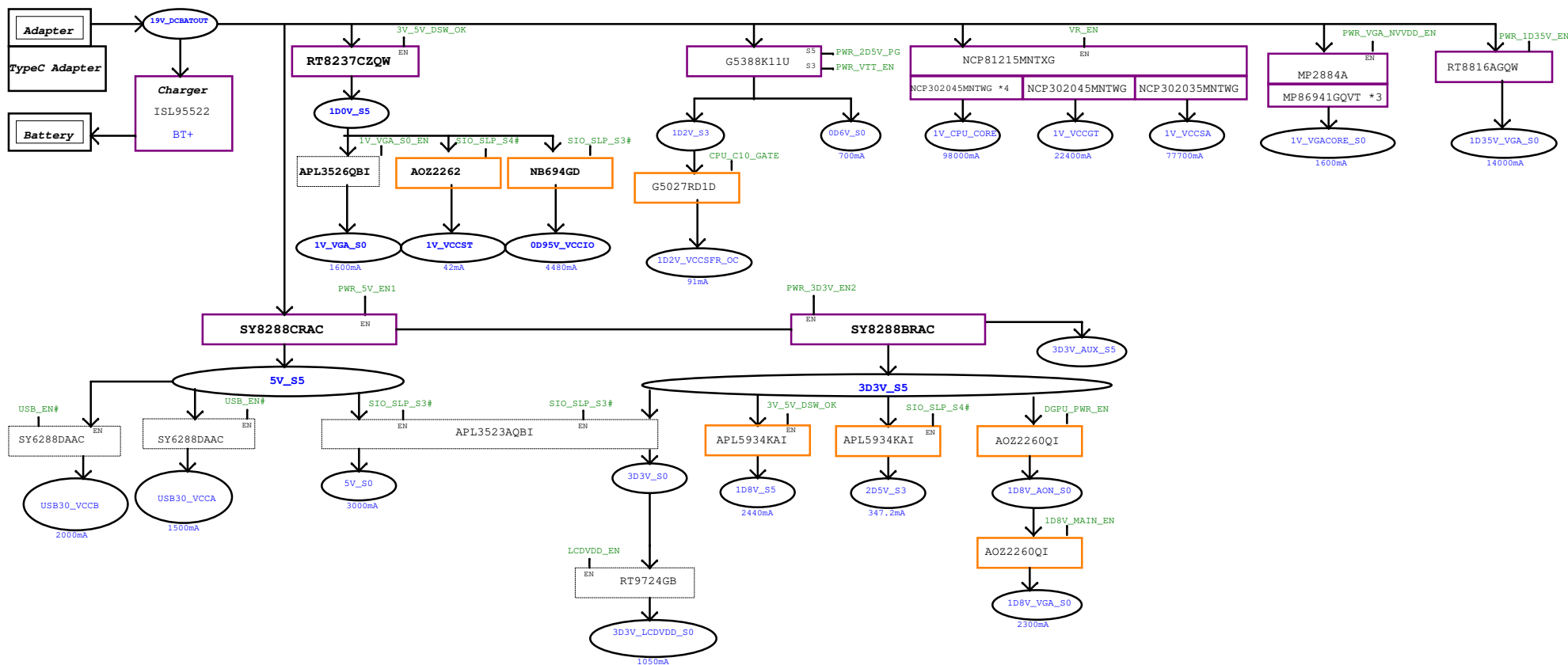
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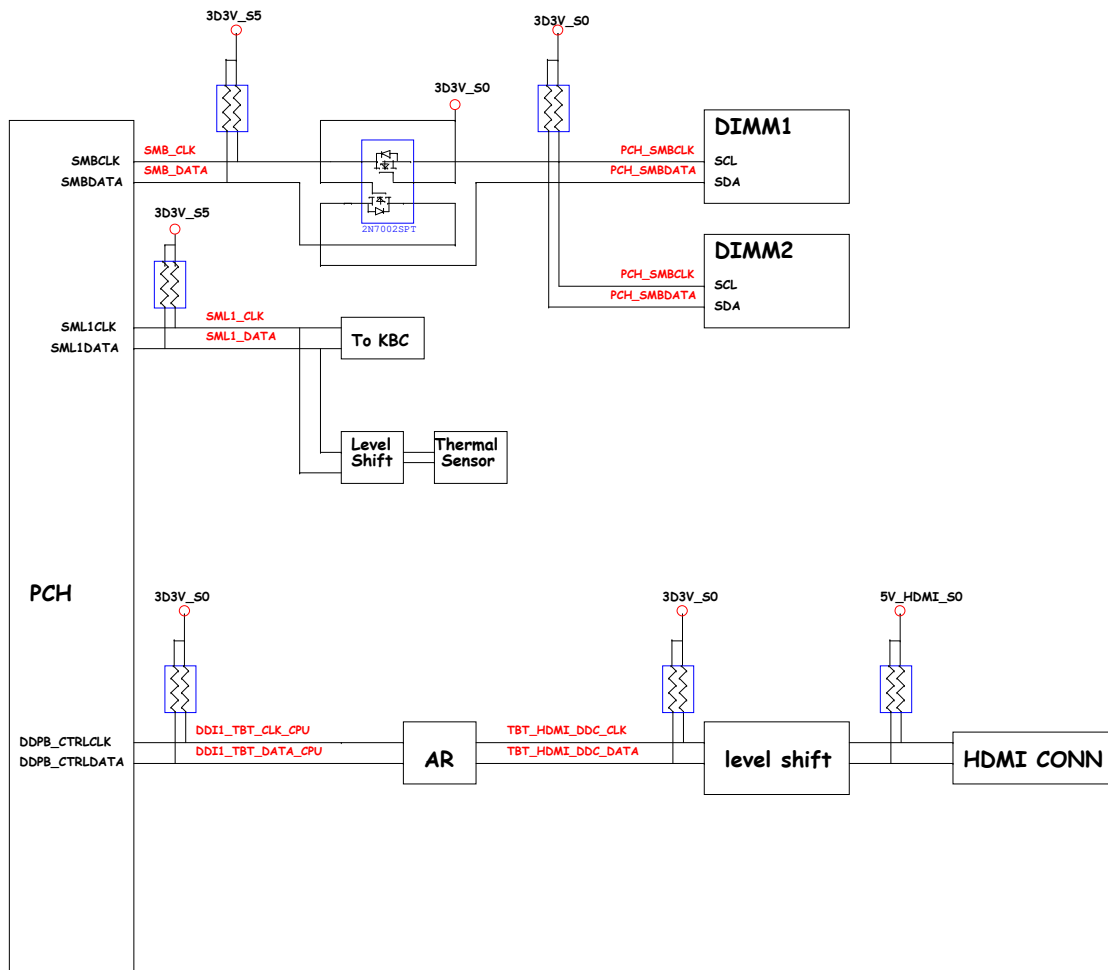
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Intel-Power Up Sequence

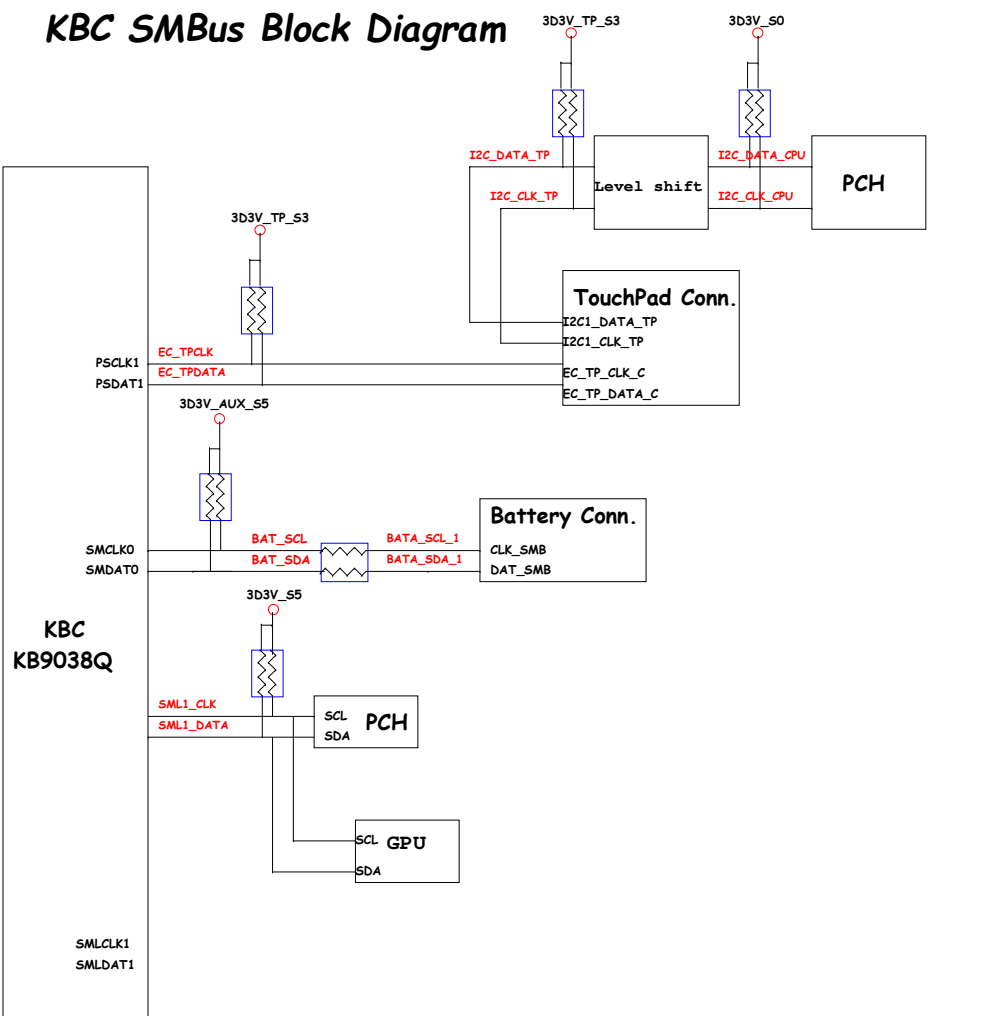




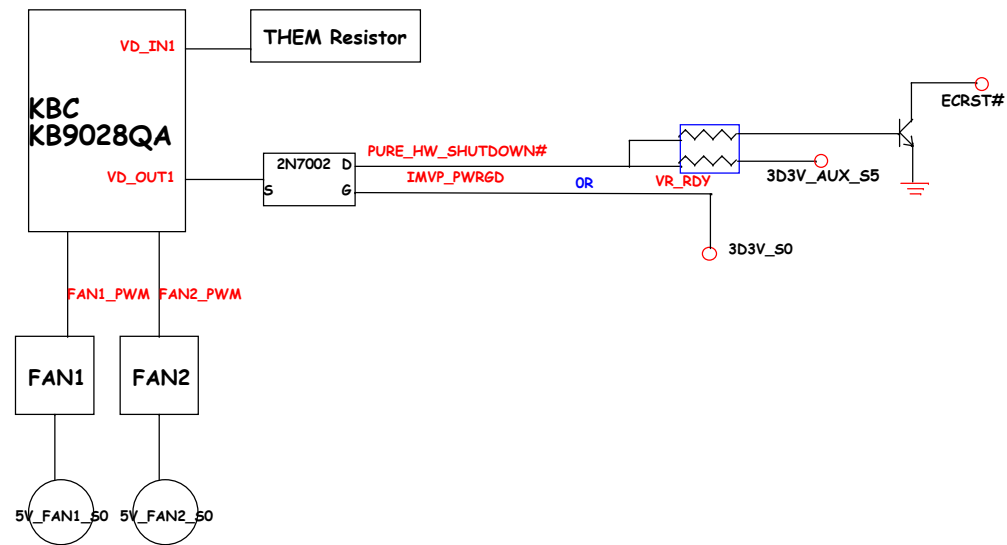
PCH SMBus Block Diagram



KBC SMBus Block Diagram



Thermal Block Diagram



Audio Block Diagram

